



ECP5™ Family Data Sheet

Advance DS1044 Version 01.0, March 2014

Features

- **Higher Logic Density for Increased System Integration**
 - 24K to 84K LUTs
 - 197 to 365 user programmable I/Os
- **Embedded SERDES**
 - 270 Mbps to 3.2 Gbps for Generic 8b10b, 10-bit SERDES, and 8-bit SERDES modes
 - Data Rates 270 Mbps to 3.2 Gbps per channel for all other protocols
 - Up to 4 channels per device: PCI Express, Ethernet (1GbE, SGMII, XAUI), CPRI, SMPTE 3G and Serial RapidIO
- **sysDSP™**
 - Fully cascadable slice architecture
 - 12 to 160 slices for high performance multiply and accumulate
 - Powerful 54-bit ALU operations
 - Time Division Multiplexing MAC Sharing
 - Rounding and truncation
 - Each slice supports
 - Half 36 x 36, two 18 x 18 or four 9 x 9 multipliers
 - Advanced 18 x 36 MAC and 18 x 18 Multiply-Multiply-Accumulate (MMAC) operations
- **Flexible Memory Resources**
 - Up to 3.744 Mbits sysMEM™ Embedded Block RAM (EBR)
 - 194K to 669K bits distributed RAM
- **sysCLOCK Analog PLLs and DLLs**
 - Four DLLs and four PLLs in LFE5-45 and LFE5-85; two DLLs and two PLLs in LFE5-25
- **Pre-Engineered Source Synchronous I/O**
 - DDR registers in I/O cells
 - Dedicated read/write levelling functionality
 - Dedicated gearing logic
 - Source synchronous standards support
 - ADC/DAC, 7:1 LVDS, XGMII
 - High Speed ADC/DAC devices
 - Dedicated DDR2/DDR3 & LPDDR2/LPDDR3 memory support with DQS logic, up to 800 B00Mbps data-rate
- **Programmable sysI/O™ Buffer Supports Wide Range of Interfaces**
 - On-chip termination
 - LVTTTL and LVCMOS 33/25/18/15/12
 - SSTL 18/15 I, II
 - HSUL12
 - LVDS, Bus-LVDS, LVPECL, RSDS, MLVDS
 - subLVDS & SLVS, MIPI D-PHY input interfaces
- **Flexible Device Configuration**
 - Shared bank for configuration I/Os
 - SPI boot flash interface
 - Dual-boot images supported
 - Slave SPI
 - TransFR™ I/O for simple field updates
 - Soft Error Detect embedded macro
- **System Level Support**
 - IEEE 1149.1 and IEEE 1532 compliant
 - Reveal Logic Analyzer
 - On-chip oscillator for initialization and general use
 - 1.1 V core power supply

Table 1-1. ECP5 Family Selection Guide

Device	LFE5UM-25	LFE5UM-45	LFE5UM-85	LFE5U-25	LFE5U-45	LFE5U-85
LUTs (K)	24	44	84	24	44	84
sysMEM Blocks (18 Kbits)	56	108	208	56	108	208
Embedded Memory (Kbits)	1,008	1944	3744	1,008	1944	3744
Distributed RAM Bits (Kbits)	194	351	669	194	351	669
18 X 18 Multipliers	28	72	156	28	72	156
SERDES (Dual/Channels)	1/2	2/4	2/4	0	0	0
PLLs/DLLs	2/2	4/4	4/4	2/2	4/4	4/4
Packages and SERDES Channels / I/O Combinations						
285 csfBGA (10 x 10 mm ² , 0.5 mm)	2/118	2/118	2/118	0/118	0/118	0/118
381 caBGA (17 x 17 mm ²)	2/197	4/203	4/205	0/197	0/203	0/205
554 caBGA (23 x 23 mm ²)		4/245	4/259		0/245	0/259
756 caBGA (27 x 27 mm ²)			4/365			0/365

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Introduction

The ECP5 family of FPGA devices is optimized to deliver high performance features such as an enhanced DSP architecture, high speed SERDES and high speed source synchronous interfaces in an economical FPGA fabric. This combination is achieved through advances in device architecture and the use of 40nm technology making the devices suitable for high-volume, high-speed, low-cost applications.

The ECP5 device family covers look-up-table (LUT) capacity to 84K logic elements and supports up to 365 user I/Os. The ECP5 device family also offers up to 156 18 x 18 multipliers and a wide range of parallel I/O standards.

The ECP5 FPGA fabric is optimized high performance with low power and low cost in mind. The ECP5 devices utilize reconfigurable SRAM logic technology and provide popular building blocks such as LUT-based logic, distributed and embedded memory, Phase Locked Loops (PLLs), Delay Locked Loops (DLLs), pre-engineered source synchronous I/O support, enhanced sysDSP slices and advanced configuration support, including encryption and dual-boot capabilities.

The pre-engineered source synchronous logic implemented in the ECP5 device family supports a broad range of interface standards, including DDR3, LPDDR3, XGMII and 7:1 LVDS.

The ECP5 device family also features high speed SERDES with dedicated PCS functions. High jitter tolerance and low transmit jitter allow the SERDES plus PCS blocks to be configured to support an array of popular data protocols including PCI Express, SMPTE, Ethernet (XAUI, GbE, and SGMII) and CPRI. Transmit De-emphasis and Receive Equalization settings make the SERDES suitable for transmission and reception over various forms of media.

The ECP5 devices also provide flexible, reliable and secure configuration options, such as dual-boot capability, bit-stream encryption, and TransFR field upgrade features.

The Lattice Diamond™ design software allows large complex designs to be efficiently implemented using the ECP5 FPGA family. Synthesis library support for ECP5 devices is available for popular logic synthesis tools. The Diamond tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the ECP5 device. The tools extract the timing from the routing and back-annotate it into the design for timing verification.

Lattice provides many pre-engineered IP (Intellectual Property) modules for the ECP5 family. By using these configurable soft core IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Architecture Overview

Each ECP5 device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sysDSP™ Digital Signal Processing slices, as shown in Figure 2-1. The LFE5-85 devices have three rows of DSP slices, the LFE5-45 devices have two rows and LFE5-25 devices have one. In addition, the LFE5U devices contain SERDES Duals on the bottom of the device.

The Programmable Functional Unit (PFU) contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFU block is optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The ECP5 devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large, dedicated 18Kbit fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths as RAM or ROM. In addition, ECP5 devices contain up to three rows of DSP slices. Each DSP slice has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The ECP5 devices feature up to 4 embedded 3.2 Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of two SERDES channels, along with its Physical Coding Sub-layer (PCS) block, creates a dual. The functionality of the SERDES/PCS duals can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every dual can be programmed via the SERDES Client Interface (SCI). These duals (up to two) are located at the bottom of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the ECP5 devices are arranged in seven banks (eight banks for LFE5UM-85 device), allowing the implementation of a wide variety of I/O standards. One of these banks (Bank 8) is shared with the programming interfaces. 50% of the PIO pairs on the left and right edges of the device can be configured as LVDS transmit pairs, and all pairs on left and right can be configured as LVDS receive pairs. The PIC logic in the left and right banks also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as XGMII, 7:1 LVDS, along with memory interfaces including DDR3 and LPDDR3.

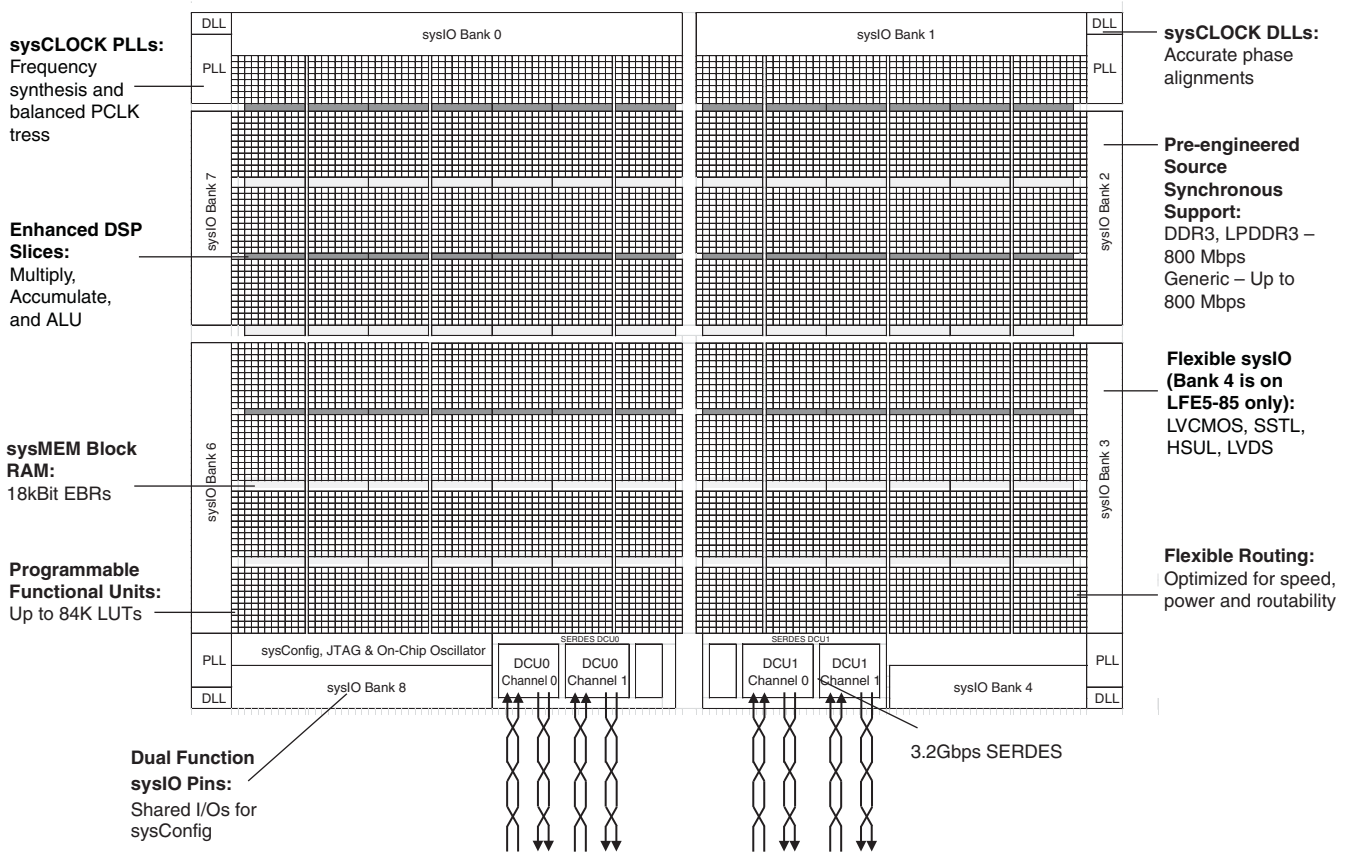
The ECP5 registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The ECP5 architecture provides up to four Delay Locked Loops (DLLs) and up to four Phase Locked Loops (PLLs). The PLL and DLL blocks are located at the corners of each device.

The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual-boot support is located at the bottom of each device, to the left of the SERDES blocks. Every device in the ECP5 family supports a sysCONFIG™ ports located in that same corner, powered by Vccio8, allowing for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator and soft error detect capability. The ECP5 devices use 1.1 V as their core voltage.

Figure 2-1. Simplified Block Diagram, LFE5UM-85 Device (Top Level)



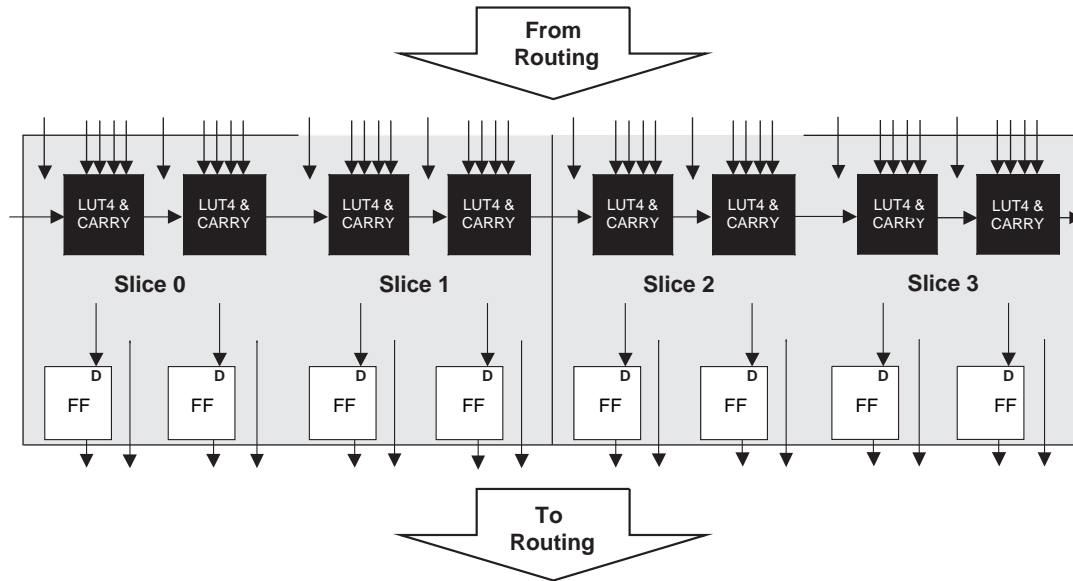
Note: There is no Bank 4 in LFE5-25 and LFE5-45.
There are no PLL and DLL on the top corners in LFE5-25.

PFU Blocks

The core of the ECP5 device consists of PFU blocks. Each PFU block consists of four interconnected slices numbered 0-3 as shown in Figure 2-2. Each slice contains two LUTs. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

The PFU block can be used in Distributed RAM or ROM function, or used to perform Logic, Arithmetic, or ROM functions. Table 2-1 shows the functions each slice can perform in either mode.

Figure 2-2. PFU Diagram



Slice

Each slice contains two LUT4s feeding two registers. In Distributed SRAM mode, Slice 0 through Slice 2 are configured as distributed memory, and Slice 3 is used as Logic or ROM. Table 2-1 shows the capability of the slices along with the operation modes they enable. In addition, each PFU contains logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/ asynchronous), clock select, chip-select and wider RAM/ROM functions.

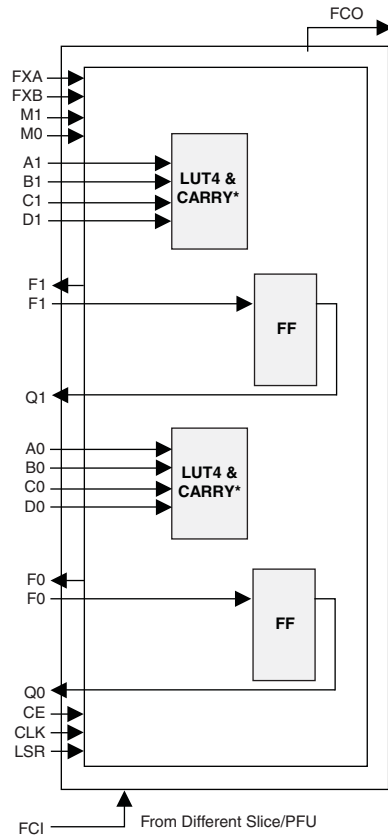
Table 2-1. Resources and Modes Available per Slice

Slice	PFU BLock		PFF Block	
	Resources	Modes	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	RAM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	RAM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	RAM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s and 2 Registers	RAM, Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM

Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 10 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

Figure 2-3. Slice Diagram



Notes: For Slices 0 and 1, memory control signals are generated from Slice 2 as follows:
WCK is CLK
WRE is from LSR
DI[3:2] for Slice 1 and DI[1:0] for Slice 0 data from Slice 2
WAD [A:D] is a 4-bit address from slice 2 LUT input

Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCI	Fast Carry-in ¹
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6 and LUT7
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6 and LUT7
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Inter-PFU signal	FCO	Fast carry chain output ¹

1. See Figure 2-3 for connection details.
2. Requires two PFUs.

Modes of Operation

Each slice has up to four potential modes of operation: Logic, Ripple, RAM and ROM.

Logic Mode

In this mode, the LUTs in each slice are configured as 4-input combinatorial lookup tables. A LUT4 can have 16 possible input combinations. Any four input logic functions can be generated by programming this lookup table. Since there are two LUT4s per slice, a LUT5 can be constructed within one slice. Larger look-up tables such as LUT6, LUT7 and LUT8 can be constructed by concatenating other slices. Note that LUT8 requires more than four slices.

Ripple Mode

Ripple mode supports the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Up/Down counter with asynchronous clear
- Up/Down counter with preload (sync)
- Ripple mode multiplier building block
- Multiplier support
- Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Ripple Mode includes an optional configuration that performs arithmetic using fast carry chain methods. In this configuration (also referred to as CCU2 mode) two additional signals, Carry Generate and Carry Propagate, are generated on a per slice basis to allow fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode

In this mode, a 16x4-bit distributed single port RAM (SPR) can be constructed using each LUT block in Slice 0 and Slice 1 as a 16x1-bit memory. Slice 2 is used to provide memory address and control signals. A 16x2-bit pseudo dual port RAM (PDPR) memory is created by using one Slice as the read-write port and the other companion slice as the read-only port.

ECP5 devices support distributed memory initialization.

The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of slices required to implement different distributed RAM primitives. For more information about using RAM in ECP5 devices, please see TN1264, [ECP5 Memory Usage Guide](#).

Table 2-3. Number of Slices Required to Implement Distributed RAM

	SPR 16X4	PDPR 16X4
Number of slices	3	3

Note: SPR = Single Port RAM, PDPR = Pseudo Dual Port RAM

ROM Mode

ROM mode uses the LUT logic; hence, Slices 0 through 3 can be used in ROM mode. Preloading is accomplished through the programming interface during PFU configuration.

For more information, please refer to TN1264, [ECP5 Memory Usage Guide](#).

Routing

There are many resources provided in the ECP5 devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The ECP5 family has an enhanced routing architecture that produces a compact design. The Diamond design software tool suites take the output of the synthesis tool and places and routes the design.

CLOCKING STRUCTURE

ECP5 clocking structure consists of clock synthesis blocks, sysCLOCK PLL; balanced clock tree networks, PCLK and ECLK trees; and efficient clock logic modules, CLOCK DIVIDER and Dynamic Clock Select (DCS), Dynamic Clock Control (DCC), and DLL. Each of these functions is described as follow.

sysCLOCK PLL

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. The devices in the ECP5 family support two to four full-featured General Purpose PLLs. The sysCLOCK PLLs provide the ability to synthesize clock frequencies.

The architecture of the PLL is shown in Figure 2-4. A description of the PLL functionality follows.

CLKI is the reference frequency input to the PLL and its source can come from two different external CLK inputs or from internal routing. A non-glitchless 2-to-1 input multiplexor is provided to dynamically select between two different external reference clock sources. The CLKI input feeds into the input Clock Divider block.

CLKFB is the feedback signal to the PLL which can come from internal feedback path, routing or an external I/O pin. The feedback divider is used to multiply the reference frequency and thus synthesize a higher frequency clock output.

The PLL has four clock outputs CLKOP, CLKOS, CLKOS2 and CLKOS3. Each output has its own output divider, thus allowing the PLL to generate different frequencies for each output. The output dividers can have a value from 1 to 128. The CLKOP, CLKOS, CLKOS2, and CLKOS3 outputs can all be used to drive the primary clock network. Only CLKOP and CLKOS outputs can go to the edge clock network.

The setup and hold times of the device can be improved by programming a phase shift into the CLKOS, CLKOS2, and CLKOS3 output clocks which will advance or delay the output clock with reference to the CLKOP output clock. This phase shift can be either programmed during configuration or can be adjusted dynamically using the PHASE-SEL, PHASEDIR, PHASESTEP, and PHASELOADREG ports.

The LOCK signal is asserted when the PLL determines it has achieved lock and de-asserted if a loss of lock is detected.

Figure 2-4. General Purpose PLL Diagram

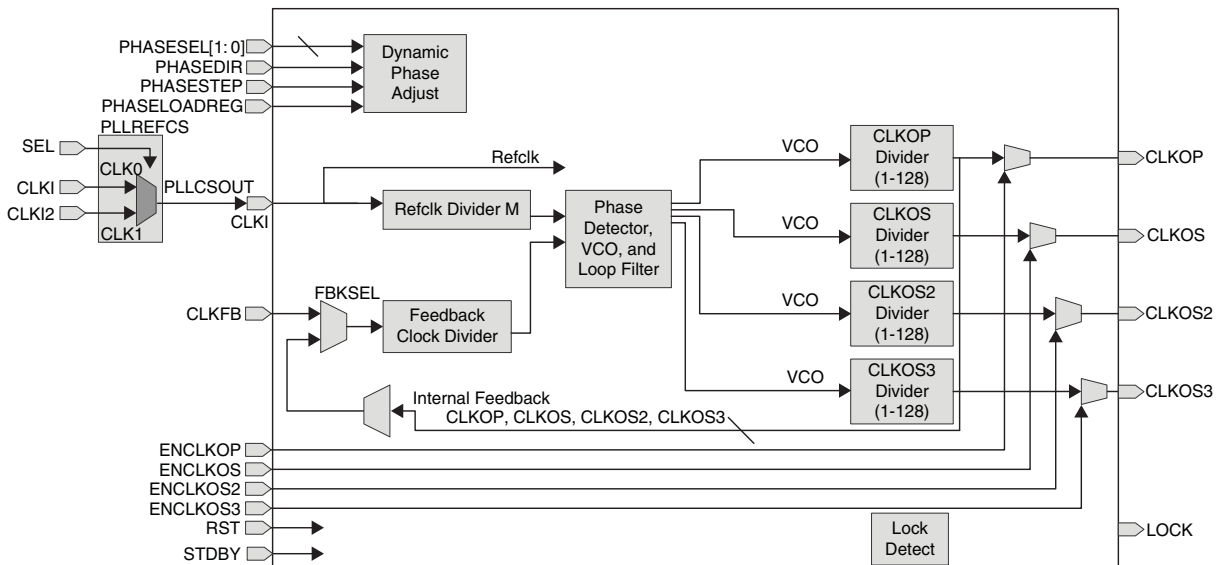


Table 2-4 provides a description of the signals in the PLL blocks.

Table 2-4. PLL Blocks Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock Input Clock to PLL from external pin or routing
CLKI2	I	Muxed clock input to PLL
SEL	I	Input Clock select
CLKFB	I	PLL Feedback Clock
PHASESEL[1:0]	I	Select the output affected by Dynamic Phase adjustment.
PHASEDIR	I	Dynamic Phase adjustment direction.
PHASESTEP	I	Dynamic Phase adjustment step.
PHASELOADREG	I	Load dynamic phase adjustment values into PLL.
CLKOP	O	Primary PLL output clock (with phase shift adjustment)
CLKOS	O	Secondary PLL output clock (with phase shift adjust)
CLKOS2	O	Secondary PLL output clock2 (with phase shift adjust)
CLKOS3	O	Secondary PLL output clock3 (with phase shift adjust)
LOCK	O	PLL LOCK to CLKI, Asynchronous signal. Active high indicates PLL lock
STDBY	I	Standby signal to power down the PLL
RST	I	Resets the PLL
ENCLKOP	I	Enable PLL output CLKOP
ENCLKOS	I	Enable PLL output CLKOS
ENCLKOS2	I	Enable PLL output CLKOS2
ENCLKOS3	I	Enable PLL output CLKOS3

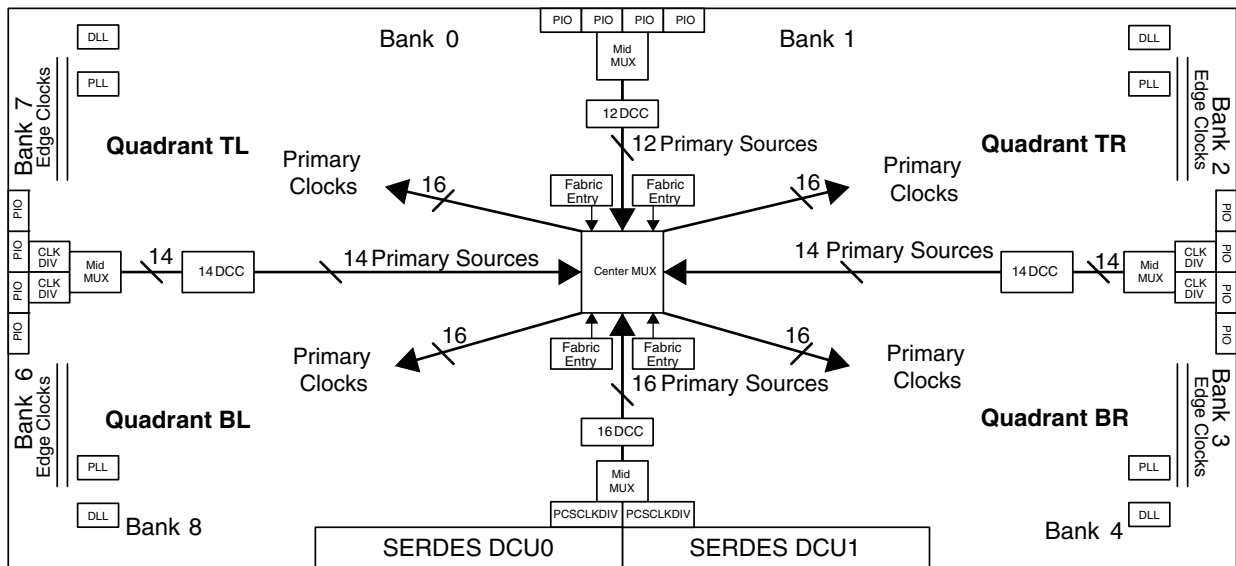
For more details on the PLL you can refer to the TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#).

Clock Distribution Network

There are two main clock distribution networks for any member of the ECP5 product family, namely Primary Clock (PCLK) and Edge Clock (ECLK). These clock networks have the clock sources come from many different sources, such as Clock Pins, PLL outputs, DLLDEL outputs, Clock divider outputs, SERDES/PCS clocks and some on chip generated clock signal. There are clock dividers (CLKDIV) blocks to provide the slower clock from these clock sources. ECP5 also supports glitch-less dynamic enable function (DCC) for the PCLK Clock to save dynamic power. There are also some logics to allow dynamic glitch-less selection between two clocks for the PCLK network (DCS).

Overview of Clocking Network is shown in Figure 2-5, for LFE5UM-85 device.

Figure 2-5. LFE5UM-85 Clocking



Primary Clocks

The ECP5 device family provides low-skew, high fanout clock distribution to all synchronous elements in the FPGA fabric through the Primary Clock Network.

The primary clock network is divided into four clocking quadrants: Top Left (TL), Bottom Left (BL), Top Right (TR), and Bottom Right (BR). Each of these quadrants has 16 clocks that can be distributed to the fabric in the quadrant.

The Lattice Diamond software can automatically route each clock to one of the 4 quadrants up to a maximum of 16 clocks per quadrant. The user can change how the clocks are routed by specifying a preference in the Lattice Diamond software to locate the clock to specific. The ECP5 device provides the user with a maximum of 64 unique clock input sources that can be routed to the primary Clock network.

Primary clock sources are:

- Dedicated clock input pins
- PLL outputs
- CLKDIV outputs
- Internal FPGA fabric entries (with minimum general routing)
- SERDES/PCS/PCSDIV clocks
- OSC clock

These sources are routed to one of four clock switches called a Mid Mux. The outputs of the Mid MUX are routed to the center of the FPGA where another clock switch, called the Center MUX, is used to route the primary clock sources to primary clock distribution to the ECP5 fabric. Since there is a maximum of 60 unique clock input sources to the clocking quadrants, there are potentially 64 unique clock domains that can be used in the ECP5 Device. For more information about the primary clock tree & connections, please see TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#).

Dynamic Clock Control (DCC)

The DCC (Quadrant Clock Enable/Disable) feature allows internal logic control of the quadrant primary clock network. When a clock network is disabled, all the logic fed by that clock does not toggle, reducing the overall power consumption of the device. The disable function will not create glitch and increase the clock latency to the primary clock network.

This DCC controls the clock sources from the Primary CLOCK MIDMUX before they are fed to the Primary Center MUXs that drive the quadrant clock network. For more information about the DCC, please see TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#).

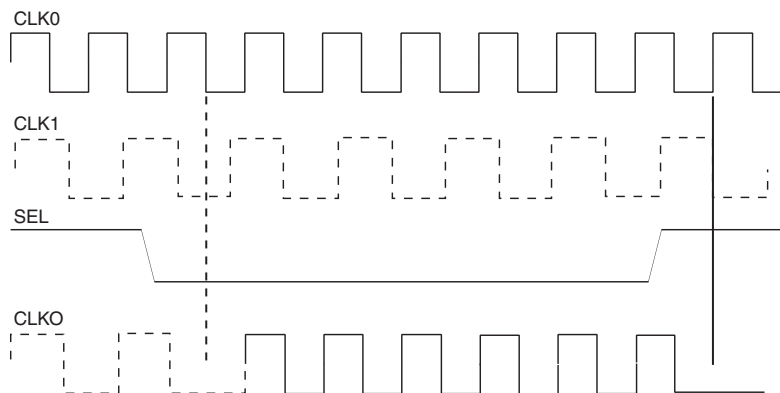
Dynamic Clock Select (DCS)

The DCS is a smart multiplexer function available in the primary clock routing. It switches between two independent input clock sources. Depending on the operation modes, it switches between two (2) independent input clock sources either with or without any glitches. This is achieved regardless of when the select signal is toggled. Both input clocks must be running to achieve functioning glitch-less DCS output clock, but it is not required running clocks when used as non-glitch-less normal clock multiplexer.

There are two DCS blocks per device that are fed to all quadrants. The inputs to the DCS block come from all the output of MIDMUXs and Clock from CIB located at the center of the PLC array core. The output of the DCS is connected to one of the inputs of Primary Clock Center MUX.

See Figure 2-6 shows the timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information about the DCS, please see TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#).

Figure 2-6. DCS Waveforms

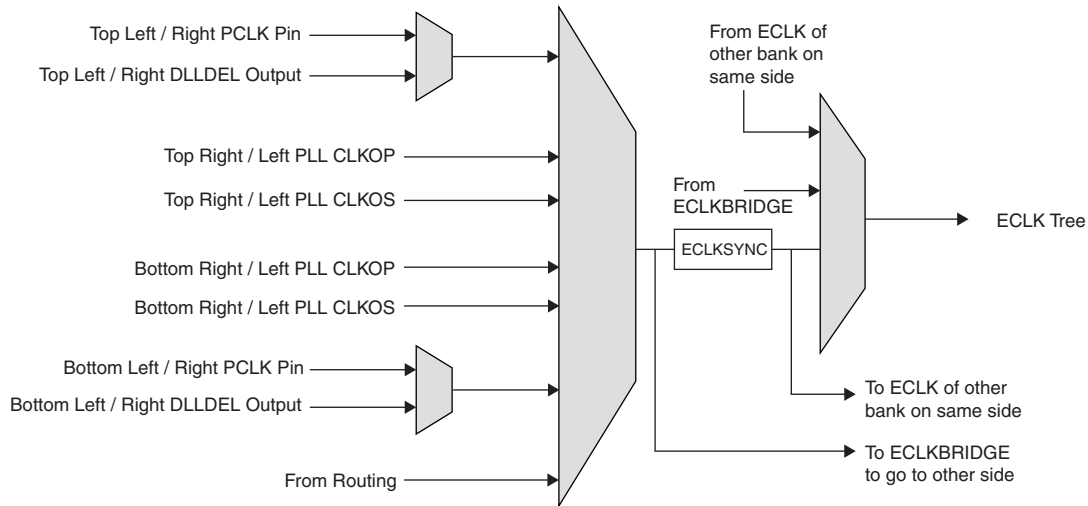


Edge Clock

ECP5 devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are two ECLK networks per bank IO on the Left and Right sides of the devices. Edge Clock (ECLK) consists of local DLLDEL delay cell, the ECLK input MUX, ECLK stop logic, ECLK Clock 2nd MUX, and the ECLK tree.

ECLK Input MUX collects all clock sources available shown in Figure 2-7 below. There are two ECLK Input MUXs, one on the left side and one on the right side. These MUXs are located on the edge close by the HIQ region. Each of these MUX will generate total of 4 ECLK Clock sources. Two of them drive the upper IO bank and two of them drive the lower IO bank. Two out of four also drive the ECLK Bridge Switch Block to form an ECLK Bridge high speed clock before drive the ECLK Tree Network.

Figure 2-7. Edge Clock Sources Per Bank



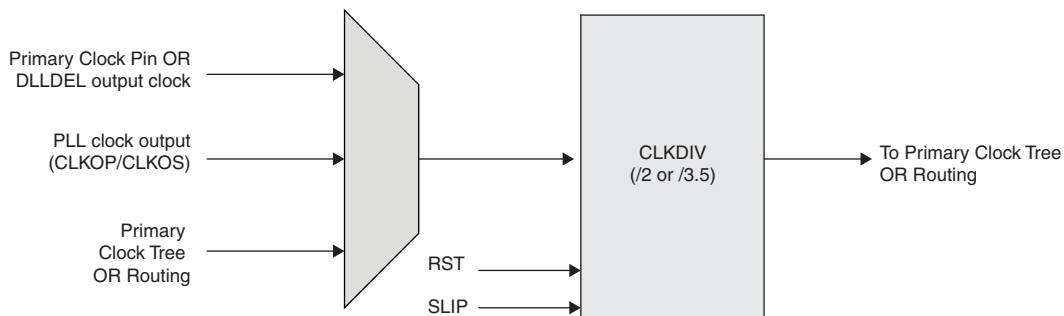
The edge clocks have low injection delay and low skew. They are used for DDR Memory or Generic DDR interfaces. For detailed information on Edge Clock connections, please see TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#).

Clock Dividers

ECP5 devices have two clock dividers, one on the left side and one on the right side of the device. These are intended to generate a slower-speed system clock from a high-speed edge clock. The block operates in a $\div 2$, $\div 3.5$ mode and maintains a known phase relationship between the divided down clock and the high-speed clock based on the release of its reset signal.

The clock dividers can be fed from selected PLL outputs, external primary clock pins multiplexed with the DDRDEL Slave Delay or from routing. The clock divider outputs serve as primary clock sources and feed into the clock distribution network. The Reset (RST) control signal resets input and asynchronously forces all outputs to low. The SLIP signal slips the outputs one cycle relative to the input clock. For further information on clock dividers, please see TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#). Figure 2-8 shows the clock divider connections.

Figure 2-8. ECP5 Clock Divider Sources



DDRDLL

Every DDRDLL (master DLL block) can generate phase shift code representing the amount of delay in a delay block that corresponding to 90 degree phase of the reference clock input. The reference clock can be either from PLL, or input pin. This code is used in the DQSBUF block that controls a set of DQS pin groups to interface with DDR memory (slave DLL). There are 2 DDRDLLs that supply two sets of codes (2 different reference clocks) to each side of the I/Os (at each of the corners). The DQSBUF uses this code to controls the DQS input of the DDR memory to 90 degree shift to clock DQs at the center of the data eye.

The code is also sent to another slave DLL, DLLDEL, that takes a clock input, and generates a 90 degree shift clock output to drive the clocking structure. This is useful to interface edge-aligned Generic DDR, where 90 degree clocking needs to be created. Figure 2-9 shows DDRDLL functional diagram.

Figure 2-9. DDRDLL Functional Diagram

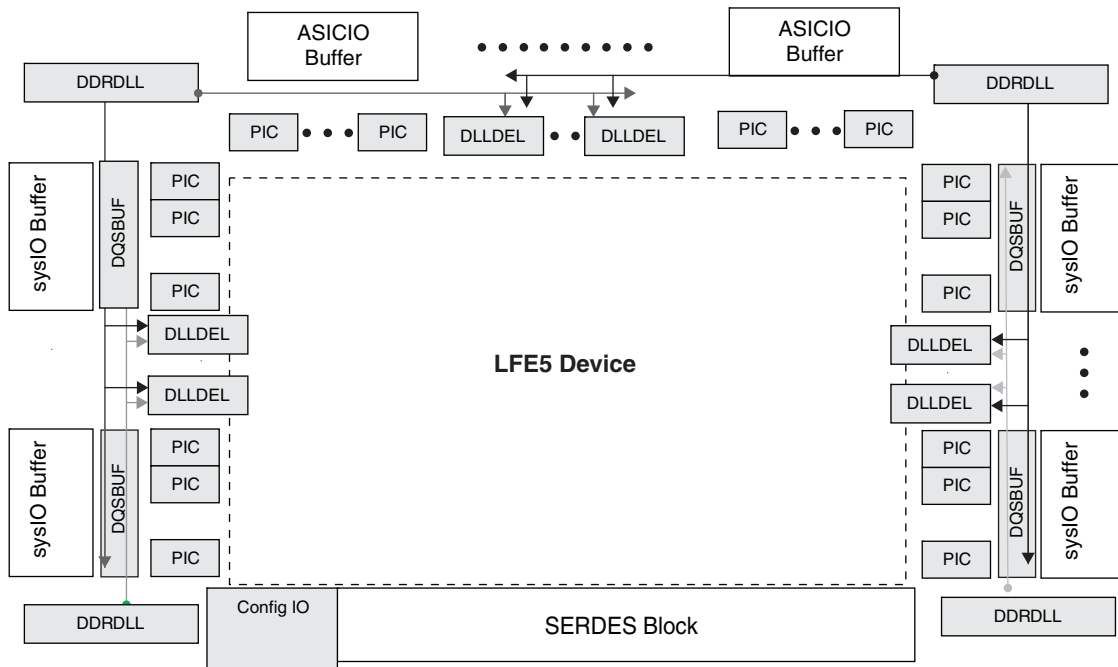


Table 2-5. DDRDLL Ports List

Port Name	I/O	Description
CLK	I	Reference clock input to the DDRDLL. Should run at the same frequency as the clock to the delayed.
RST	I	Reset Input to the DDRDLL
UDDCNTLN	I	Update Control to update the delay code. When low the delay code out the DDRDLL is updated. Should not be active during a read or a write cycle
FREEZE	I	FREEZE goes high and, without a glitch, turns off the DLL internal clock and the ring oscillator output clock. When FREEZE goes low, it turns them back on.
DDRDEL	O	The delay codes from the DDRDLL to be used in DQSBUF or DLLDEL
LOCK	O	Lock output to indicate the DDRDLL has valid delay output
DCNTL [7:0]	O	The delay codes from the DDRDLL available for the user IP.

There are 4 identical DDRDLL in the four corners in LFE5-85 and LFE5-45 devices, and two DDRDLLs in LFE5-25 devices. Each DDRDLL can generate delay code based on the reference frequency. The slave DLL (DQSBUF and DLLDEL) use the code to delay the signal, to create the phase shifted signal used for either DDR memory, or creating 90 degree shift clock. Figure 2-10 shows the DDRDLL and the slave DLLs on the top level view.

Figure 2-10. ECP5 DLL Top Level View



sysMEM Memory

ECP5 devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with memory core, dedicated input registers and output registers with separate clock and clock enable. Each EBR includes functionality to support true dual-port, pseudo dual-port, single-port RAM, ROM and FIFO buffers (via external PFUs).

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with 18-bit and 36-bit data widths. For more information, please see TN1264, [ECP5 Memory Usage Guide](#).

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1
	8,192 x 2
	4,096 x 4
	2,048 x 9
	1,024 x 18
	512 x 36
True Dual Port	16,384 x 1
	8,192 x 2
	4,096 x 4
	2,048 x 9
	1,024 x 18
	512 x 36
Pseudo Dual Port	16,384 x 1
	8,192 x 2
	4,096 x 4
	2,048 x 9
	1,024 x 18
	512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

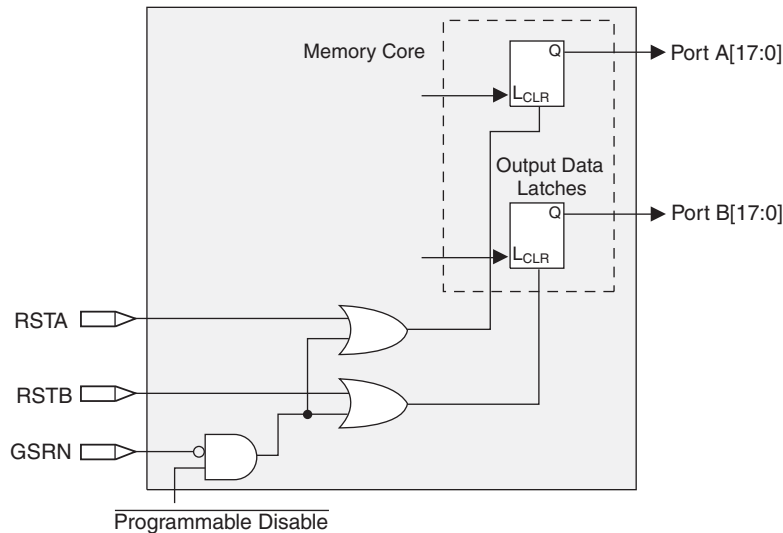
EBR memory supports the following forms of write behavior for single port or dual port operation:

- **Normal** – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
- **Write Through** – A copy of the input data appears at the output of the same port during a write cycle. This mode is supported for all data widths.
- **Read-Before-Write** – When new data is written, the old content of the address appears at the output. This mode is supported for x9, x18, and x36 data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously or synchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B, respectively. The Global Reset (GSRN) signal can reset both ports. The output data latches and associated resets for both ports are as shown in Figure 2-11.

Figure 2-11. Memory Core Reset



For further information on the sysMEM EBR block, please see the list of technical documentation at the end of this data sheet.

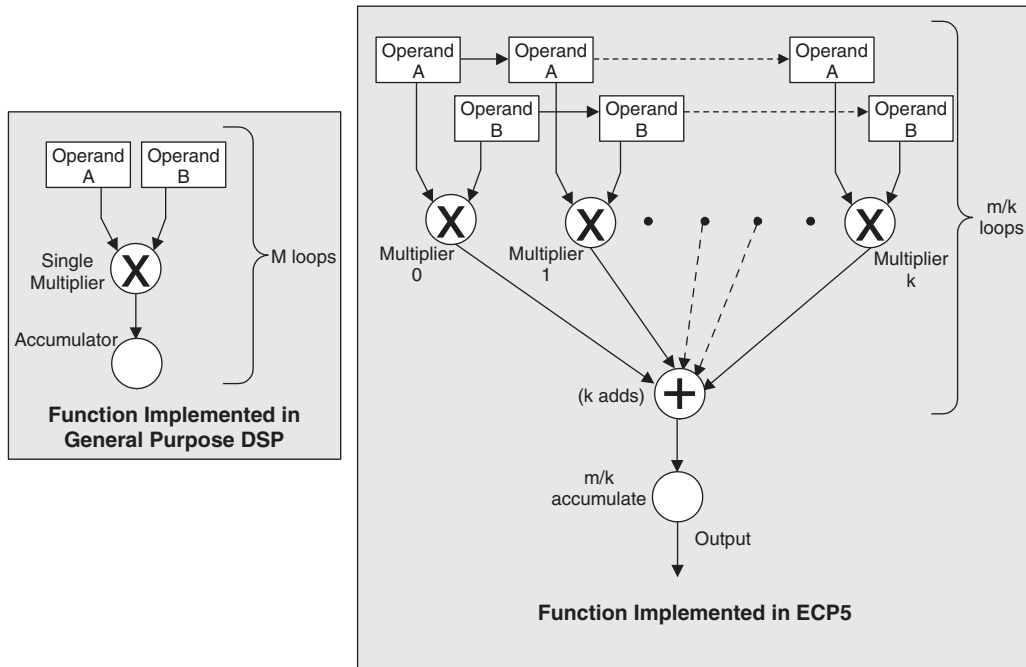
sysDSP™ Slice

The ECP5 family provides an enhanced sysDSP architecture, making it ideally suited for low-cost, high-performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Slice Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. In the ECP5 device family, there are many DSP slices that can be used to support different data widths. This allows designers to use highly parallel implementations of DSP functions. Designers can optimize DSP performance vs. area by choosing appropriate levels of parallelism. Figure 2-12 compares the fully serial implementation to the mixed parallel and serial implementation.

Figure 2-12. Comparison of General DSP and ECP5 Approaches



ECP5 sysDSP Slice Architecture Features

The ECP5 sysDSP Slice has been significantly enhanced to provide functions needed for advanced processing applications. These enhancements provide improved flexibility and resource utilization.

The ECP5 sysDSP Slice supports many functions that include the following:

- Fully double data rate support - Higher operation frequency (throughput of up to 370 Mbps) is achieved by double input and output interfaces that enable twice the fabric operation throughput for most of the operation modes.
- Symmetry support. The primary target application is wireless. 1D Symmetry is useful for many applications that use FIR filters when their coefficients have symmetry or asymmetry characteristics. The main motivation for using 1D symmetry is cost/size optimization. The expected size reduction is up to 2x.
 - Odd mode – Filter with Odd number of taps
 - Even mode – Filter with Even number of taps
 - Two dimensional (2D) symmetry mode – supports 2D filters for mainly video applications
- Dual-multiplier architecture. Lower accumulator overhead to half and the latency to half compared to single multiplier architecture
- Fully cascadable DSP across slices. Support for symmetric, asymmetric and non-symmetric filters.
- Multiply (one 18x36, two 18x18 or four 9x9 Multiplies per Slice)
- Multiply (36x36 by cascading across two sysDSP slices)
- Multiply Accumulate (supports one 18x36 multiplier result accumulation or two 18x18 multiplier result accumulation)
- Two Multiplies feeding one Accumulate per cycle for increased processing with lower latency (two 18x18 Multiplies feed into an accumulator that can accumulate up to 52 bits)
- Pipeline registers

- 1D Symmetry support. The coefficients of FIR filters have symmetry or negative symmetry characteristics.
 - Odd mode – Filter with Odd number of taps
 - Even mode – Filter with Even number of taps
- 2D Symmetry support. The coefficients of 2D FIR filters have symmetry or negative symmetry characteristics.
 - 3*3 and 3*5 – Internal DSP Slice support
 - 5*5 and larger size 2D blocks – Semi internal DSP Slice support
- Flexible saturation and rounding options to satisfy a diverse set of applications situations
- Flexible cascading across DSP slices
 - Minimizes fabric use for common DSP and ALU functions
 - Enables implementation of FIR Filter or similar structures using dedicated sysDSP slice resources only
 - Provides matching pipeline registers
 - Can be configured to continue cascading from one row of sysDSP slices to another for longer cascade chains
- Flexible and Powerful Arithmetic Logic Unit (ALU) Supports:
 - Dynamically selectable ALU OP CODE
 - Ternary arithmetic (addition/subtraction of three inputs)
 - Bit-wise two-input logic operations (AND, OR, NAND, NOR, XOR and XNOR)
 - Eight flexible and programmable ALU flags that can be used for multiple pattern detection scenarios, such as, overflow, underflow and convergent rounding, etc.
 - Flexible cascading across slices to get larger functions
- RTL Synthesis friendly synchronous reset on all registers, while still supporting asynchronous reset for legacy users
- Dynamic MUX selection to allow Time Division Multiplexing (TDM) of resources for applications that require processor-like flexibility that enables different functions for each clock cycle

For most cases, as shown in Figure 2-13, the ECP5 sysDSP slice is backwards-compatible with the LatticeECP2™ and LatticeECP3™ sysDSP block, such that, legacy applications can be targeted to the ECP5 sysDSP slice. Figure 2-13 shows the Diagram of the sysDSP, and Figure 2-14 shows the detailed diagram.

Figure 2-13. Simplified sysDSP Slice Block Diagram

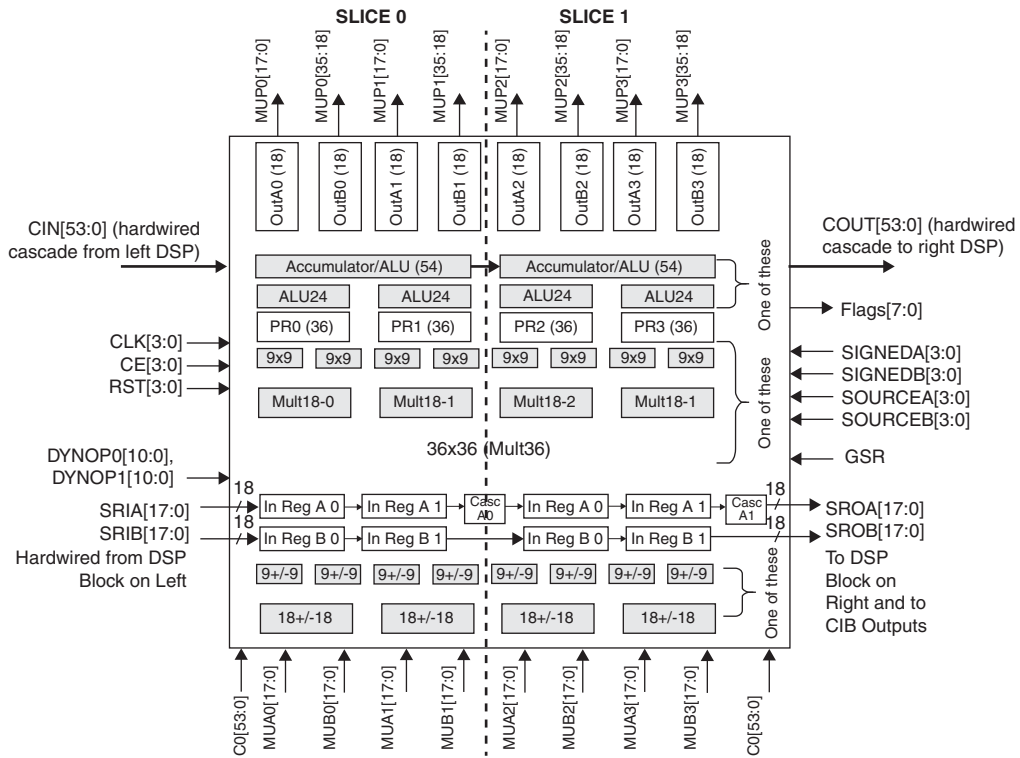
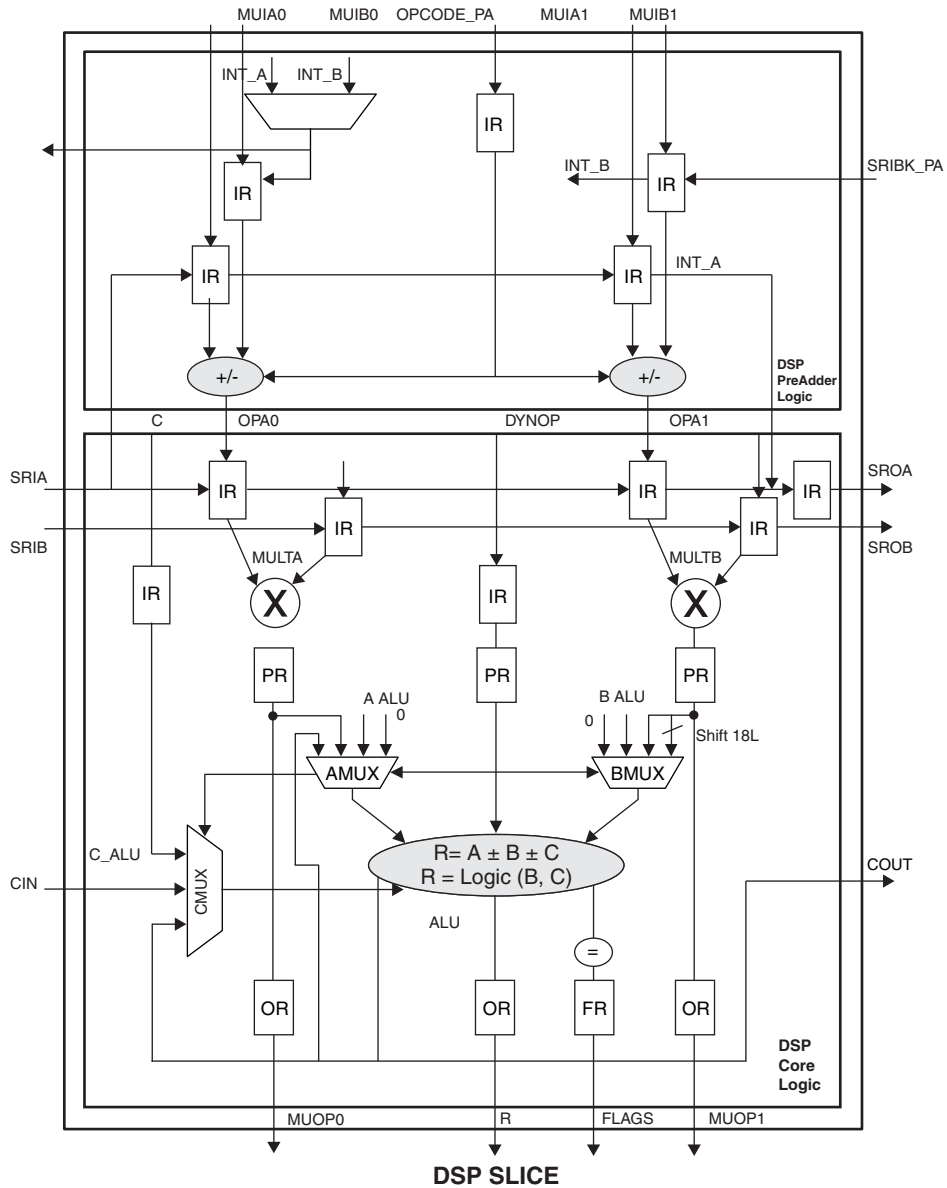


Figure 2-14. Detailed sysDSP Slice Diagram



In Figure 2-14, note that A_ALU, B_ALU and C_ALU are internal signals generated by combining bits from AA, AB, BA, BB and C inputs. For further information, please refer to TN1267, [ECP5 sysDSP Usage Guide](#).

The ECP5 sysDSP block supports the following basic elements.

- MULT (Multiply)
- MAC (Multiply, Accumulate)
- MULTADDSUB (Multiply, Addition/Subtraction)
- MULTADDSUBSUM (Multiply, Addition/Subtraction, Summation)

Table 2-7 shows the capabilities of each of the ECP5 slices versus the above functions.

Table 2-7. Maximum Number of Elements in a Slice

Width of Multiply	x9	x18	x36
MULT	4	2	1/2
MAC	1	1	—
MULTADDSUB	2	1	—
MULTADDSUBSUM	1 ¹	1/2	—

1. One slice can implement 1/2 9x9 m9x9addsubsum and two m9x9addsubsum with two slices.

Some options are available in the four elements. The input register in all the elements can be directly loaded or can be loaded as a shift register from previous operand registers. By selecting “dynamic operation” the following operations are possible:

- In the Add/Sub option the Accumulator can be switched between addition and subtraction on every cycle.
- The loading of operands can switch between parallel and serial operations.

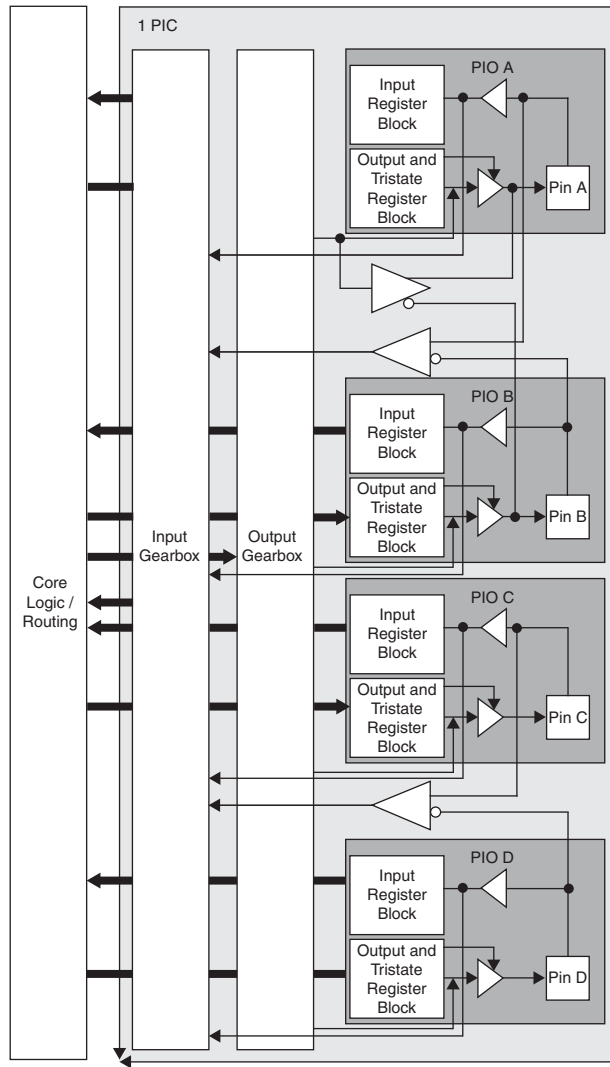
For further information, please refer to TN1267, [ECP5 sysDSP Usage Guide](#).

Programmable I/O Cells (PIC)

The programmable logic associated with an I/O is called a PIO. The individual PIO are connected to their respective sysIO buffers and pads. On the ECP5 devices, the PIO cells are assembled into groups of four PIO cells called a Programmable I/O Cell or PIC. The PICs are placed on all four sides of the device.

On all the ECP5 devices, two adjacent PIOs can be combined to provide a complementary output driver pair. All PIO pairs can implement differential receivers. Half of the PIO pairs on the left and right edges of these devices can be configured as true LVDS transmit pairs.

Figure 2-15. Group of Four Programmable I/O Cells on Left/Right Sides



PIO

The PIO contains three blocks: an input register block, output register block and tristate register block. These blocks contain registers for operating in a variety of modes along with the necessary clock and selection logic.

Input Register Block

The input register blocks for the PIOs on all edges contain delay elements and registers that can be used to condition high-speed interface signals before they are passed to the device core. In addition the input register blocks for the PIOs on the left and right edges include built-in FIFO logic to interface to DDR and LPDDR memory.

The Input register block on the right & left sides includes gearing logic and registers to implement IDDRX1, IDDRX2 functions. With two PICs sharing the DDR register path, it can also implement IDDRX71 function used for 7:1 LVDS interfaces. It uses three sets of registers -- shift, update, and transfer to implement gearing and the clock domain transfer. The first stage registers samples the high-speed input data by the high-speed edge clock on its rising and falling edges. The second stage registers perform data alignment based on the control signals. The third stage pipeline registers pass the data to the device core synchronized to the low-speed system clock. The Top side of the device will support IDDRX1 gearing function. For more information on gearing function, refer to TN1265, [ECP5 High-Speed I/O Interface](#).

Figure 2-16 shows the input register block for the PIOs on the top edge.

Figure 2-16. Input Register Block for PIO on Top Side of the Device

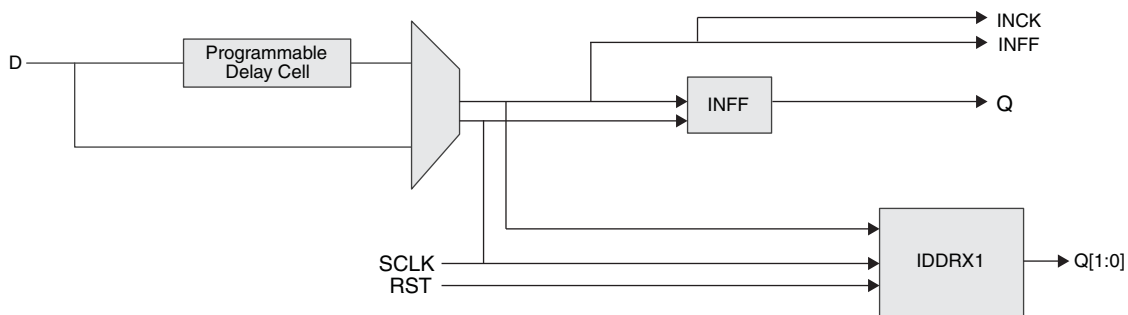
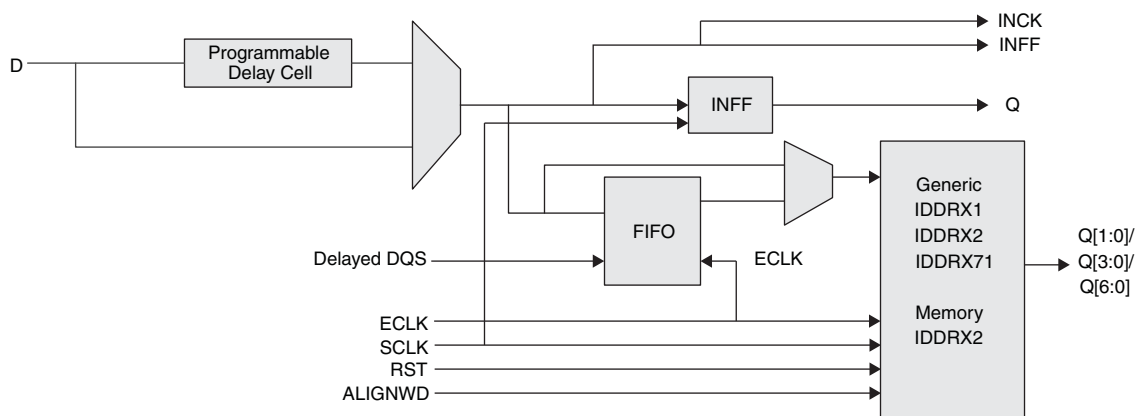


Figure 2-17 shows the input register block for the PIOs located on the left and right edges.

Figure 2-17. Input Register Block for PIO on Left and Right Side of the Device



Input FIFO

The ECP5 PIO has dedicated input FIFO per single-ended pin for input data register for DDR Memory interfaces. The FIFO resides before the gearing logic. It transfers data from DQS domain to continuous ECLK domain. On the Write side of the FIFO, it is clocked by DQS clock which is the delayed version of the DQS Strobe signal from DDR memory. On the Read side of FIFO, it is clocked by ECLK. ECLK may be any high speed clock with identical frequency as DQS (the frequency of the memory chip). Each DQS group has one FIFO control block. It distributes FIFO read/write pointer to every PIC in same DQS group. DQS Grouping and DQS Control Block is described in DDR memory Support section below.

Table 2-8. Input Block Port Description

Name	Type	Description
D	Input	High Speed Data Input
Q[1:0]/Q[3:0]/Q[6:0]	Output	Low Speed Data to the device core
RST	Input	Reset to the Output Block
SCLK	Input	Slow Speed System Clock
ECLK	Input	High Speed Edge Clock
DQS	Input	Clock from DQS control Block used to clock DDR memory data
ALIGNWD	Input	Data Alignment signal from device core.

Output Register Block

The output register block registers signals from the core of the device before they are passed to the sysIO buffers.

ECP5 output data path has output programmable flip flops and output gearing logic. On the left and right sides the output register block can support 1x, 2x and 7:1 gearing enabling high speed DDR interfaces and DDR memory interfaces. On the top side, the banks will support 1x gearing. ECP5 output data path diagram is shown in Figure 2-18. The programmable delay cells are also available in the output data path.

For detailed description of the output register block modes and usage, you can refer to TN1265, [ECP5 High-Speed I/O Interface](#).

Figure 2-18. Output Register Block on Top Side

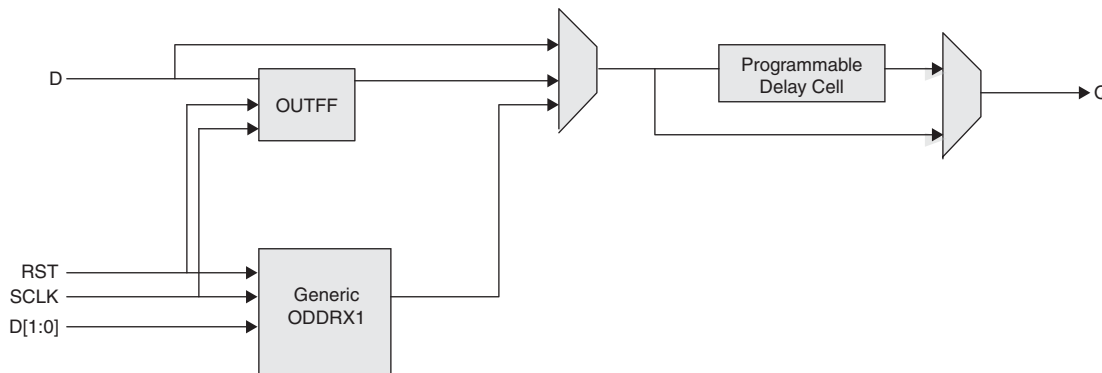


Figure 2-19. Output Register Block on Left and Right Sides

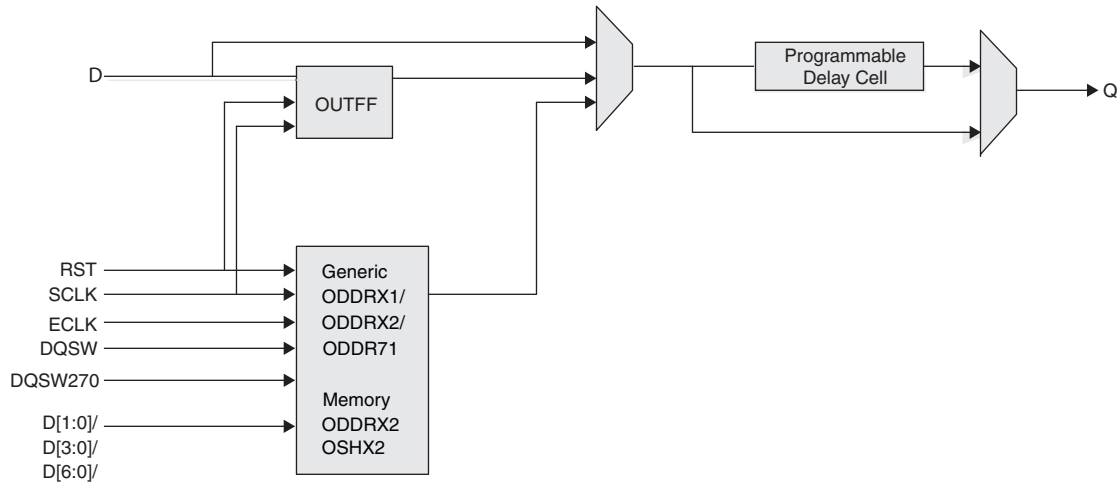


Table 2-9. Output Block Port Description

Name	Type	Description
Q	Output	High Speed Data Output
D	Input	Data from core to output SDR register
D[1:0]/D[3:0]/ D[6:0]	Input	Low Speed Data from device core to output DDR register
RST	Input	Reset to the Output Block
SCLK	Input	Slow Speed System Clock
ECLK	Input	High Speed Edge Clock
DQSW	Input	Clock from DQS control Block used to generate DDR memory DQS output
DQSW270	Input	Clock from DQS control Block used to generate DDR memory DQ output

Tristate Register Block

The tristate register block registers tristate control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation. In SDR, TD input feeds one of the flip-flops that then feeds the output. In DDR operation used mainly for DDR memory interface can be implemented on the left and right sides of the device. Here 2 inputs feed the tristate registers clocked by both ECLK and SCLK.

Figure 2-19 and Figure 2-20 show the Tristate Register Block functions on the device. For detailed description of the tristate register block modes and usage, you can refer to TN1265, [ECP5 High-Speed I/O Interface](#).

Figure 2-20. Tristate Register Block on Top Side

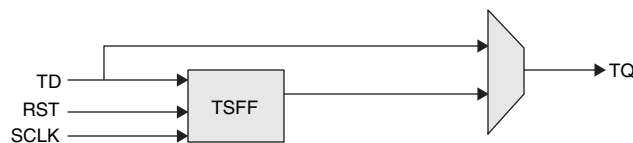


Figure 2-21. Tristate Register Block on Left and Right Sides

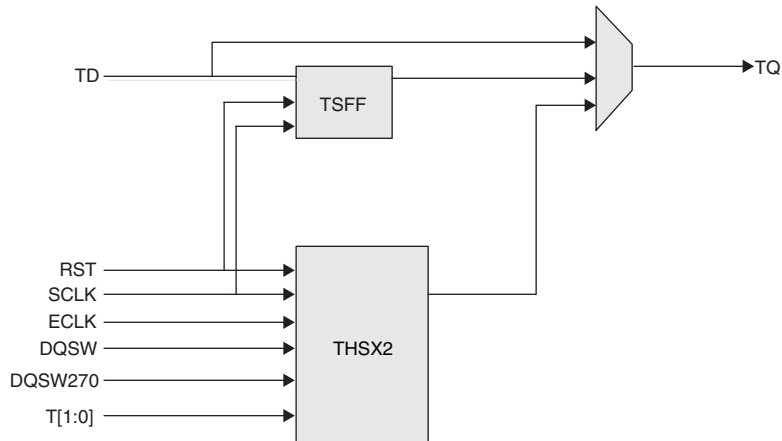


Table 2-10. Tristate Block Port Description

Name	Type	Description
TD	Input	Tristate Input to Tristate SDR Register
RST	Input	Reset to the Tristate Block
TD[1:0]	Input	Tristate input to TSHX2 function
SCLK	Input	Slow Speed System Clock
ECLK	Input	High Speed Edge Clock
DQSW	Input	Clock from DQS control Block used to generate DDR memory DQS output
DQSW270	Input	Clock from DQS control Block used to generate DDR memory DQ output
TQ	Output	Output of the Tristate block

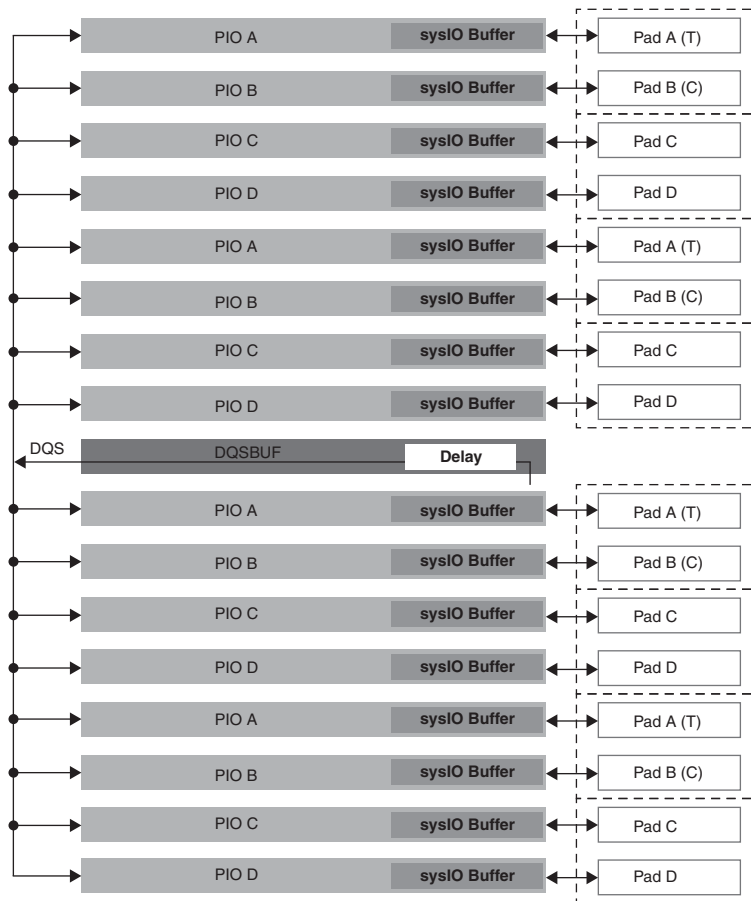
DDR Memory Support

DQS Grouping for DDR Memory

Certain PICs have additional circuitry to allow the implementation of high-speed source synchronous and DDR2, DDR3, LPDDR2 or LPDDR3 memory interfaces. The support varies by the edge of the device as detailed below.

The left and right sides of the PIC have fully functional elements supporting DDR2, DDR3, LPDDR2 or LPDDR3 memory interfaces. One of every 12 to 16 PIOs supports the dedicated DQS pins with the DQS control logic block. Figure 2-22 shows the DQS bus spanning 16 I/O pins. Two of every 16 PIOs support the dedicated DQS and DQS# pins with the DQS control logic block.

Figure 2-22. DQS Grouping on the Left and Right Edges



DLL Calibrated DQS Delay and Control Block (DQSBUF)

To support DDR memory interfaces (DDR2/3, LPDDR2/3), the DQS strobe signal from the memory must be used to capture the data (DQ) in the PIC registers during memory reads. This signal is output from the DDR memory device aligned to data transitions and must be time shifted before it can be used to capture data in the PIC. This time shifted is achieved by using DQSDEL programmable delay line in the DQS Delay Block (DQS read circuit). The DQSDEL is implemented as a slave delay line and works in conjunction with a master DDRDLL.

This block also includes slave delay line to generate delayed clocks used in the write side to generate DQ and DQS with correct phases within one DQS group. There is a third delay line inside this block used to provide write leveling feature for DDR write if needed.

Each of the read and write side delays can be dynamically shifted using margin control signals that can be controlled by the core logic.

FIFO Control Block include here generates the Read and Write Pointers for the FIFO block inside the Input Register Block. These pointers are generated to control the DQS to ECLK domain crossing using the FIFO module.

Figure 2-23. DQS Control & Delay Block (DQSBUF)

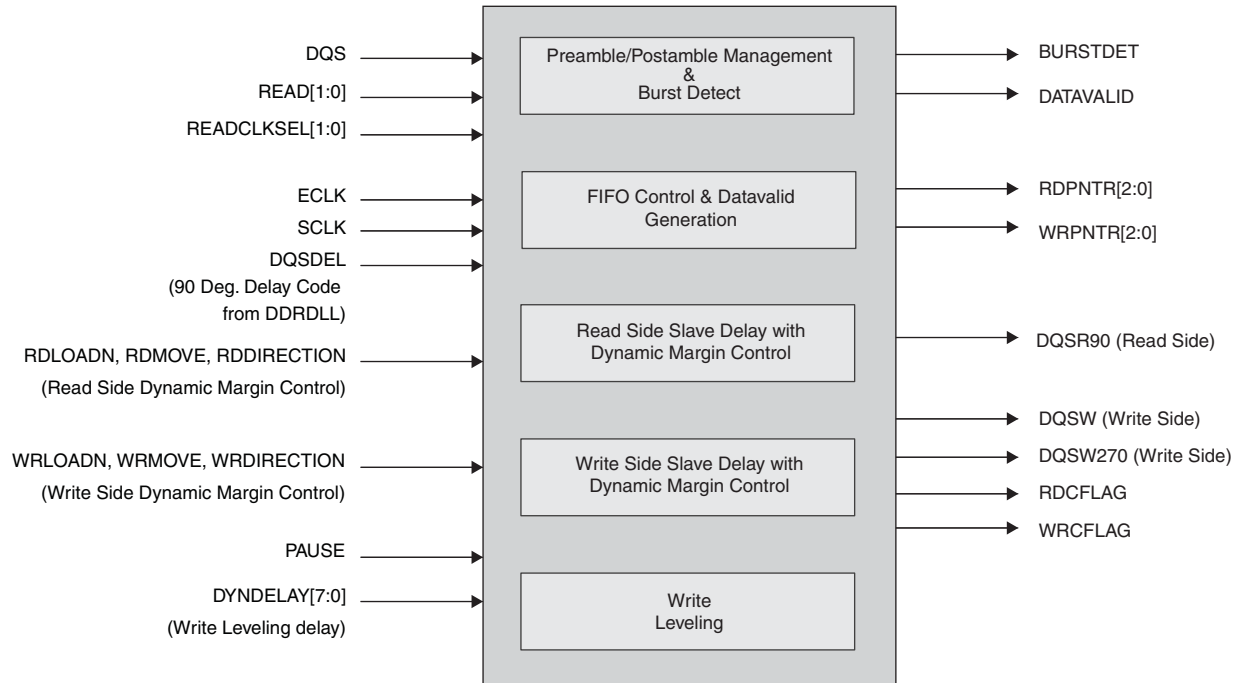


Table 2-11. DQSBUF Port list description

Name	Type	Description
DQS	Input	DDR memory DQS strobe
READ[1:0]	Input	Read Input from DDR Controller
READCLKSEL[1:0]	Input	Read pulse selection
SCLK	Input	Slow System Clock
ECLK	Input	High Speed Edge Clock (same frequency as DDR memory)
DQSDEL	Input	90 Deg Delay Code from DDRDLL
RDLOADN, RDMOVE, RDDIRECTION	Input	Dynamic Margin Control ports for Read delay
WRLOADN, WRMOVE, WRDIRECTION	Input	Dynamic Margin Control ports for Write delay
PAUSE	Input	Used by DDR Controller to Pause write side signals during DDRDLL Code update or Write Leveling
DYNDELAY[7:0]	Input	Dynamic Write Leveling Delay Control
DQSR90	Output	90 delay DQS used for Read
DQSW270	Output	90 delay clock used for DQ Write
DQSW	Output	Clock used for DQS Write
RDPNTR[2:0]	Output	Read Pointer for IFIFO module
WRPNTR[2:0]	Output	Write Pointer for IFIFO module
DATAVALID	Output	Signal indicating start of valid data
BURSTDET	Output	Burst Detect indicator
RDFLAG	Output	Read Dynamic Margin Control output to indicate max value
WRFLAG	Output	Write Dynamic Margin Control output to indicate max value

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in groups referred to as banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVDS, HSUL, BLVDS, SSTL Class I & II, LVCMOS, LVTTTL, LVPECL, and MIPI.

sysI/O Buffer Banks

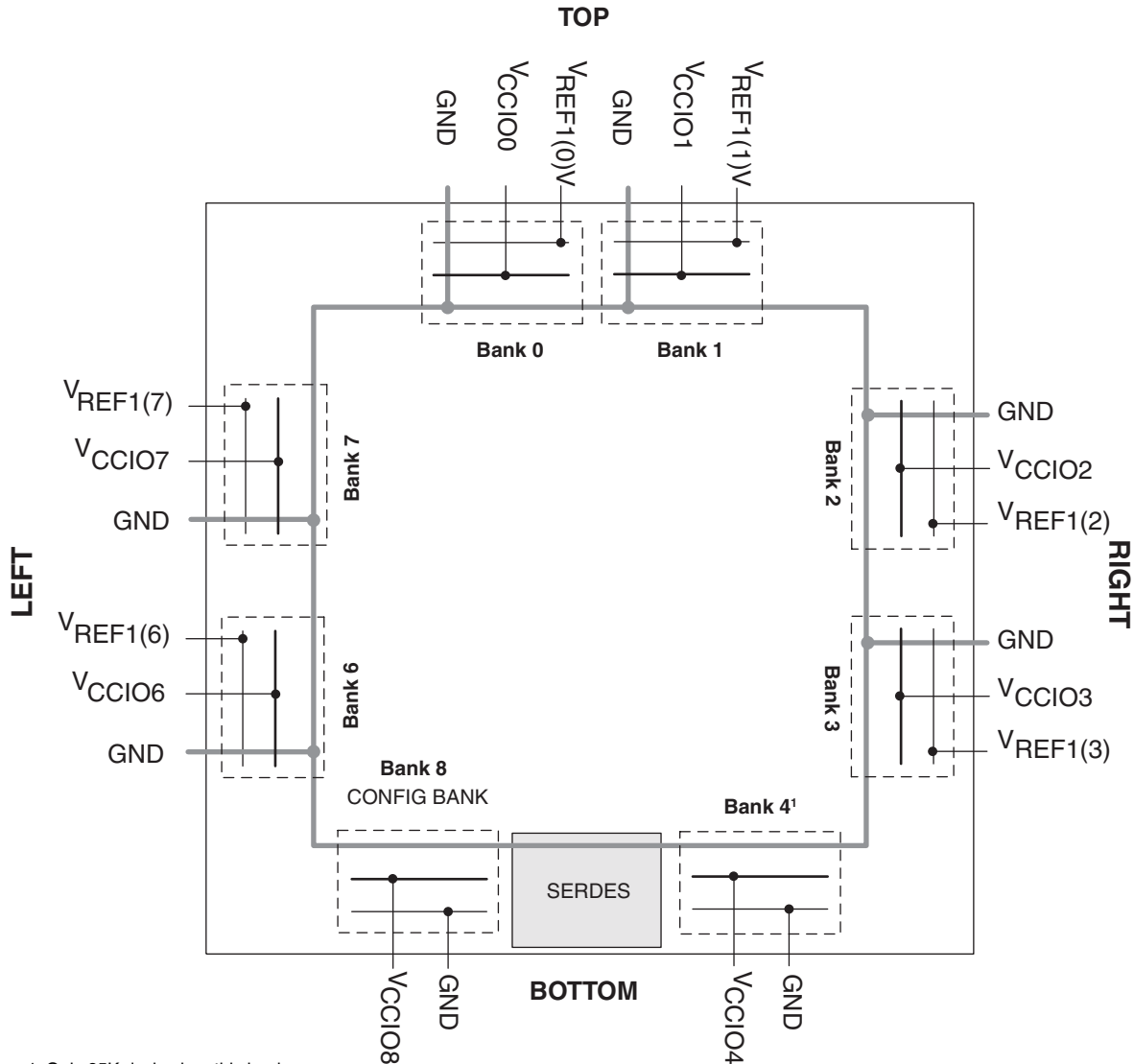
ECP5 devices have seven sysI/O buffer banks, two banks per side at Top, Left and Right, plus one at the bottom left side. The bottom left side bank (Bank 8) is a shared I/O bank. The I/Os in that bank contains both dedicated and shared I/O for sysConfig function. When a shared pin is not used for configuration, It is available as a user I/O. For LFE5-85 devices, there is an additional I/O bank (Bank 4) that is not available in other device in the family.

In ECP5 devices, the Left and Right sides are tailored to support high performance interfaces, such as DDR2, DDR3, LPDDR2, LPDDR3 and other high speed source synchronous standards. The banks on the Left and Right sides of the devices feature LVDS input and output buffers, data-width gearing, and DQSBUF block to support DDR2/3 and LPDDR2/3 interfaces. The I/Os on the top and bottom banks do not have LVDS input and output buffer, and gearing logic, but can use LVCMOS to emulate most of differential output signaling.

Each sysIO bank has its own I/O supply voltage (V_{CCIO}). In addition, the banks on the Left and Right sides of the device, have voltage reference input (shared I/O pin), VREF1 per bank, which allow it to be completely independent of each other. The VREF voltage is used to set the threshold for the referenced input buffers, such as SSTL. Figure 2-24 shows the seven banks and their associated supplies.

In ECP5 devices, single-ended output buffers and ratioed input buffers (LVTTTL, and LVCMOS) are powered using V_{CCIO} . LVTTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold inputs independent of V_{CCIO} .

Figure 2-24. ECP5 Device Family Banks



1. Only 85K device has this bank.

ECP5 devices contain two types of sysI/O buffer pairs.

- **Top (Bank 0 and Bank 1) and Bottom (Bank 8 and Bank 4) sysI/O Buffer Pairs (Single-Ended Only)**

The sysI/O buffers in the Banks at top and bottom of the device consist of ratioed single-ended output drivers and single-ended input buffers. The I/Os in these banks are not usually used as a pair, except when used as emulated differential output pair. They are used as individual I/Os and be configured as different I/O modes, as long as they are compatible with the V_{ccio} voltage in the bank. When used as emulated differential outputs, the pair can be used together.

The top and bottom side IOs also support hot socketing. They support IO standards from 3.3 V to 1.2 V. They are ideal for general purpose I/Os, or as ADDR/CMD bus for DDR2/DDR3 applications, or for used as emulated differential signaling.

Bank 4 I/O only exists in the LFE5-85 device.

Bank 8 is a bottom bank that shares with sysConfig I/Os. During configuration, these I/Os are used for programming the device. Once the configuration is completed, these I/Os can be released and user can use these I/Os for functional signals in his design.

The top and bottom side pads can be identified by the Lattice Diamond tool.

- **Left and Right (Banks 2, 3, 6 and 7) sys/I/O Buffer Pairs (50% Differential and 100% Single-Ended Outputs)**

The sys/I/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. One of the referenced input buffers can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

In addition, programmable on-chip input termination (parallel or differential, static or dynamic) is supported on these sides, which is required for DDR3 interface. However, there is no support for hot-socketing for the I/O pins located on the left and right side of the device as the PCI clamp is always enabled on these pins.

LVDS differential output drivers are available on 50% of the buffer pairs on the left and right banks.

Typical sys/I/O I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} , V_{CCIO8} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in ECP5 devices, see the list of technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported sys/I/O Standards

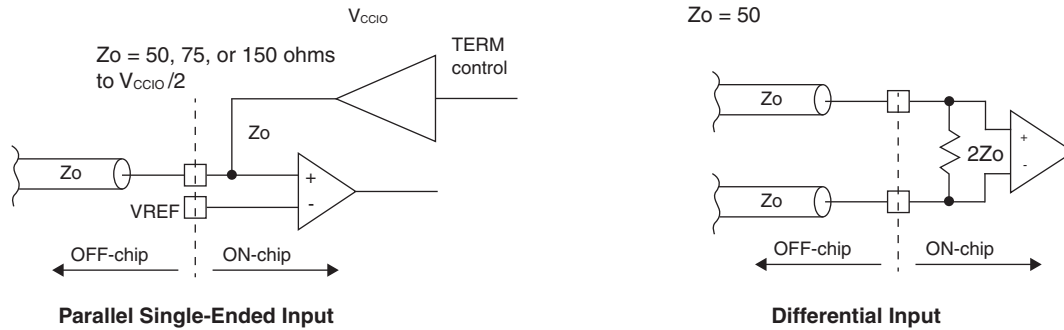
The ECP5 sys/I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTTL and other standards. The buffers support the LVTTTL, LVCMOS 1.2V, 1.5V, 1.8 V, 2.5 V and 3.3 V standards. In the LVCMOS and LVTTTL modes, the buffer has individual configuration options for drive strength, slew rates, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSUL. Differential standards supported include LVDS, differential SSTL and differential HSUL. For further information on utilizing the sys/I/O buffer to support a variety of standards, please see TN1262, [ECP5 sysIO Usage Guide](#).

On-Chip Programmable Termination

The ECP5 devices support a variety of programmable on-chip terminations options, including:

- Dynamically switchable Single-Ended Termination with programmable resistor values of 50, 75, or 150 ohms.
- Common mode termination of 100 ohms for differential inputs

Figure 2-25. On-Chip Termination



See Table 2-12 for termination options for input modes.

Table 2-12. On-Chip Termination Options for Input Modes

IO_TYPE	TERMINATE to Vccio/21	DIFFERENTIAL TERMINATION RESISTOR1
LVDS25	-	100
BLVDS25	-	100
MLVDS	-	100
LVPECL33	-	100
subLVDS	-	100
SLVS	-	100
HSUL12	50, 75, 150	-
HSUL12D	-	100
SSTL135_I / II	50, 75, 150	-
SSTL135D_I / II	-	100
SSTL15_I / II	50, 75, 150	-
SSTL15D_I / II	-	100
SSTL18_I / II	50, 75, 150	-
SSTL18D_I / II	-	100

1. TERMINATE to VCCIO/2 (Single-Ended) and DIFFERENTIAL TERMINATION RESISTOR when turned on can only have one setting per bank. Only left and right banks have this feature.
Use of TERMINATE to VCCIO/2 and DIFFERENTIAL TERMINATION RESISTOR are mutually exclusive in an I/O bank.
On-chip termination tolerance +/- 20%.

Please see TN1262, [ECP5 sysIO Usage Guide](#) for on-chip termination usage and value ranges.

Hot Socketing

ECP5 devices have been carefully designed to ensure predictable behavior during power-up and power-down. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled within specified limits. Please refer to the Hot Socketing Specifications in the DC and Switching Characteristics in this data sheet.

SERDES and PCS (Physical Coding Sublayer)

LFE5UM devices feature up to 4 channels of embedded SERDES/PCS arranged in dual-channel blocks at the bottom of the devices supporting up to 3.2 Gbps data rate. Figure 2-26 shows the position of the dual blocks for the LFE5-85. Table 2-13 shows the location of available SERDES Duals for all devices. The LFE5UM SERDES/PCS supports a range of popular serial protocols, including:

- PCI Express 2.0 (2.5 Gbps)

- Ethernet (XAUI, GbE - 1000 Base CS/SX/LX and SGMII)
- Serial RapidIO (SR and LR, Type 1: 1.25 Gbps, Type 2: 2.5 Gbps, Type 3: 3.125 Gbps)
- SMPTE SDI (3G, HD, SD)
- CPRI (E.6.LV: 614.4 Mbps, E.12.LV: 1228.8 Mbps, E.24.V: 2457.6 Mbps, E.30.LV: 3072 Mbps)
- JESD204A/B – ADC and DAC converter interface: 312.5 Mbps to 3.125 Gbps

Each dual contains two dedicated SERDES for high speed, full duplex serial data transfer. Each dual also has a PCS block that interfaces to the SERDES channels and contains protocol specific digital logic to support the standards listed above. The PCS block also contains interface logic to the FPGA fabric. All PCS logic for dedicated protocol support can also be bypassed to allow raw 8-bit or 10-bit interfaces to the FPGA fabric.

Even though the SERDES/PCS blocks are arranged in duals, multiple baud rates can be supported within a dual with the use of dedicated, per channel /1, /2 and /11 rate dividers. Additionally, two duals can be arranged together to form x4 channel link.

When a SERDES Dual in a 2-Dual device is not used, the power VCCA power supply for that Dual should be connected. It is advised to connect the VCCA of unused channel to core if the user knows he will not use the Dual at all, or it should be connected to a different regulated 1.1 V supply, if that Dual maybe used in the future.

For an unused channel in a Dual, it is advised to connect the VCCHTX to VCCA, and user can leave VCCHRX unconnected.

For information on how to use the SERDES/PCS blocks to support specific protocols, as well on how to combine multiple protocols and baud rates within a device, please refer to TN1261, [ECP5 SERDES/PCS Usage Guide](#).

Figure 2-26. SERDES/PCS Duals (LFE5UM-85)

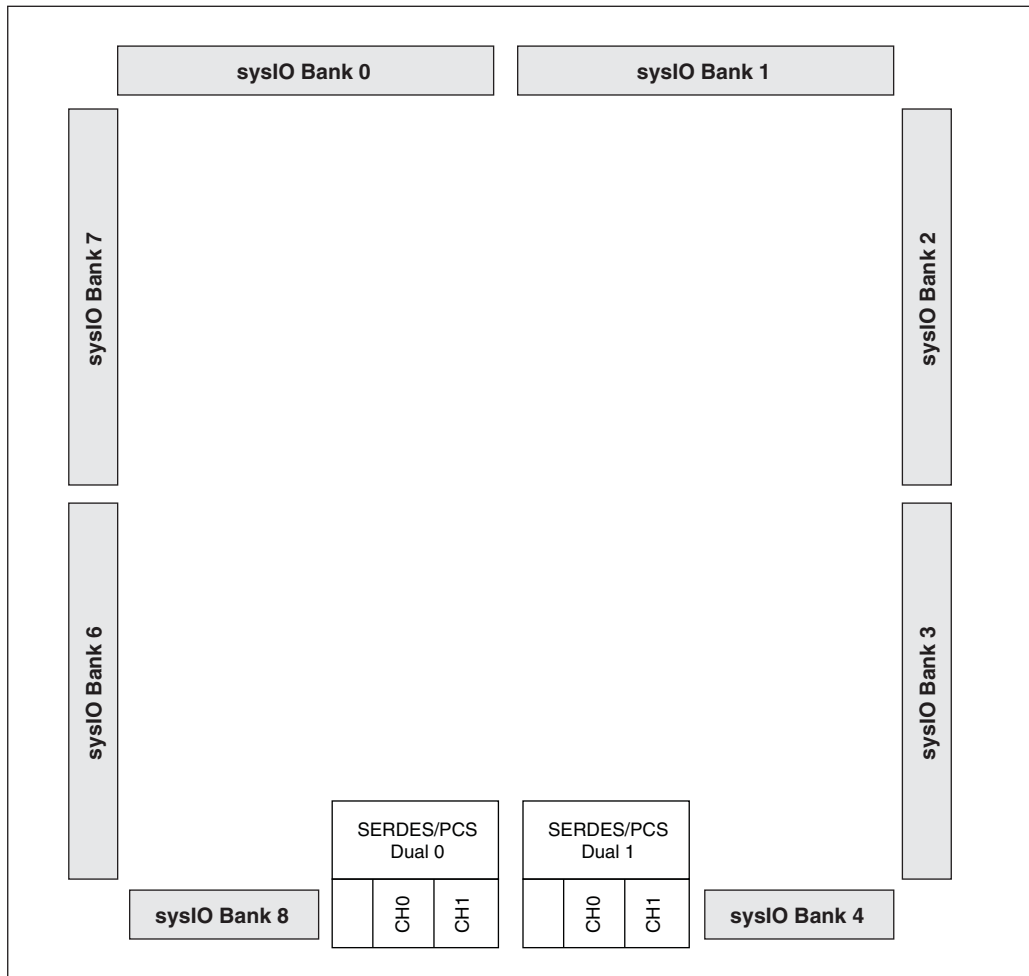


Table 2-13. LFE5UM SERDES Standard Support

Standard	Data Rate (Mbps)	Number of General/Link Width	Encoding Style
PCI Express 1.1	2500	x1, x2, x4	8b10b
Gigabit Ethernet	1250, 2500	x1	8b10b
SGMII	1250	x1	8b10b
XAUI	3125	x4	8b10b
Serial RapidIO Type I	1250	x1, x4	8b10b
Serial RapidIO Type II	2500		
Serial RapidIO Type III	3125		
CPRI-1	614.4	x1	8b10b
CPRI-2	1228.8		
CPRI-3	2457.6		
CPRI-4	3072.0		
SD-SDI (259M, 344M) ¹	270, 360, 540	x1	NRZI/ Scrambled
HD-SDI (292M)	1483.5 1485	x1	NRZI/ Scrambled
3G-SDI (424M)	2967, 2970	x1	NRZI/ Scrambled
JESD204A/B	3125	x1	8b/10b

1. For slower rates, the SERDES are bypassed and CML signals are directly connected to the FPGA routing.

Table 2-14. Available SERDES Duals per LFE5UM Devices

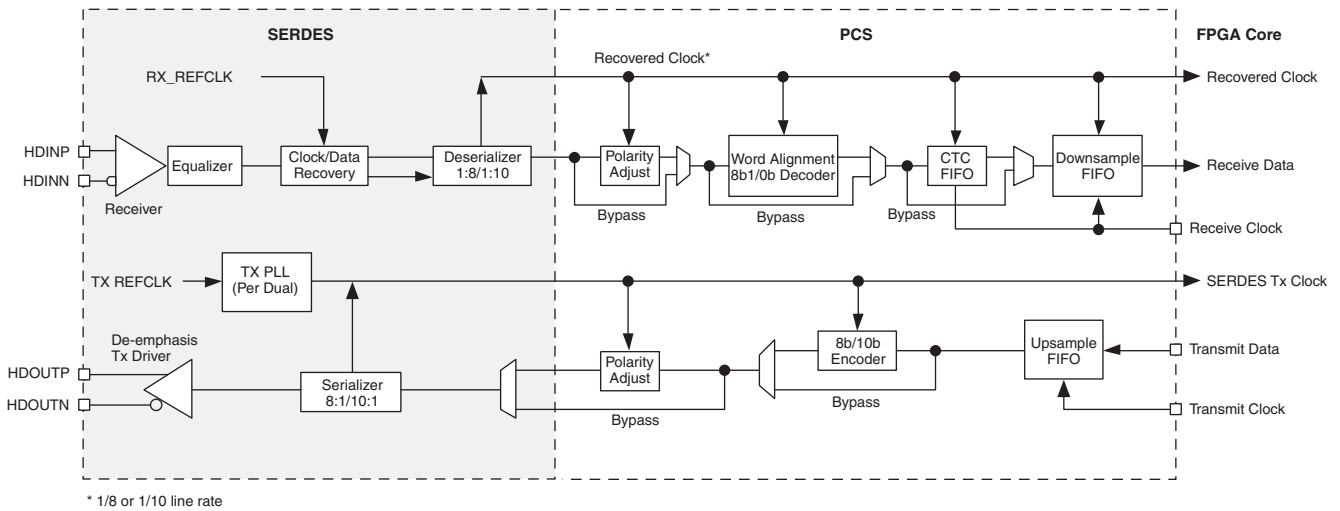
Package	LFE5UM-25	LFE5UM-45	LFE5UM-85
285 csfBGA	1	1	1
381 caBGA	1	2	2
554 caBGA	—	2	2
756 caBGA	—	—	2

SERDES Block

A SERDES receiver channel may receive the serial differential data stream, equalize the signal, perform Clock and Data Recovery (CDR) and de-serialize the data stream before passing the 8- or 10-bit data to the PCS logic. The SERDES transmitter channel may receive the parallel 8- or 10-bit data, serialize the data and transmit the serial bit stream through the differential drivers. Figure 2-27 shows a single-channel SERDES/PCS block. Each SERDES channel provides a recovered clock and a SERDES transmit clock to the PCS block and to the FPGA core logic.

Each transmit channel, receiver channel, and SERDES PLL shares the same power supply (VCCA). The output and input buffers of each channel have their own independent power supplies (VCCHTX and VCCHRX).

Figure 2-27. Simplified Channel Block Diagram for SERDES/PCS Block



PCS

As shown in Figure 2-27, the PCS receives the parallel digital data from the deserializer and selects the polarity, performs word alignment, decodes (8b/10b), provides Clock Tolerance Compensation and transfers the clock domain from the recovered clock to the FPGA clock via the Down Sample FIFO.

For the transmit channel, the PCS block receives the parallel data from the FPGA core, encodes it with 8b/10b, selects the polarity and passes the 8/10 bit data to the transmit SERDES channel.

The PCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic. The PCS interface to the FPGA can also be programmed to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic.

Some of the enhancements in LFE5UM SERDES/PCS include:

- Higher clock/channel granularity: Dual channel architecture provides more clock resource per channel.
- Enhanced Tx de-emphasis: Programmable pre- and post- cursors improves Tx output signaling
- Bit-slip function in PCS: Improves logic needed to perform Word Alignment function

Please refer to TN1261, [ECP5 SERDES/PCS Usage Guide](#) for more information.

SCI (SERDES Client Interface) Bus

The SERDES Client Interface (SCI) is an IP interface that allows the SERDES/PCS Dual block to be controlled by registers rather than the configuration memory cells. It is a simple register configuration interface that allows SERDES/PCS configuration without power cycling the device.

The Diamond design tools support all modes of the PCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow users to define their own operation. With these tools, the user can define the mode for each dual in a design.

Popular standards such as 10Gb Ethernet, x4 PCI Express and 4x Serial RapidIO can be implemented using IP (available through Lattice), with two duals (Four SERDES channels and PCS) and some additional logic from the core.

The LFE5UM devices support a wide range of primary and secondary protocols. Within the same dual, the LFE5UM devices support mixed protocols with semi-independent clocking as long as the required clock frequen-

cies are integer x1, x2, or x11 multiples of each other. Table 2-15 lists the allowable combination of primary and secondary protocol combinations.

Flexible Dual SERDES Architecture

The LFE5UM SERDES architecture is a dual channel-based architecture. For most SERDES settings and standards, the whole dual (consisting of two SERDES channels) is treated as a unit. This helps in silicon area savings, better utilization, higher granularity on clock/SERDES channel and overall lower cost.

However, for some specific standards, the LFE5UM dual-channel architecture provides flexibility; more than one standard can be supported within the same dual.

Table 2-15 shows the standards that can be mixed and matched within the same dual. In general, the SERDES standards whose nominal data rates are either the same or a defined subset of each other, can be supported within the same dual. In Table 2-15, the two Protocol columns define the different combinations of protocols that can be implemented together within a Dual.

Table 2-15. LFE5UM Mixed Protocol Support

Protocol		Protocol
PCI Express 1.1	with	SGMII
PCI Express 1.1	with	Gigabit Ethernet
PCI Express 1.1	with	Serial RapidIO Type I
PCI Express 1.1	with	Serial RapidIO Type II
Serial RapidIO Type I	with	SGMII
Serial RapidIO Type I	with	Gigabit Ethernet
Serial RapidIO Type II	with	SGMII
Serial RapidIO Type II	with	Gigabit Ethernet
Serial RapidIO Type II	with	Serial RapidIO Type I
CPRI-3	with	CPRI-2 and CPRI-1
3G-SDI	with	HD-SDI and SD-SDI

There are some restrictions to be aware of when using spread spectrum. When a dual shares a PCI Express x1 channel with a non-PCI Express channel, ensure that the reference clock for the dual is compatible with all protocols within the dual. For example, a PCI Express spread spectrum reference clock is not compatible with most Gigabit Ethernet applications because of tight CTC ppm requirements.

While the LFE5UM architecture will allow the mixing of a PCI Express channel and a Gigabit Ethernet, Serial RapidIO or SGMII channel within the same dual, using a PCI Express spread spectrum clocking as the transmit reference clock will cause a violation of the Gigabit Ethernet, Serial RapidIO and SGMII transmit jitter specifications.

For further information on SERDES, please see TN1261, [ECP5 SERDES/PCS Usage Guide](#).

IEEE 1149.1-Compliant Boundary Scan Testability

All ECP5 devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more information, please see TN1260, [ECP5 sysCONFIG Usage Guide](#).

Device Configuration

All ECP5 devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support dual-byte, byte and serial configuration. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In-System Configuration specification. There are 11 dedicated pins for TAP and sysConfig supports (TDI, TDO, TCK, TMS, CFG[2:0], PROGRAMN, DONE, INITN and CCLK). The remaining sysCONFIG pins are used as dual function pins. See TN1260, [ECP5 sysCONFIG Usage Guide](#) for more information about using the dual-use pins as general purpose I/Os.

There are various ways to configure a ECP5 device:

- JTAG
- Standard Serial Peripheral Interface (SPI) - interface to boot PROM Support x1, x2, x4 wide SPI memory interfaces.
- System microprocessor to drive a x8 CPU port SPCM mode
- System microprocessor to drive a serial slave SPI port (SSPI mode)
- Slave Serial model (SCM)

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

ECP5 devices also support the Slave SPI Interface. In this mode, the FPGA behaves like a SPI Flash device (slave mode) with the SPI port of the FPGA to perform read-write operations.

Enhanced Configuration Options

ECP5 devices have enhanced configuration features such as: decryption support, decompression support, TransFR™ I/O and dual-boot and multi-boot image support.

TransFR (Transparent Field Reconfiguration)

TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Dual-Boot and Multi-Boot Image Support

Dual-boot and multi-boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the ECP5 devices can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the ECP5 device can revert back to the original backup golden configuration and try again. This all can be done without power cycling the system. For more information, please see TN1260, [ECP5 sysCONFIG Usage Guide](#).

Soft Error Detect (SED) Support

ECP5 devices have dedicated logic to perform Cycle Redundancy Code (CRC) checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the ECP5 device can also be programmed to utilize a Soft Error Detect (SED) mode that checks for soft errors in configuration SRAM. The SED operation can be run in the background during user mode. If a soft error occurs, during user mode (normal operation) the device can be programmed to generate an error signal.

For further information on SED support, please see TN1268, [ECP5 Soft Error Detection \(SED\) Usage Guide](#).

On-Chip Oscillator

Every ECP5 device has an internal CMOS oscillator which is used to derive a Master Clock (MCCLK) for configuration. The oscillator and the MCCLK run continuously and are available to user logic after configuration is completed. The software default value of the MCCLK is nominally 2.5MHz. Table 2-16 lists all the available MCCLK frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a nominal Master Clock frequency of 2.4 MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the MCCLK frequency of 2.5MHz.

This internal 130 MHz +/- 15% CMOS oscillator is available to the user by routing it as an input clock to the clock tree. For further information on the use of this oscillator for configuration or user mode, please see TN1260, [ECP5 sysCONFIG Usage Guide](#).

Table 2-16. Selectable Master Clock (MCCLK) Frequencies During Configuration (Nominal)

MCCLK Frequency (MHz)
2.4
4.8
9.7
19.4
38.8
77.5
155

Density Shifting

The ECP5 family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. An example is that some user I/Os may become No Connects in smaller devices in the same package. Refer to the ECP5 Pin Migration Tables and Diamond software for specific restrictions and limitations.

Absolute Maximum Ratings^{1, 2, 3}

Supply Voltage V_{CC}	-0.5 to 1.21V
Supply Voltage V_{CCAUX}	-0.5 to 2.75V
Supply Voltage V_{CCIO}	-0.5 to 3.63V
Input or I/O Transient Voltage Applied	-0.5 to 3.63V
SERDES RX/TX Buffer Supply Voltages $V_{CCHR X}$, V_{CCHTX}	-0.5 to 1.32V
Storage Temperature (Ambient)	-65 to 150°C
Junction Temperature (TJ)	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.

Recommended Operating Conditions¹

Symbol	Parameter	Min.	Max.	Units
V_{CC}^2	Core Supply Voltage	1.045	1.155	V
$V_{CCAUX}^{2,4}$	Auxiliary Supply Voltage	2.375	2.625	V
$V_{CCIO}^{2,3}$	I/O Driver Supply Voltage	1.14	3.465	V
V_{REF}^1	Input Reference Voltage	0.5	1.0	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	°C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	°C
SERDES External Power Supply⁵				
V_{CCA}	SERDES Analog Power Supply	1.045	1.155	V
V_{CCAUXA}	SERDES Auxiliary Supply Voltage	2.374	2.625	V
$V_{CCHR X}$	SERDES Input Buffer Power Supply	0.30 ⁶	1.26	V
V_{CCHTX}	SERDES Output Buffer Power Supply (1.2V)	1.14	1.26	V

1. For correct operation, all supplies except V_{REF} must be held in their valid operation range. This is true independent of feature usage.
2. All supplies with same voltage, except V_{CCA} , should be connected together.
3. See recommended voltages by I/O standard in subsequent table.
4. V_{CCAUX} ramp rate must not exceed 30mV/μs during power-up when transitioning between 0 V and 3 V.
5. See TN1261, [ECP5 SERDES/PCS Usage Guide](#) for information on board considerations for SERDES power supplies.
6. If $V_{CCHR X}$ is used as DC bias for external AC coupling, HDin pins swing about $V_{CCHR X}$ must meet the HDin input voltage level requirement specified in the Rx section of the data sheet.

Hot Socketing Specifications^{1, 2, 3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
IDK_HS	Input or I/O Leakage Current for Top and Bottom Banks Only	$0 \leq V_{IN} \leq V_{IH} \text{ (Max.)}$	—	—	+/-1	mA
IDK	Input or I/O Leakage Current for Left and Right Banks Only	$0 \leq V_{IN} < V_{CCIO}$	—	—	+/-1	mA
		$V_{CCIO} \leq V_{IN} \leq V_{CCIO} + 0.5V$	—	18	—	mA

1. V_{CC} , V_{CCAUX} and V_{CCIO} should rise/fall monotonically.
2. I_{DK} is additive to I_{PU} , I_{PW} or I_{BH} .
3. LVCMOS and LVTTTL only.

Hot Socketing Requirements^{1, 2}

Description	Min.	Typ.	Max.	Units
Input current per SERDES I/O pin when device is powered down and inputs driven.	—	—	8	mA
Input current per HDIN pin when device power supply is off, inputs driven ^{1, 2}	-	-	15	mA
Current per HDIN pin when device power ramps up, input driven ³	-	-	50	mA
Current per HDOUT pin when device power supply is off, outputs pulled up ⁴	-	-	30	mA

1. Device is powered down with all supplies grounded, both HDINP and HDINN inputs driven by a CML driver with maximum allowed output ($V_{CCTx} = 1.26V$), 8b/10b data, no external AC coupling.
2. Each P and N input must have less than the specified maximum input current during hot plug. For a device with 2 DCU, the total input current would be $15mA * 4 \text{ channels} * 2 \text{ input pins per channel} = 120 \text{ mA}$.
3. Device power supplies are ramping up (V_{CCA} and V_{CCAUX}), both HDINP and HDINN inputs are driven by a CML driver with maximum allowed output ($V_{CCHTX}=1.26V$), 8b/10b data, internal AC coupling.
4. Device is powered down with all supplies grounded. Both HDOUTP and HDOUN outputs are pulled up to 1.26 V by the far end receiver termination of 50 Ω single ended.

ESD Performance

Please refer to the [ECP5 Product Family Qualification Summary](#) for complete qualification data, including ESD performance.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	100	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{CCIO}$	30	—	150	μA
C1	I/O Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
C2	Dedicated Input Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	7	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, $f = 1.0MHz$.
3. Applicable to general purpose I/Os in top and bottom banks.
4. When used as V_{REF} maximum leakage= 25 μA .

ECP5 Supply Current (Standby)^{1, 2, 3, 4, 5, 6}
Over Recommended Operating Conditions

Symbol	Parameter	Device	Typical	Units
I _{CC}	Core Power Supply Current	LFE5-25	17.07	mA
		LFE5-45	25.59	mA
		LFE5-85	42.26	mA
I _{CCAUX}	Auxiliary Power Supply Current	LFE5-25	12.7	mA
		LFE5-45	17.72	mA
		LFE5-85	23.71	mA
I _{CCIO}	Bank Power Supply Current (Per Bank)	LFE5-25	0.48	mA
		LFE5-45	0.48	mA
		LFE5-85	0.48	mA
I _{CCA}	SERDES Power Supply Current (Per Dual)	LFE5-25	3.62	mA
		LFE5-45	3.62	mA
		LFE5-85	3.62	mA

1. For further information on supply current, please see the list of technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0 Hz.
4. Pattern represents a “blank” configuration data file.
5. T_J = 85°C, power supplies at nominal voltage.
6. To determine the ECP5 peak start-up current, please use the Power Calculator tool in the Lattice Diamond Design Software.

SERDES Power Supply Requirements^{1, 2, 3}

Over Recommended Operating Conditions

Symbol	Description	Typ.	Max.	Units
Standby (Power Down)				
I _{CCA-SB}	V _{CCA} Power Supply Current (Per Channel)			mA
I _{CCHRX-SB}	V _{CCHRX} , Input Buffer Current (Per Channel)			mA
I _{CCHTX-SB}	V _{CCHTX} , Output Buffer Current (Per Channel)			mA
Operating (Data Rate = 3.2 Gbps)				
I _{CCA-OP}	V _{CCA} Power Supply Current (Per Channel)	63.47	-	mA
I _{CCHRX-OP}	V _{CCHRX} , Input Buffer Current (Per Channel)	0.4	-	mA
I _{CCHTX-OP}	V _{CCHTX} , Output Buffer Current (Per Channel)	17.75	-	mA
Operating (Data Rate = 2.5 Gbps)				
I _{CCA-OP}	V _{CCA} Power Supply Current (Per Channel)	53.71	-	mA
I _{CCHRX-OP}	V _{CCHRX} , Input Buffer Current (Per Channel)	0.45	-	mA
I _{CCHTX-OP}	V _{CCHTX} , Output Buffer Current (Per Channel)	15.715	-	mA
Operating (Data Rate = 1.25 Gbps)				
I _{CCA-OP}	V _{CCA} Power Supply Current (Per Channel)	34.185	-	mA
I _{CCHRX-OP}	V _{CCHRX} , Input Buffer Current (Per Channel)	0.4	-	mA
I _{CCHTX-OP}	V _{CCHTX} , Output Buffer Current (Per Channel)	11.595	-	mA
Operating (Data Rate = 270 Mbps)				
I _{CCA-OP}	V _{CCA} Power Supply Current (Per Channel)	18.875	-	mA
I _{CCHRX-OP}	V _{CCHRX} , Input Buffer Current (Per Channel)	0.4	-	mA
I _{CCHTX-OP}	V _{CCHTX} , Output Buffer Current (Per Channel)	8.36	-	mA

1. Rx Equalization enabled, Tx De-emphasis (pre-cursor and post-cursor) disabled

2. Per Channel current is calculated with both channels on in a Dual, and divide current by two. If only one channel is on current will be higher.

3. To calculate with Tx De-emphasis enabled, please refer to the Diamond Power Calculator tool.

sysI/O Recommended Operating Conditions

Standard	V _{CCIO}			V _{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVC MOS33 ²	3.135	3.3	3.465	—	—	—
LVC MOS33D ⁴ Output	3.135	3.3	3.465	—	—	—
LVC MOS25 ²	2.375	2.5	2.625	—	—	—
LVC MOS18	1.71	1.8	1.89	—	—	—
LVC MOS15	1.425	1.5	1.575	—	—	—
LVC MOS12 ²	1.14	1.2	1.26	—	—	—
LV TTL33 ²	3.135	3.3	3.465	—	—	—
SSTL15_I, II ³	1.43	1.5	1.57	0.68	0.75	0.9
SSTL18_I, II ²	1.71	1.8	1.89	0.833	0.9	0.969
SSTL135_1, II	1.28	1.35	1.42	0.6	0.675	0.75
HSUL12	1.14	1.2	1.26	0.588	0.6	0.612
MIPI D-PHY LP Input ⁴	1.425	1.5	1.575	—	—	—
LVDS25 ^{2,4} Output	2.375	2.5	2.625	—	—	—
subLV ⁴ (Input only)	—	—	—	—	—	—
SLV ⁴ (Input only)	—	—	—	—	—	—
LVDS25E ⁴ Output	2.375	2.5	2.625	—	—	—
MLVDS ^{1,4} Output	2.375	2.5	2.625	—	—	—
LVPECL33 ^{1,2,4} Output	3.135	3.3	3.465	—	—	—
BLVDS25 ^{1,2,4} Output	2.375	2.5	2.625	—	—	—
HSULD12D ^{3,4}	1.43	1.5	1.57	—	—	—
SSTL135D_I, II ^{3,4}	1.28	1.35	1.42	—	—	—
SSTL15D_I, II ^{3,M4}	1.43	1.5	1.57	—	—	—
SSTL18D_I ^{2,3,4} , II ^{2,3,4}	1.71	1.8	1.89	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. For input voltage compatibility, see TN1262, [ECP5 sysIO Usage Guide](#).
3. VREF is required when using Differential SSTL and HSUL to interface to DDR/LPDDR memories.
4. These differential inputs use LVDS input comparator, which uses VCCAUX power
5. All differential inputs and LVDS25 output are supported in the Left and Right banks only. Please refer to TN1262, [ECP5 sysIO Usage Guide](#) for details.

sysI/O Single-Ended DC Electrical Characteristics^{1, 2}

Input/Output Standard	V _{IL}		V _{IH}		V _{OL} Max. (V)	V _{OH} Min. (V)	I _{OL} ¹ (mA)	I _{OH} ¹ (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS33	-0.3	0.8	2.0	3.465	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS25	-0.3	0.7	1.7	3.465	0.4	V _{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS18	-0.3	0.35 V _{CCIO}	0.65 V _{CCIO}	3.465	0.4	V _{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS15	-0.3	0.35 V _{CCIO}	0.65 V _{CCIO}	3.465	0.4	V _{CCIO} - 0.4	8, 4	-8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVCMOS12	-0.3	0.35 V _{CCIO}	0.65 V _{CCIO}	3.465	0.4	V _{CCIO} - 0.4	8, 4	-8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVTTTL33	-0.3	0.8	2.0	3.465	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-16, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
SSTL18_I (DDR2 Memory)	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	3.465	0.4	V _{CCIO} - 0.4	6.7	-6.7
SSTL18_II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	3.465	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL15_I (DDR3 Memory)	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.465	0.3	V _{CCIO} - 0.31	7.5	-7.5
SSTL15_II (DDR3L Memory)	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.465	0.3	V _{CCIO} - 0.31	8.8	-8.8
SSTL135_I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	3.465	0.4	V _{CCIO} - 0.27	7	-7
SSTL15_II	-0.3	V _{REF} - 0.09	V _{REF} + 0.09	3.465	0.4	V _{CCIO} - 0.27	8	-8
MIPI D-PHY (LP)	-0.3	V _{REF} - 0.55	V _{REF} + 0.98	3.465	—	—	—	—
HSUL12 (LPDDR2/3 Memory)	-0.3	V _{REF} - 0.2	V _{REF} + 0.2	3.465	0.4	V _{CCIO} - 0.3	18, 4	-8, -4

1. For electromigration, the average DC current drawn by the I/O pads within a bank of I/Os shall not exceed 10mA per I/O (All I/Os used in the same V_{CCIO}).
2. Not all IO types are supported in all banks. Please refer to TN1262, [ECP5 sysIO Usage Guide](#) for details.

sysI/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}^1, V_{INM}^1	Input Voltage		0	—	2.4	V
V_{CM}^1	Input Common Mode Voltage	Half the Sum of the Two Inputs	0.05	—	2.35	V
V_{THD}	Differential Input Threshold	Difference Between the Two Inputs	+/-100	—	—	mV
I_{IN}	Input Current	Power On or Power Off	—	—	+/-10	μ A
V_{OH}	Output High Voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	—	1.38	1.60	V
V_{OL}	Output Low Voltage for V_{OP} or V_{OM}	$R_T = 100$ Ohm	0.9V	1.03	—	V
V_{OD}	Output Voltage Differential	$(V_{OP} - V_{OM}), R_T = 100$ Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} Between High and Low		—	—	50	mV
V_{OS}	Output Voltage Offset	$(V_{OP} + V_{OM})/2, R_T = 100$ Ohm	1.125	1.20	1.375	V
ΔV_{OS}	Change in V_{OS} Between H and L		—	—	50	mV
I_{SAB}	Output Short Circuit Current	$V_{OD} = 0V$ Driver Outputs Shorted to Each Other	—	—	12	mA

¹, On the left and right sides of the device, this specification is valid only for $V_{CCIO} = 2.5$ V or 3.3 V.

SSTLD

All differential SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVC MOS33D

All I/O banks support emulated differential I/O using the LVC MOS33D I/O type. This option, along with the external resistor network, provides the system designer the flexibility to place differential outputs on an I/O bank with 3.3 V V_{CCIO} . The default drive current for LVC MOS33D output is 12mA with the option to change the device strength to 4mA, 8mA, 12mA or 16mA. Follow the LVC MOS33 specifications for the DC characteristics of the LVC MOS33D.

LVDS25E

The top and bottom sides of ECP5 devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

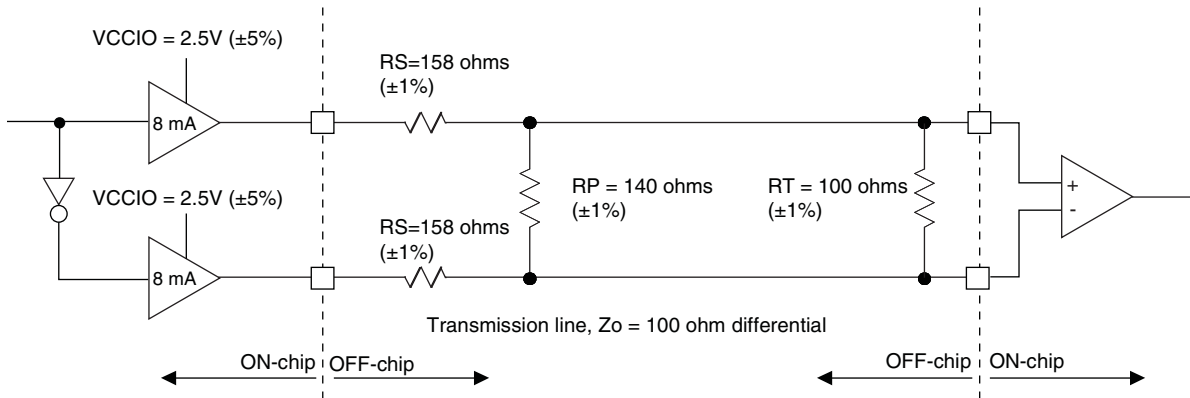


Table 3-1. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V _{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z _{OUT}	Driver Impedance	20	Ω
R _S	Driver Series Resistor (+/-1%)	158	Ω
R _P	Driver Parallel Resistor (+/-1%)	140	Ω
R _T	Receiver Termination (+/-1%)	100	Ω
V _{OH}	Output High Voltage	1.43	V
V _{OL}	Output Low Voltage	1.07	V
V _{OD}	Output Differential Voltage	0.35	V
V _{CM}	Output Common Mode Voltage	1.25	V
Z _{BACK}	Back Impedance	100.5	Ω
I _{DC}	DC Output Current	6.03	mA

BLVDS25

The ECP5 devices support the BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS25 Multi-point Output Example

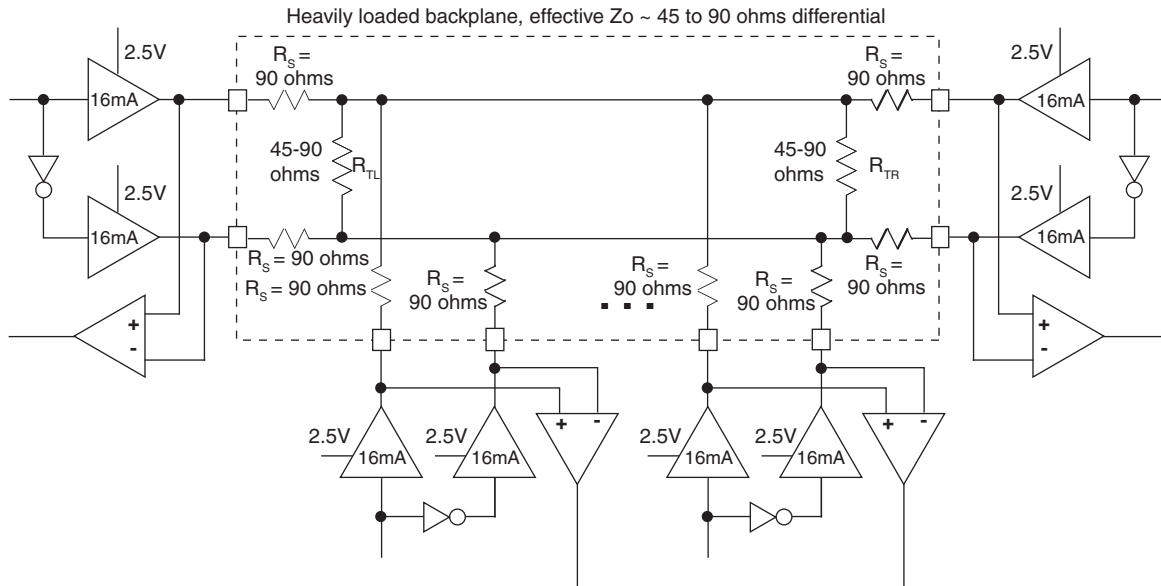


Table 3-2. BLVDS25 DC Conditions¹

Over Recommended Operating Conditions

Parameter	Description	Typical		Units
		Zo = 45Ω	Zo = 90Ω	
V _{CCIO}	Output Driver Supply (+/- 5%)	2.50	2.50	V
Z _{OUT}	Driver Impedance	10.00	10.00	Ω
R _S	Driver Series Resistor (+/- 1%)	90.00	90.00	Ω
R _{TL}	Driver Parallel Resistor (+/- 1%)	45.00	90.00	Ω
R _{TR}	Receiver Termination (+/- 1%)	45.00	90.00	Ω
V _{OH}	Output High Voltage	1.38	1.48	V
V _{OL}	Output Low Voltage	1.12	1.02	V
V _{OD}	Output Differential Voltage	0.25	0.46	V
V _{CM}	Output Common Mode Voltage	1.25	1.25	V
I _{DC}	DC Output Current	11.24	10.20	mA

1. For input buffer, see LVDS table.

LVPECL33

The ECP5 devices support the differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL33

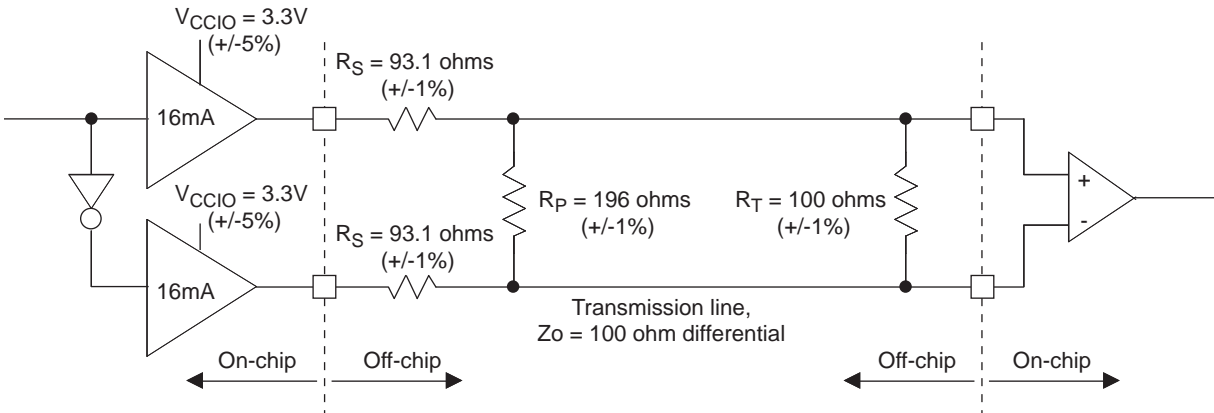


Table 3-3. LVPECL33 DC Conditions¹

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply ($\pm 5\%$)	3.30	V
Z_{OUT}	Driver Impedance	10	Ω
R_S	Driver Series Resistor ($\pm 1\%$)	93	Ω
R_P	Driver Parallel Resistor ($\pm 1\%$)	196	Ω
R_T	Receiver Termination ($\pm 1\%$)	100	Ω
V_{OH}	Output High Voltage	2.05	V
V_{OL}	Output Low Voltage	1.25	V
V_{OD}	Output Differential Voltage	0.80	V
V_{CM}	Output Common Mode Voltage	1.65	V
Z_{BACK}	Back Impedance	100.5	Ω
I_{DC}	DC Output Current	12.11	mA

1. For input buffer, see LVDS table.

MLVDS25

The ECP5 devices support the differential MLVDS standard. This standard is emulated using complementary LVC-MOS outputs in conjunction with a parallel resistor across the driver outputs. The MLVDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for MLVDS standard implementation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. MLVDS25 (Multipoint Low Voltage Differential Signaling)

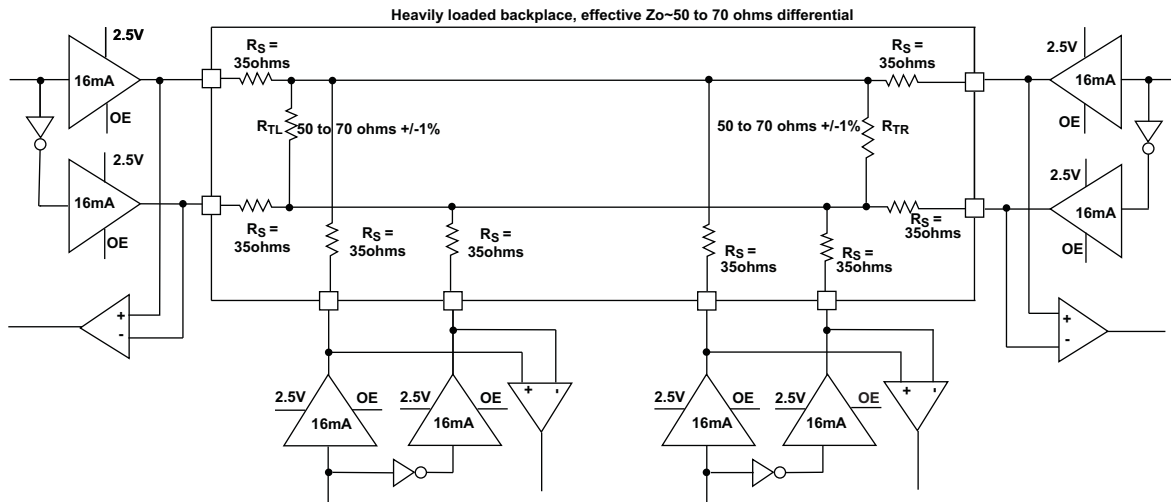


Table 3-4. MLVDS25 DC Conditions¹

Parameter	Description	Typical		Units
		Zo=50Ω	Zo=70Ω	
V _{CCIO}	Output Driver Supply (+/-5%)	2.50	2.50	V
Z _{OUT}	Driver Impedance	10.00	10.00	Ω
R _S	Driver Series Resistor (+/-1%)	35.00	35.00	Ω
R _{TL}	Driver Parallel Resistor (+/-1%)	50.00	70.00	Ω
R _{TR}	Receiver Termination (+/-1%)	50.00	70.00	Ω
V _{OH}	Output High Voltage	1.52	1.60	V
V _{OL}	Output Low Voltage	0.98	0.90	V
V _{OD}	Output Differential Voltage	0.54	0.70	V
V _{CM}	Output Common Mode Voltage	1.25	1.25	V
I _{DC}	DC Output Current	21.74	20.00	mA

1. For input buffer, see LVDS table.

SLVS

Scalable Low-Voltage Signaling (SLVS) is based on a point-to-point signaling method defined in the JEDEC JESD8-13 (SLVS-400) standard. This standard evolved from the traditional LVDS standard and relies on the advantage of its use of smaller voltage swings and a lower common-mode voltage. The 200 mV (400 mV p-p) SLVS swing contributes to a reduction in power.

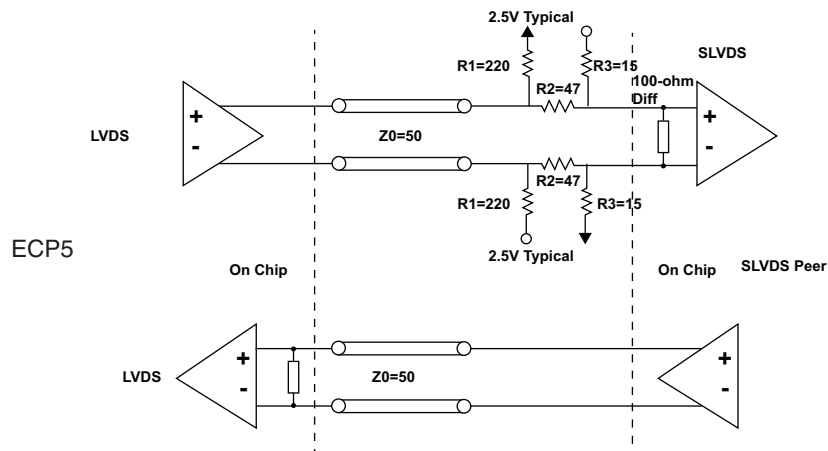
The ECP5 devices can receive differential input up to 800 Mbps with its LVDS input buffer. This LVDS input buffer is used to meet the SLVS input standard specified by the JEDEC standard. The SLVS output parameters are compared to ECP5 LVDS input parameters, as listed in Table 3-5:

Table 3-5. Input to SLVS

Parameter	ECP5 LVDS Input	SLVS Output	Units
Vcm (min)	50	150	mV
Vcm (max)	2350	250	mV
Differential Voltage (min)	100	140	mV
Differential Voltage (max)	-	270	mV

ECP5 does not support SLVS output. However, SLVS output can be created using ECP5 LVDS outputs by level shift to meet the low Vcm/Vod levels required by SLVS. Figure 3-5 shows how the LVDS output can be shifted external to meet SLVS levels.

Figure 3-5. SLVS Interface



ECP5 External Switching Characteristics ^{1, 2}

Over Recommended Commercial Operating Conditions

Parameter	Description	Device	-8		-7		-6		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Clocks									
Primary Clock⁶									
f _{MAX_PRI}	Frequency for Primary Clock Tree		-	370	-	303	-	257	MHz
t _{W_PRI}	Clock Pulse Width for Primary Clock		0.8	-	0.8	-	0.8	-	ns
t _{ISKEW_PRI}	Primary Clock Skew Within a Device		-	420	-	462	-	505	ps
Edge Clock⁶									
f _{MAX_EDGE}	Frequency for Edge Clock Tree		-	400	-	327.9	-	277.8	MHz
t _{W_EDGE}	Clock Pulse Width for Edge Clock		1.175	-	1.434	-	1.76	-	ns
t _{ISKEW_EDGE}	Edge Clock Skew Within a Bank		-	160	-	180	-	200	ps
Generic SDR Input									
General I/O Pin Parameters Using Dedicated Clock Input Primary Clock Without PLL²									
t _{CO}	Clock to Output - PIO Output Register	LFE5-85	-	5.4	-	6.1	-	6.8	ns
t _{SU}	Clock to Data Setup - PIO Input Register	LFE5-85	0	-	0	-	0	-	ns
t _H	Clock to Data Hold - PIO Input Register	LFE5-85	2.7	-	3	-	3.3	-	ns
t _{SU_DEL}	Clock to Data Setup - PIO Input Register with Data Input Delay	LFE5-85	1.2	-	1.33	-	1.46	-	ns
t _{H_DEL}	Clock to Data Hold - PIO Input Register with Data Input Delay	LFE5-85	0	-	0	-	0	-	ns
f _{MAX_IO}	Clock Frequency of I/O and PFU Register	LFE5-85	-	400	-	327.9	-	277.8	MHz
t _{CO}	Clock to Output - PIO Output Register	Other Devices	-	-	-	-	-	-	ns
t _{SU}	Clock to Data Setup - PIO Input Register	Other Devices	-	-	-	-	-	-	ns
t _H	Clock to Data Hold - PIO Input Register	Other Devices	-	-	-	-	-	-	ns
t _{SU_DEL}	Clock to Data Setup - PIO Input Register with Data Input Delay	Other Devices	-	-	-	-	-	-	ns
t _{H_DEL}	Clock to Data Hold - PIO Input Register with Data Input Delay	Other Devices	-	-	-	-	-	-	ns
f _{MAX_IO}	Clock Frequency of I/O and PFU Register	Other Devices	-	-	-	-	-	-	MHz
General I/O Pin Parameters Using Dedicated Clock Input Primary Clock With PLL with Clock Injection Removal Setting²									
t _{COPLL}	Clock to Output - PIO Output Register	LFE5-85	-	3.1	-	3.44	-	3.78	ns
t _{SUPLL}	Clock to Data Setup - PIO Input Register	LFE5-85	0.7	-	0.78	-	0.85	-	ns
t _{HPLL}	Clock to Data Hold - PIO Input Register	LFE5-85	0.8	-	0.89	-	0.98	-	ns
t _{SU_DELP}	Clock to Data Setup - PIO Input Register with Data Input Delay	LFE5-85	1.6	-	1.78	-	1.95	-	ns
t _{H_DELP}	Clock to Data Hold - PIO Input Register with Data Input Delay	LFE5-85	0	-	0	-	0	-	ns
t _{COPLL}	Clock to Output - PIO Output Register	Other Devices	-	-	-	-	-	-	ns
t _{SUPLL}	Clock to Data Setup - PIO Input Register	Other Devices	-	-	-	-	-	-	ns
t _{HPLL}	Clock to Data Hold - PIO Input Register	Other Devices	-	-	-	-	-	-	ns
t _{SU_DELP}	Clock to Data Setup - PIO Input Register with Data Input Delay	Other Devices	-	-	-	-	-	-	ns
t _{H_DELP}	Clock to Data Hold - PIO Input Register with Data Input Delay	Other Devices	-	-	-	-	-	-	ns

ECP5 External Switching Characteristics (Continued)^{1, 2}

Over Recommended Commercial Operating Conditions

Parameter	Description	Device	-8		-7		-6		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDR¹² Input									
Generic DDRX1 Inputs with Clock and Data Centered at Pin (GDDR1_RX.SCLK.Centered) Using PCLK Pin for Clock Input									
t _{SU_GDDR1}	Data Setup Before CLK	All Devices	0.52	-	0.52	-	0.52	-	ns
t _{HO_GDDR1}	Data Hold After CLK	All Devices	0.52	-	0.52	-	0.52	-	ns
f _{MAX_GDDR1}	DDR1 Clock Frequency	All Devices	-	250	-	250	-	250	MHz
Generic DDRX1 Inputs with Clock and Data Aligned at Pin (GDDR1_RX.SCLK.Aligned) Using PCLK Pin for Clock Input									
t _{DVA_GDDR1}	Input Data Valid After CLK	All Devices	-	-0.55	-	-0.55	-	-0.55	ns + 1/2 UI
t _{DVE_GDDR1}	Input Data Hold After CLK	All Devices	0.55	-	0.55	-	0.55	-	ns + 1/2 UI
t _{DW_GDDR1}	Input Data Setup-Hold Window	All Devices	1.1	-	1.1	-	1.1	-	ns
f _{MAX_GDDR1}	DDR1 Clock Frequency	All Devices	-	250	-	250	-	250	MHz
Generic DDRX2 Inputs with Clock and Data Centered at Pin (GDDR2_RX.ECLK.Centered, GDDR2_RX.MIPI) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{SU_GDDR2}	Data Setup Before CLK	All Devices	0.321	-	0.403	-	0.471	-	ns
t _{HO_GDDR2}	Data Hold After CLK	All Devices	0.321	-	0.403	-	0.471	-	ns
f _{MAX_GDDR2}	DDR2 Clock Frequency (ECLK)	All Devices	-	400	-	327.9	-	277.8	MHz
Generic DDRX2 Inputs with Clock and Data Aligned at Pin (GDDR2_RX.ECLK.Aligned) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{DVA_GDDR2}	Input Data Valid After CLK	All Devices	-	-0.344	-	-0.42	-	-0.495	ns + 1/2 UI
t _{DVE_GDDR2}	Input Data Hold After CLK	All Devices	0.344	-	0.42	-	0.495	-	ns + 1/2 UI
t _{DW_GDDR2}	Input Data Setup-Hold Window	All Devices	0.688	-	0.839	-	0.99	-	ns
f _{MAX_GDDR2}	DDR2 Clock Frequency (ECLK)	All Devices	-	400	-	327.9	-	277.8	MHz
Video DDRX71 Inputs with Clock and Data Aligned at Pin (GDDR71_RX.ECLK) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{RPBI_DVA}	Input Valid Bit i switching from CLK Rising Edge (i = 0 to 6, 0 aligns with CLK)	All Devices	-0.271	-	-0.39	-	-0.41	-	ns + (i + 1/2) * UI
t _{RPBI_DVE}	Input Hold Bit i switching from CLK Rising Edge (i = 0 to 6, 0 aligns with CLK)	All Devices	-	0.271	-	0.39	-	0.41	ns + (i + 1/2) * UI
f _{MAX_GDDR71}	DDR71 Clock Frequency (ECLK)	All Devices	-	378	-	310	-	262.5	MHz
Generic DDR¹² Output									
Generic DDRX1 Outputs with Clock and Data (>10 Bits Wide) Centered at Pin (GDDR1_TX.SCLK.Centered) Using PCLK Pin for Clock Input									
t _{DVB_GDDR1}	Data Output Valid Before CLK Output	All Devices	0.67	-	0.67	-	0.67	-	ns
t _{DVA_GDDR1}	Data Output Valid After CLK Output	All Devices	0.67	-	0.67	-	0.67	-	ns
f _{MAX_GDDR1}	DDR1 Clock Frequency	All Devices	-	250	-	250	-	250	MHz
Generic DDRX1 Outputs with Clock and Data Aligned at Pin (GDDR1_TX.SCLK.Aligned) Using PCLK Pin for Clock Input									
t _{DIA_GDDR1}	Data Output Invalid After CLK Output	All Devices	-	0.3	-	0.3	-	0.3	ns
t _{DIB_GDDR1}	Data Output Invalid Before CLK Output	All Devices	-	0.3	-	0.3	-	0.3	ns
f _{MAX_GDDR1}	DDR1 Clock Frequency	All Devices	-	250	-	250	-	250	MHz
Generic DDRX2 Outputs with Clock and Data Centered at Pin (GDDR2_TX.ECLK.Centered) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{DVB_GDDR2}	Data Output Valid Before CLK Output	All Devices	0.442	-	0.56	-	0.676	-	ns
t _{DVA_GDDR2}	Data Output Valid After CLK Output	All Devices	0.442	-	0.56	-	0.676	-	ns
f _{MAX_GDDR2}	DDR2 Clock Frequency (ECLK)	All Devices	-	400	-	327.9	-	277.8	MHz

ECP5 External Switching Characteristics (Continued)^{1, 2}

Over Recommended Commercial Operating Conditions

Parameter	Description	Device	-8		-7		-6		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Generic DDRX2 Outputs with Clock and Data Aligned at Pin (GDDR2_TX.ECLK.Aligned) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{DIA_GDDR2}	Data Output Invalid After CLK Output	All Devices	-	0.16	-	0.18	-	0.2	ns
t _{DIB_GDDR2}	Data Output Invalid Before CLK Output	All Devices	-	0.16	-	0.18	-	-	ns
f _{MAX_GDDR2}	DDR2 Clock Frequency (ECLK)	All Devices	-	400	-	327.9	-	277.8	MHz
Video DDRX71 Outputs with Clock and Data Aligned at Pin (GDDR71_TX.ECLK) Using PCLK Pin for Clock Input, Using Left and Right Sides Only									
t _{TPBI_D0V}	Data Output Valid for Bit i from CLK Rising Edge (i = 0 to 6, 0 aligns with CLK)	All Devices	-	0.16	-	0.18	-	0.2	ns + i * UI
t _{TPBI_D0I}	Data Output Invalid for Bit i from CLK Rising Edge (i = 0 to 6, 0 aligns with CLK)	All Devices	-0.16	-	-0.18	-	-0.2	-	ns + (i + 1) * UI
f _{MAX_GDDR71}	DDR71 Clock Frequency (ECLK)	All Devices	-	378	-	310	-	262.5	MHz
Memory Interface									
DDR2/DDR3/LPDDR2/LPDDR3 READ (Input Data are Strobed Aligned by DQS)									
t _{DVADQ}	DQ Input Valid After DQS Input	All Devices	-	-0.26	-	-0.317	-	-0.374	ns + 1/2 UI
t _{DVBDQ}	DQ Input Valid Before DQS Input	All Devices	0.26	-	0.317	-	0.374	-	ns + 1/2 UI
t _{DWDQ}	DQ Input Valid Window	All Devices	0.519	-	0.633	-	0.747	-	MHz
DDR2/DDR3/LPDDR2/LPDDR3 WRITE (DQS Output is Centered Aligned to DQ Data Outputs)									
t _{DQVBS}	DQ Output Valid Before DQS	All Devices	0.25	-	0.25	-	0.25	-	UI
t _{DQVAS}	DQ Output Valid After DQS	All Devices	0.25	-	0.25	-	0.25	-	UI
f _{MAX_DDR2}	DDR2 Memory Max ECLK Frequency	All Devices	-	400	-	327.9	-	277.8	MHz
f _{MAX_DDR3}	DDR3 Memory Max ECLK Frequency	All Devices	-	400	-	327.9	-	277.8	MHz
f _{MAX_LPDDR2}	LPDDR2 Memory Max ECLK Frequency	All Devices	-	400	-	327.9	-	277.8	MHz
f _{MAX_LPDDR3}	LPDDR3 Memory Max ECLK Frequency	All Devices	-	400	-	327.9	-	277.8	MHz

- Commercial timing numbers are shown. Industrial numbers are typically slower and can be extracted from the Diamond software.
- General I/O timing numbers based on LVCMOS 2.5, 12mA, Fast Slew Rate, 0pf load.
- Generic DDR timing numbers based on LVDS I/O.
- DDR timing numbers based on SSTL25. DDR2 timing numbers based on SSTL18.
- DDR3 timing numbers based on SSTL15.
- Uses LVDS I/O standard.
- The current version of software does not support per bank skew numbers; this will be supported in a future release.
- Maximum clock frequencies are tested under best case conditions. System performance may vary upon the user environment.
- Using settings generated by IPexpress.
- These numbers are generated using best case PLL located in the center of the device.
- Uses SSTL25 Class II Differential I/O Standard.
- All numbers are generated with the Diamond software.

Figure 3-6. Generic DDRX1/DDR2 (With Clock and Data Edges Aligned)

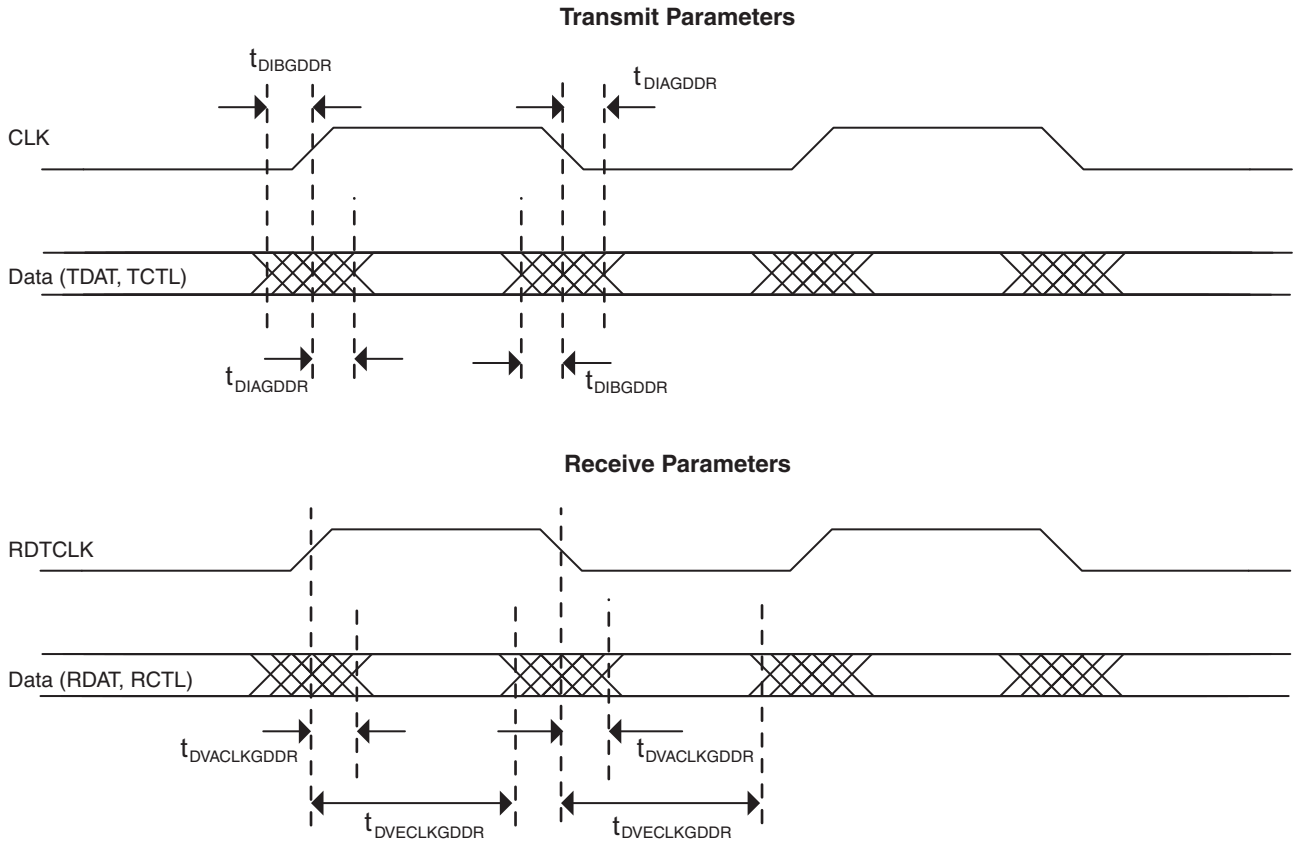


Figure 3-7. DDR/DDR2/DDR3 Parameters

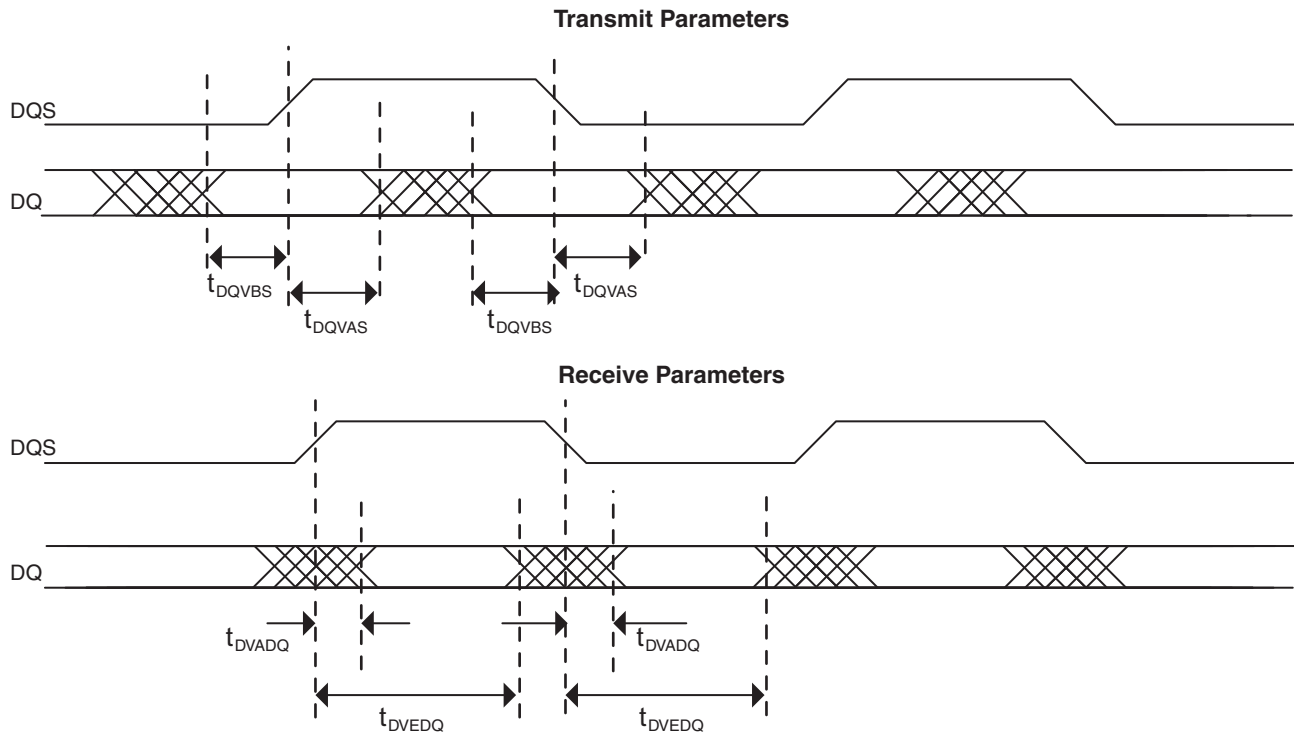
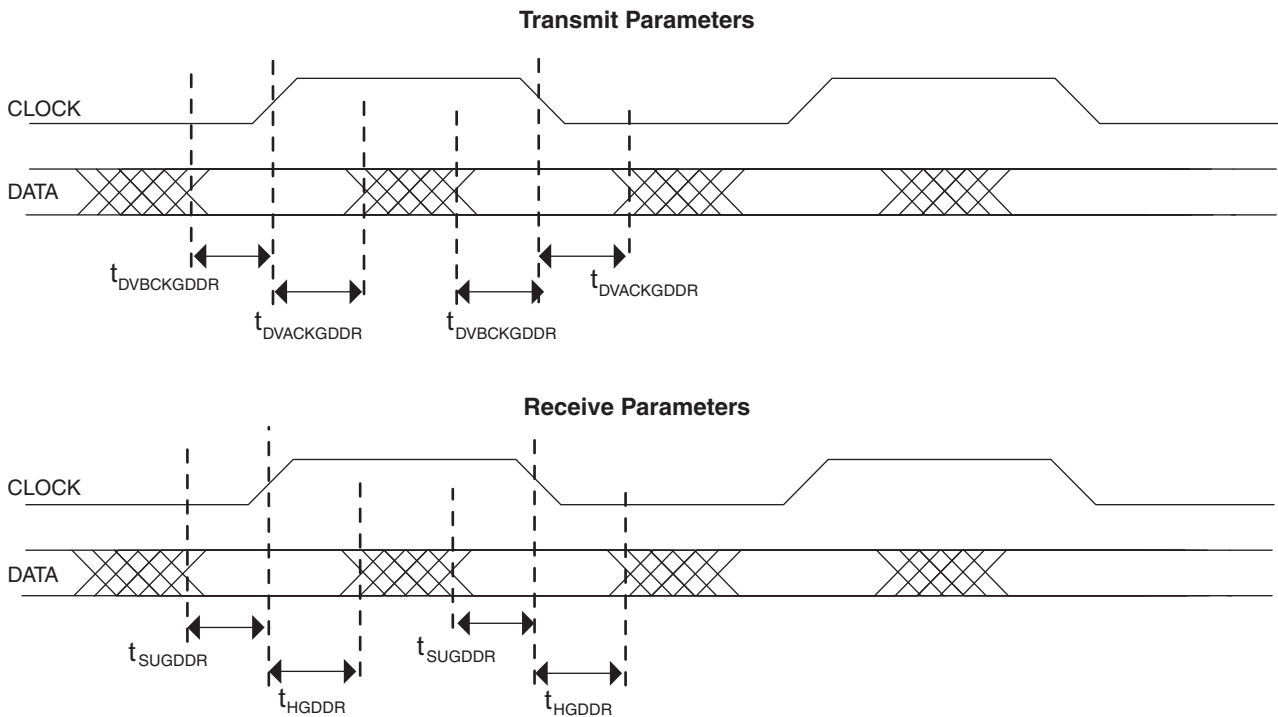
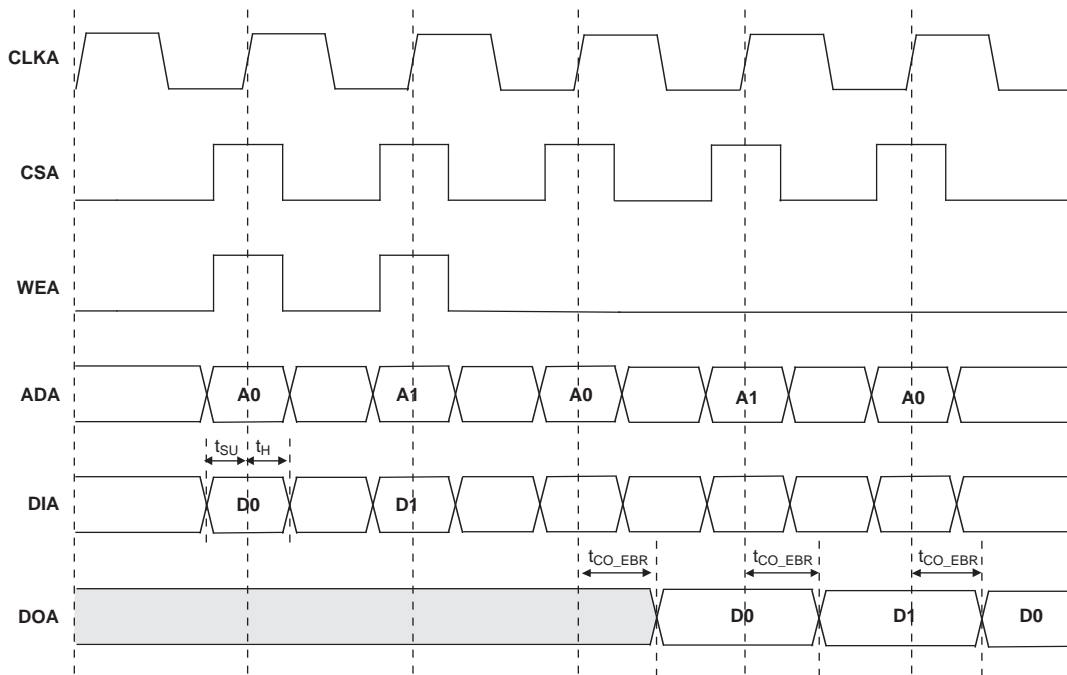


Figure 3-8. Generic DDRX1/DDR2 (With Clock Center on Data Window)



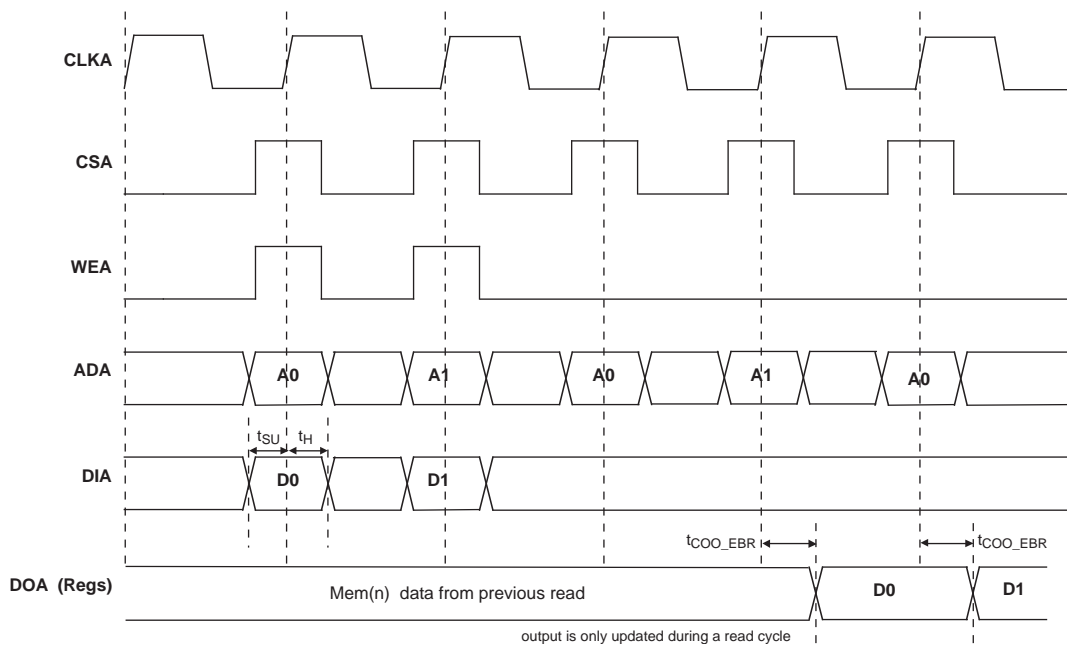
Timing Diagrams

Figure 3-9. Read/Write Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Figure 3-10. Read/Write Mode with Input and Output Registers



ECP5 Family Timing Adders^{1, 2, 3, 4, 5}

Over Recommended Commercial Operating Conditions

Buffer Type	Description	-8	-7	-6	Units
Input Adjusters					
LVDS25E	LVDS, Emulated, VCCIO = 2.5V	0.03	-0.01	-0.03	ns
LVDS25	LVDS, VCCIO = 2.5V	0.03	0.00	-0.04	ns
BLVDS25	BLVDS, Emulated, VCCIO = 2.5V	0.03	0.00	-0.04	ns
MLVDS25	MLVDS, Emulated, VCCIO = 2.5V	0.03	0.00	-0.04	ns
LVPECL33	LVPECL	0.17	0.23	0.28	ns
MIPI D-PHY	MIPI Video				ns
SLVS	SLVS, similar to MIPI				ns
SSTL18_I	SSTL_18 class I, VCCIO = 1.8V	0.08	0.06	0.04	ns
SSTL18_II	SSTL_18 class II, VCCIO = 1.8V	0.08	0.06	0.04	ns
SSTL18D_I	Differential SSTL_18 class I	0.08	0.06	0.04	ns
SSTL18D_II	Differential SSTL_18 class II	0.08	0.06	0.04	ns
SSTL15_I	SSTL_15, VCCIO = 1.5 V class I	0.09	0.06	0.03	ns
SSTL15_II	SSTL_15, VCCIO = 1.5 V class II	0.09	0.06	0.03	ns
SSTL15D_I	Differential SSTL_15 class I	0.09	0.06	0.03	ns
SSTL15D_II	Differential SSTL_15 class II	0.09	0.06	0.03	ns
SSTL135_I	SSTL_135, VCCIO = 1.35 V class I				ns
SSTL135_II	SSTL_135, VCCIO = 1.35 V class II				ns
SSTL135D_I	Differential SSTL_135 class I				ns
SSTL135D_II	Differential SSTL_135 class II				ns
HSUL12	HSUL, VCCIO=1.2 V				ns
LVTTTL33	LVTTTL, VCCIO = 3.3 V	0.07	0.07	0.07	ns
LVTTTL33D	LVTTTL, VCCIO = 3.3 V	0.07	0.07	0.07	ns
LVC MOS33	LVC MOS, VCCIO = 3.3 V	0.07	0.07	0.07	ns
LVC MOS33D	LVC MOS, VCCIO = 3.3 V	0.07	0.07	0.07	ns
LVC MOS25	LVC MOS, VCCIO = 2.5 V	0.00	0.00	0.00	ns
LVC MOS25D	LVC MOS, VCCIO = 2.5 V	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS, VCCIO = 1.8 V	-0.13	-0.13	-0.13	ns
LVC MOS15	LVC MOS, VCCIO = 1.5 V	-0.07	-0.07	-0.07	ns
LVC MOS12	LVC MOS, VCCIO = 1.2 V	-0.20	-0.19	-0.19	ns
Output Adjusters					
LVDS25E	LVDS, Emulated, VCCIO = 2.5 V	1.02	1.14	1.26	ns
LVDS25	LVDS, VCCIO = 2.5 V	-0.11	-0.07	-0.03	ns
BLVDS25	BLVDS, Emulated, VCCIO = 2.5 V	1.01	1.13	1.25	ns
MLVDS25	MLVDS, Emulated, VCCIO = 2.5 V	1.01	1.13	1.25	ns
LVPECL33	LVPECL, Emulated, VCCIO = 3.3 V	0.67	0.76	0.86	ns
HSUL12_4mA	HSUL, VCCIO=1.2, 4 mA Drive				ns
HSUL12_8mA	HSUL, VCCIO=1.2, 8 mA Drive				ns
SSTL18_I	SSTL_1.8 class I, VCCIO = 1.8 V	0.70	0.84	0.97	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.70	0.84	0.97	ns
SSTL15_I	SSTL_1.5, VCCIO = 1.5 V	1.22	1.35	1.48	ns
SSTL15_II	SSTL_1.5, VCCIO = 1.5 V	1.22	1.35	1.48	ns

ECP5 Family Timing Adders^{1, 2, 3, 4, 5} (Continued)

Over Recommended Commercial Operating Conditions

Buffer Type	Description	-8	-7	-6	Units
SSTL15D_I	Differential SSTL_15	1.22	1.35	1.48	ns
SSTL15D_II	Differential SSTL_15	1.22	1.35	1.48	ns
SSTL135_I	SSTL_135, VCCIO=1.35V				ns
SSTL135D_I	Differential SSTL_135, VCCIO=1.35V				ns
SSTL135D_II	Differential SSTL_135, VCCIO=1.35V				ns
LVTTTL33_4mA	LVTTTL 4mA drive, VCCIO = 3.3V	0.04	0.02	0.01	ns
LVTTTL33_8mA	LVTTTL 8mA drive, VCCIO = 3.3V	-0.02	-0.03	-0.05	ns
LVTTTL33_12mA	LVTTTL 12mA drive, VCCIO = 3.3V	-0.08	-0.08	-0.09	ns
LVTTTL33_16mA	LVTTTL 16mA drive, VCCIO = 3.3V	-0.10	-0.10	-0.11	ns
LVTTTL33D_4mA	LVTTTL 4mA drive, VCCIO = 3.3V	0.04	0.02	0.01	ns
LVTTTL33D_8mA	LVTTTL 8mA drive, VCCIO = 3.3V	-0.02	-0.03	-0.05	ns
LVTTTL33D_12mA	LVTTTL 12mA drive, VCCIO = 3.3V	-0.08	-0.08	-0.09	ns
LVTTTL33D_16mA	LVTTTL 16mA drive, VCCIO = 3.3V	-0.10	-0.10	-0.11	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive, fast slew rate	0.04	0.02	0.01	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive, fast slew rate	-0.02	-0.03	-0.05	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive, fast slew rate	-0.08	-0.08	-0.09	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive, fast slew rate	-0.10	-0.10	-0.11	ns
LVC MOS33D_4mA	LVC MOS 3.3 4mA drive, fast slew rate	0.04	0.02	0.01	ns
LVC MOS33D_8mA	LVC MOS 3.3 8mA drive, fast slew rate	-0.02	-0.03	-0.05	ns
LVC MOS33D_12mA	LVC MOS 3.3 12mA drive, fast slew rate	-0.08	-0.08	-0.09	ns
LVC MOS33D_16mA	LVC MOS 3.3 16mA drive, fast slew rate	-0.10	-0.10	-0.11	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive, fast slew rate	0.12	0.10	0.08	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive, fast slew rate	0.06	0.05	0.04	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive, fast slew rate	0.00	0.00	0.00	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive, fast slew rate	-0.04	-0.03	-0.03	ns
LVC MOS25D_4mA	LVC MOS 2.5 4mA drive, fast slew rate	0.12	0.10	0.08	ns
LVC MOS25D_8mA	LVC MOS 2.5 8mA drive, fast slew rate	0.06	0.05	0.04	ns
LVC MOS25D_12mA	LVC MOS 2.5 12mA drive, fast slew rate	-0.04	-0.03	-0.03	ns
LVC MOS25D_16mA	LVC MOS 2.5 16mA drive, fast slew rate	-0.04	-0.03	-0.03	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive, fast slew rate	0.11	0.12	0.14	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive, fast slew rate	0.11	0.12	0.14	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive, fast slew rate	-0.04	-0.03	-0.03	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive, fast slew rate	-0.04	-0.03	-0.03	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive, fast slew rate	0.21	0.25	0.29	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive, fast slew rate	0.05	0.07	0.09	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive, fast slew rate	0.43	0.51	0.59	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive, fast slew rate	0.23	0.28	0.33	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive, slow slew rate	1.44	1.58	1.72	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive, slow slew rate	0.98	1.10	1.22	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive, slow slew rate	0.67	0.77	0.86	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive, slow slew rate	0.97	1.09	1.21	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive, slow slew rate	0.67	0.76	0.85	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive, slow slew rate	1.48	1.63	1.78	ns

ECP5 Family Timing Adders^{1, 2, 3, 4, 5} (Continued)
Over Recommended Commercial Operating Conditions

Buffer Type	Description	-8	-7	-6	Units
LVC MOS25_8mA	LVC MOS 2.5 8mA drive, slow slew rate	1.02	1.14	1.27	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive, slow slew rate	0.74	0.84	0.94	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive, slow slew rate	1.02	1.14	1.26	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive, slow slew rate	0.74	0.83	0.93	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive, slow slew rate	1.60	1.77	1.93	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive, slow slew rate	1.11	1.25	1.38	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive, slow slew rate	0.87	0.98	1.09	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive, slow slew rate	0.86	0.97	1.07	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive, slow slew rate	1.71	1.89	2.08	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive, slow slew rate	1.20	1.34	1.48	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive, slow slew rate	1.37	1.56	1.74	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive, slow slew rate	1.11	1.27	1.43	ns

1. Timing adders are characterized but not tested on every device.
2. LVC MOS timing measured with the load specified in Switching Test Condition table.
3. All other standards tested according to the appropriate specifications.
4. Not all I/O standards and drive strengths are supported for all banks. See the Architecture section of this data sheet for details.
5. Commercial timing numbers are shown. Industrial numbers are typically slower and can be extracted from the Diamond or isp-LEVER software.

ECP5 Maximum I/O Buffer Speed^{1, 2, 3, 4, 5, 6}

Over Recommended Operating Conditions

Buffer	Description	Max.	Units
Maximum Input Frequency			
LVDS25	LVDS, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MLVDS25	MLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	400	MHz
BLVDS25	BLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MIPI D-PHY (HS Mode)	MIPI Video	400	MHz
SLVS	SLVS similar to MIPI	400	MHz
Mini LVDS	Mini LVDS	400	MHz
LVPECL33	LVPECL, Emulated, $V_{CCIO} = 3.3\text{ V}$	400	MHz
SSTL18 (all supported classes)	SSTL_18 class I, II, $V_{CCIO} = 1.8\text{ V}$	400	MHz
SSTL15 (all supported classes)	SSTL_15 class I, II, $V_{CCIO} = 1.5\text{ V}$	400	MHz
SSTL135 (all supported classes)	SSTL_135 class I, II, $V_{CCIO} = 1.35\text{ V}$	400	MHz
HSUL12 (all supported classes)	HSUL_12 class I, II, $V_{CCIO} = 1.2\text{ V}$	400	MHz
LVTTTL33	LVTTTL, $V_{CCIO} = 3.3\text{ V}$	150	MHz
LVC MOS33	LVC MOS, $V_{CCIO} = 3.3\text{ V}$	150	MHz
LVC MOS25	LVC MOS, $V_{CCIO} = 2.5\text{ V}$	150	MHz
LVC MOS18	LVC MOS, $V_{CCIO} = 1.8\text{ V}$	150	MHz
LVC MOS15	LVC MOS 1.5, $V_{CCIO} = 1.5\text{ V}$	150	MHz
LVC MOS12	LVC MOS 1.2, $V_{CCIO} = 1.2\text{ V}$	150	MHz
Maximum Output Frequency			
LVDS25E	LVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	300	MHz
LVDS25	LVDS, $V_{CCIO} = 2.5\text{ V}$	400	MHz
MLVDS25	MLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	300	MHz
BLVDS25	BLVDS, Emulated, $V_{CCIO} = 2.5\text{ V}$	300	MHz
LVPECL33	LVPECL, Emulated, $V_{CCIO} = 3.3\text{ V}$	300	MHz
SSTL18 (all supported classes)	SSTL_18 class I, II, $V_{CCIO} = 1.8\text{ V}$	400	MHz
SSTL15 (all supported classes)	SSTL_15 class I, II, $V_{CCIO} = 1.5\text{ V}$	400	MHz
SSTL135 (all supported classes)	SSTL_135 class I, II, $V_{CCIO} = 1.35\text{ V}$	400	MHz
HSUL12 (all supported classes)	HSUL12 class I, II, $V_{CCIO} = 1.2\text{ V}$	400	MHz
LVTTTL33	LVTTTL, $V_{CCIO} = 3.3\text{ V}$	150	MHz
LVC MOS33 (For all drives)	LVC MOS, 3.3 V	150	MHz
LVC MOS25 (For all drives)	LVC MOS, 2.5 V	150	MHz
LVC MOS18 (For all drives)	LVC MOS, 1.8 V	150	MHz
LVC MOS15 (For all drives)	LVC MOS, 1.5 V	150	MHz
LVC MOS12 (For all drives except 2mA)	LVC MOS, $V_{CCIO} = 1.2\text{ V}$	150	MHz
LVC MOS12 (2mA drive)	LVC MOS, $V_{CCIO} = 1.2\text{ V}$	150	MHz

1. These maximum speeds are characterized but not tested on every device.
2. Maximum I/O speed for differential output standards emulated with resistors depends on the layout.
3. LVC MOS timing is measured with the load specified in the Switching Test Conditions table of this document.
4. All speeds are measured at fast slew.
5. Actual system operation may vary depending on user logic implementation.
6. Maximum data rate equals 2 times the clock rate when utilizing DDR.

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		10	400	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS,		3.125	400	MHz
f_{VCO}	PLL VCO Frequency		400	800	MHz
f_{PFD}^3	Phase Detector Input Frequency		10	400	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle		47	53	%
t_{PH4}	Output Phase Accuracy		-5	5	%
t_{OPJIT}^1	Output Clock Period Jitter	$f_{OUT} \geq 100\text{MHz}$	—	100	ps p-p
		$f_{OUT} < 100\text{MHz}$	—	0.025	UIPP
	Output Clock Cycle-to-Cycle Jitter	$f_{OUT} \geq 100\text{MHz}$	—	200	ps p-p
		$f_{OUT} < 100\text{MHz}$	—	0.050	UIPP
	Output Clock Phase Jitter	$f_{PFD} > 100\text{MHz}$	—	160	ps p-p
		$f_{PFD} < 100\text{MHz}$	—	0.011	UIPP
t_{SPO}	Static Phase Offset	Divider ratio = integer	—	400	ps p-p
t_W	Output Clock Pulse Width	At 90% or 10%3	0.9	—	ns
t_{LOCK}^2	PLL Lock-in Time		—	15	ms
t_{UNLOCK}	PLL Unlock Time		—	50	ns
t_{IPJIT}^6	Input Clock Period Jitter	$f_{PFD} \geq 20\text{ MHz}$	—	1,000	ps p-p
		$f_{PFD} < 20\text{ MHz}$	—	0.02	UIPP
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST/ Pulse Width		1	—	ms
t_{RSTREC}	RST Recovery Time		1	—	ns
t_{LOAD_REG}	Min Pulse for CIB_LOAD_REG		10	—	ns
$t_{ROTATE-SETUP}$	Min time for CIB dynamic phase controls to be stable fore CIB_ROTATE		5	—	ns
$t_{ROTATE-WD}$	Min pulse width for CIB_ROTATE to maintain "0" or "1"		4	—	VCO cycles

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock with no additional I/O toggling.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Period jitter and cycle-to-cycle jitter numbers are guaranteed for $f_{PFD} > 4\text{MHz}$. For $f_{PFD} < 4\text{MHz}$, the jitter numbers may not be met in certain conditions. Please contact the factory for $f_{PFD} < 4\text{MHz}$.

DLL Timing

Over Recommended Operating Conditions

Parameter	Description	Condition	Min.	Typ.	Max.	Units
f _{REF}	Input reference clock frequency (on-chip or off-chip)		100	—	400	MHz
t _{PWH}	Input clock minimum pulse width high (at 80% level)		550	—	—	ps
t _{PWL}	Input clock minimum pulse width low (at 20% level)		550	—	—	ps
t _{INSTB}	Input clock period jitter		—	—	500	ps
t _{LOCK}	DLL lock time		8	—	8200	cycles
t _{RSWD}	Digital reset minimum pulse width (at 80% level)		3	—	—	ns

1. CLKOP runs at the same frequency as the input clock.
2. CLKOS minimum frequency is obtained with divide by 4.
3. This is intended to be a “path-matching” design guideline and is not a measurable specification.

SERDES High-Speed Data Transmitter¹

Table 3-6. Serial Output Timing and Levels

Symbol	Description	Min.	Typ.	Max.	Units
V _{TX-DIFF-PP-1.2}	Differential Swing, 1.2 V setting, only at V _{CCHTX} =1.2V±5% ^{1,2}	-20%	1200	20%	mV, pp
V _{TX-DIFF-PP-1.1}	Differential Swing, 1.1 V setting ^{1,2}	-25%	1100	25%	mV, pp
V _{TX-DIFF-PP-1.0}	Differential Swing, 1.0 V setting ^{1,2}	-25%	1000	25%	mV, pp
V _{TX-DIFF-PP-0.9}	Differential Swing, 0.9 V setting ^{1,2}	-25%	900	25%	mV, pp
V _{TX-DIFF-PP-0.85}	Differential Swing, 0.85 V setting ^{1,2}	-25%	850	25%	mV, pp
V _{TX-DIFF-PP-0.75}	Differential Swing, 0.75 V setting ^{1,2}	-25%	750	25%	mV, pp
V _{TX-DIFF-PP-0.7}	Differential Swing, 0.7 V setting ^{1,2}	-25%	700	25%	mV, pp
V _{TX_COM}	Output common mode voltage	-10%	V _{CCHTX} /2	10%	mV, pp
T _{TX-R}	Rise time (20% to 80%)	50	-	-	ps
T _{TX-F}	Fall time (80% to 20%)	50	-	-	ps
T _{TX-SKEW}	Transmit output skew of P/N	-	-	15	ps
Z _{TX_SE}	Single ended output impedance	-20%	50/75/HiZ	20%	Ohms
R _{LTX_DIFF}	Differential return loss (with package included) ³	-	-	-10	dB
R _{LTX_COM}	Common mode return loss (with package included) ³	-	-	-6	dB

1. All measurements are with 50 ohm impedance.
2. See TN1261, [ECP5 SERDES/PCS Usage Guide](#) for actual binary settings and the min-max range.
3. Return los = -10dB (differential), -6dB (common mode) for 50kHz ≤ f ≤ 1.6GHz with 50-ohm output impedance configuration. This includes degradation due to package effects.

Table 3-7. Channel Output Jitter

Description	Frequency	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	—	—	0.17	UI, p-p
Random	3.125 Gbps	—	—	0.25	UI, p-p
Total	3.125 Gbps	—	—	0.35	UI, p-p
Deterministic	2.5 Gbps	—	—	0.17	UI, p-p
Random	2.5 Gbps	—	—	0.20	UI, p-p
Total	2.5 Gbps	—	—	0.35	UI, p-p
Deterministic	1.25 Gbps	—	—	0.10	UI, p-p
Random	1.25 Gbps	—	—	0.22	UI, p-p
Total	1.25 Gbps	—	—	0.24	UI, p-p
Deterministic	622 Mbps	—	—	0.10	UI, p-p
Random	622 Mbps	—	—	0.20	UI, p-p
Total	622 Mbps	—	—	0.24	UI, p-p
Deterministic	250 Mbps	—	—	0.10	UI, p-p
Random	250 Mbps	—	—	0.18	UI, p-p
Total	250 Mbps	—	—	0.24	UI, p-p
Deterministic	150 Mbps	—	—	0.10	UI, p-p
Random	150 Mbps	—	—	0.18	UI, p-p
Total	150 Mbps	—	—	0.24	UI, p-p

Note: Values are measured with PRBS 2^7-1 , all channels operating, FPGA logic active, I/Os around SERDES pins quiet, reference clock @ 10X mode.

SERDES/PCS Block Latency

Table 3-8 describes the latency of each functional block in the transmitter and receiver. Latency is given in parallel clock cycles. Figure 3-11 shows the location of each block.

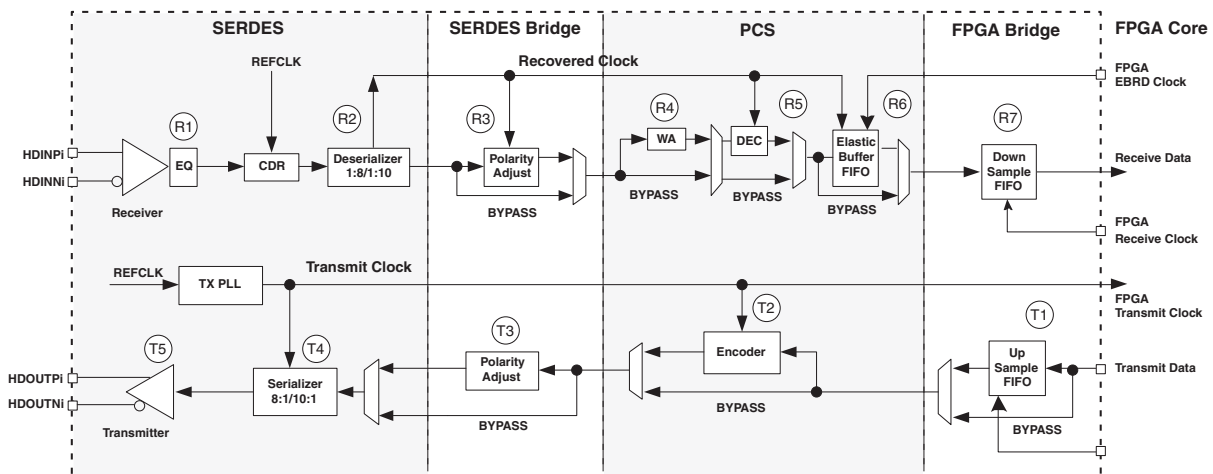
Table 3-8. SERDES/PCS Latency Breakdown

Item	Description	Min.	Avg.	Max.	Fixed	Bypass	Units
Transmit Data Latency¹							
T1	FPGA Bridge - Gearing disabled with different clocks	1	3	5	—	1	word clk
	FPGA Bridge - Gearing disabled with same clocks	—	—	—	3	1	word clk
	FPGA Bridge - Gearing enabled	1	3	5	—	—	word clk
T2	8b10b Encoder	—	—	—	2	1	word clk
T3	SERDES Bridge transmit	—	—	—	2	1	word clk
T4	Serializer: 8-bit mode	—	—	—	15 + Δ1	—	UI + ps
	Serializer: 10-bit mode	—	—	—	18 + Δ1	—	UI + ps
T5	Pre-emphasis ON	—	—	—	1 + Δ2	—	UI + ps
	Pre-emphasis OFF	—	—	—	0 + Δ3	—	UI + ps
Receive Data Latency²							
R1	Equalization ON	—	—	—	Δ1	—	UI + ps
	Equalization OFF	—	—	—	Δ2	—	UI + ps
R2	Deserializer: 8-bit mode	—	—	—	10 + Δ3	—	UI + ps
	Deserializer: 10-bit mode	—	—	—	12 + Δ3	—	UI + ps
R3	SERDES Bridge receive	—	—	—	2	—	word clk
R4	Word alignment	3.1	—	4	—	—	word clk
R5	8b10b decoder	—	—	—	1	—	word clk
R6	Clock Tolerance Compensation	7	15	23	1	1	word clk
R7	FPGA Bridge - Gearing disabled with different clocks	1	3	5	—	1	word clk
	FPGA Bridge - Gearing disabled with same clocks	—	—	—	3	1	word clk
	FPGA Bridge - Gearing enabled	1	3	5	—	—	word clk

1. Δ1 = -245ps, Δ2 = +88ps, Δ3 = +112ps.

2. Δ1 = +118ps, Δ2 = +132ps, Δ3 = +700ps.

Figure 3-11. Transmitter and Receiver Latency Block Diagram



SERDES High Speed Data Receiver

Table 3-9. Serial Input Data Specifications

Symbol	Description	Min.	Typ.	Max.	Units	
RX-CID _S	Stream of nontransitions ¹ (CID = Consecutive Identical Digits) @ 10 ⁻¹² BER	3.125G	—	—	136	Bits
		2.5G	—	—	144	
		1.485G	—	—	160	
		622M	—	—	204	
		270M	—	—	228	
		150M	—	—	296	
V _{RX-DIFF-S}	Differential input sensitivity	150	—	1760	mV, p-p	
V _{RX-IN}	Input levels	0	—	V _{CCA} +0.5 ⁴	V	
V _{RX-CM-DC}	Input common mode range (DC coupled)	0.6	—	V _{CCA}	V	
V _{RX-CM-AC}	Input common mode range (AC coupled) ³	0.1	—	V _{CCA} +0.2	V	
T _{RX-RELOCK}	SCDR re-lock time ²	—	1000	—	Bits	
Z _{RX-TERM}	Input termination 50/75 Ohm/High Z	-20%	50/75/HiZ	+20%	Ohms	
RL _{RX-RL}	Return loss (without package)	—	—	-10	dB	

1. This is the number of bits allowed without a transition on the incoming data stream when using DC coupling.
2. This is the typical number of bit times to re-lock to a new phase or frequency within +/- 300 ppm, assuming 8b10b encoded data.
3. AC coupling is used to interface to LVPECL and LVDS. LVDS interfaces are found in laser drivers and Fibre Channel equipment. LVDS interfaces are generally found in 622 Mbps SERDES devices.
4. Up to 1.76 V.

Input Data Jitter Tolerance

A receiver's ability to tolerate incoming signal jitter is very dependent on jitter type. High speed serial interface standards have recognized the dependency on jitter type and have specifications to indicate tolerance levels for different jitter types as they relate to specific protocols. Sinusoidal jitter is considered to be a worst case jitter type.

Table 3-10. Receiver Total Jitter Tolerance Specification

Description	Frequency	Condition	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	600 mV differential eye	—	—	0.47	UI, p-p
Random		600 mV differential eye	—	—	0.18	UI, p-p
Total		600 mV differential eye	—	—	0.65	UI, p-p
Deterministic	2.5 Gbps	600 mV differential eye	—	—	0.47	UI, p-p
Random		600 mV differential eye	—	—	0.18	UI, p-p
Total		600 mV differential eye	—	—	0.65	UI, p-p
Deterministic	1.25 Gbps	600 mV differential eye	—	—	0.47	UI, p-p
Random		600 mV differential eye	—	—	0.18	UI, p-p
Total		600 mV differential eye	—	—	0.65	UI, p-p
Deterministic	622 Mbps	600 mV differential eye	—	—	0.47	UI, p-p
Random		600 mV differential eye	—	—	0.18	UI, p-p
Total		600 mV differential eye	—	—	0.65	UI, p-p

Note: Values are measured with CJPAT, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, voltages are nominal, room temperature.

Table 3-11. Periodic Receiver Jitter Tolerance Specification

Description	Frequency	Condition	Min.	Typ.	Max.	Units
Periodic	2.97 Gbps	600 mV differential eye	—	—	0.24	UI, p-p
Periodic	2.5 Gbps	600 mV differential eye	—	—	0.22	UI, p-p
Periodic	1.485 Gbps	600 mV differential eye	—	—	0.24	UI, p-p
Periodic	622 Mbps	600 mV differential eye	—	—	0.15	UI, p-p

Note: Values are measured with PRBS 2⁷-1, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, voltages are nominal, room temperature.

SERDES External Reference Clock

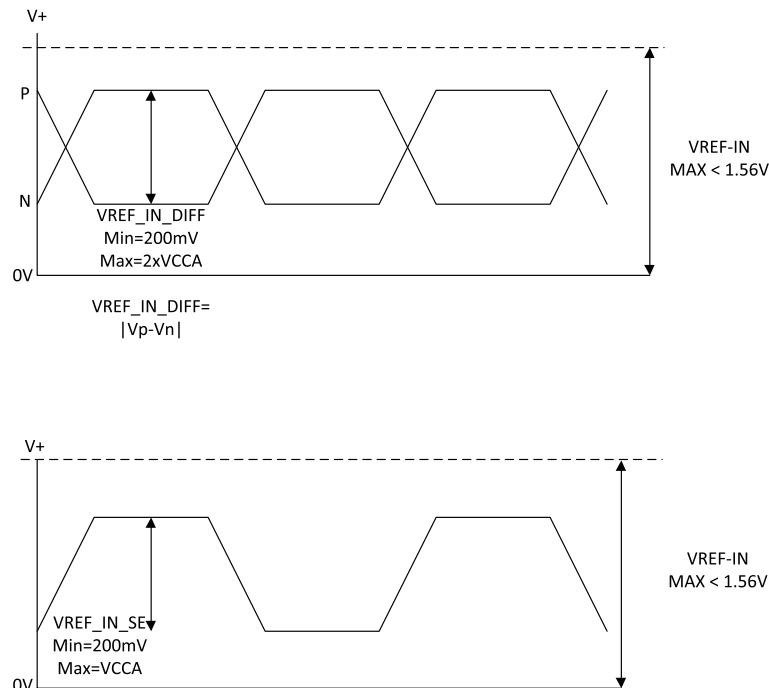
The external reference clock selection and its interface are a critical part of system applications for this product. Table 3-12 specifies reference clock requirements, over the full range of operating conditions.

Table 3-12. External Reference Clock Specification (refclkp/refclkn)

Symbol	Description	Min.	Typ.	Max.	Units
F_{REF}	Frequency range	50	—	320	MHz
$F_{REF-PPM}$	Frequency tolerance ¹	-1000	—	1000	ppm
$V_{REF-IN-SE}$	Input swing, single-ended clock ²	200	—	V_{CCA}	mV, p-p
$V_{REF-IN-DIFF}$	Input swing, differential clock	200	—	$2 \cdot V_{CCA}$	mV, p-p differential
V_{REF-IN}	Input levels	0	—	$V_{CCA} + 0.4$	V
D_{REF}	Duty cycle ³	40	—	60	%
T_{REF-R}	Rise time (20% to 80%)	200	500	1000	ps
T_{REF-F}	Fall time (80% to 20%)	200	500	1000	ps
$Z_{REF-IN-TERM-DIFF}$	Differential input termination	-20%	100/2K	+20%	Ohms
$C_{REF-IN-CAP}$	Input capacitance	—	—	7	pF

1. Depending on the application, the PLL_LOL_SET and CDR_LOL_SET control registers may be adjusted for other tolerance values as described in TN1261, [ECP5 SERDES/PCS Usage Guide](#).
2. The signal swing for a single-ended input clock must be as large as the p-p differential swing of a differential input clock to get the same gain at the input receiver. Lower swings for the clock may be possible, but will tend to increase jitter.
3. Measured at 50% amplitude.

Figure 3-12. SERDES External Reference Clock Waveforms



PCI Express Electrical and Timing Characteristics

AC and DC Characteristics

Over Recommended Operating Conditions

Symbol	Description	Test Conditions	Min	Typ	Max	Units
Transmit¹						
UI	Unit interval		399.88	400	400.12	ps
V _{TX-DIFF_P-P}	Differential peak-to-peak output voltage		0.8	1.0	1.2	V
V _{TX-DE-RATIO}	De-emphasis differential output voltage ratio		-3	-3.5	-4	dB
V _{TX-CM-AC_P}	RMS AC peak common-mode output voltage		—	—	20	mV
V _{TX-RCV-DETECT}	Amount of voltage change allowed during receiver detection		—	—	600	mV
V _{TX-DC-CM}	Tx DC common mode voltage		0	—	V _{CCOB} + 5%	V
I _{TX-SHORT}	Output short circuit current	V _{TX-D+=0.0V} V _{TX-D-=0.0V}	—	—	90	mA
Z _{TX-DIFF-DC}	Differential output impedance		80	100	120	Ohms
RL _{TX-DIFF}	Differential return loss		10	—	—	dB
RL _{TX-CM}	Common mode return loss		6.0	—	—	dB
T _{TX-RISE}	Tx output rise time	20 to 80%	0.125	—	—	UI
T _{TX-FALL}	Tx output fall time	20 to 80%	0.125	—	—	UI
L _{TX-SKEW}	Lane-to-lane static output skew for all lanes in port/link		—	—	1.3	ns
T _{TX-EYE}	Transmitter eye width		0.75	—	—	UI
T _{TX-EYE-MEDIAN-TO-MAX-JITTER}	Maximum time between jitter median and maximum deviation from median		—	—	0.125	UI
Receive^{1, 2}						
UI	Unit Interval		399.88	400	400.12	ps
V _{RX-DIFF_P-P}	Differential peak-to-peak input voltage		0.34 ³	—	1.2	V
V _{RX-IDLE-DET-DIFF_P-P}	Idle detect threshold voltage		65	—	340 ³	mV
V _{RX-CM-AC_P}	Receiver common mode voltage for AC coupling		—	—	150	mV
Z _{RX-DIFF-DC}	DC differential input impedance		80	100	120	Ohms
Z _{RX-DC}	DC input impedance		40	50	60	Ohms
Z _{RX-HIGH-IMP-DC}	Power-down DC input impedance		200K	—	—	Ohms
RL _{RX-DIFF}	Differential return loss		10	—	—	dB
RL _{RX-CM}	Common mode return loss		6.0	—	—	dB
T _{RX-IDLE-DET-DIFF-ENTERTIME}	Maximum time required for receiver to recognize and signal an unexpected idle on link		—	—	—	ms

1. Values are measured at 2.5 Gbps.

2. Measured with external AC-coupling on the receiver.

3. Not in compliance with PCI Express 1.1 standard.

XAUI/Serial Rapid I/O Type 3/CPRI LV E.30 Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-13. Transmit

Over Recommended Operating Conditions

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
T_{RF}	Differential rise/fall time	20%-80%	—	80	—	ps
$Z_{TX_DIFF_DC}$	Differential impedance		80	100	120	Ohms
$J_{TX_DDJ}^{2,3,4}$	Output data deterministic jitter		—	—	0.17	UI
$J_{TX_TJ}^{1,2,3,4}$	Total output data jitter		—	—	0.35	UI

1. Total jitter includes both deterministic jitter and random jitter.
2. Jitter values are measured with each CML output AC coupled into a 50-ohm impedance (100-ohm differential impedance).
3. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
4. Values are measured at 2.5 Gbps.

Table 3-14. Receive and Jitter Tolerance

Over Recommended Operating Conditions

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
RL_{RX_DIFF}	Differential return loss	From 100 MHz to 3.125 GHz	10	—	—	dB
RL_{RX_CM}	Common mode return loss	From 100 MHz to 3.125 GHz	6	—	—	dB
Z_{RX_DIFF}	Differential termination resistance		80	100	120	Ohms
$J_{RX_DJ}^{1,2,3}$	Deterministic jitter tolerance (peak-to-peak)		—	—	0.37	UI
$J_{RX_RJ}^{1,2,3}$	Random jitter tolerance (peak-to-peak)		—	—	0.18	UI
$J_{RX_SJ}^{1,2,3}$	Sinusoidal jitter tolerance (peak-to-peak)		—	—	0.10	UI
$J_{RX_TJ}^{1,2,3}$	Total jitter tolerance (peak-to-peak)		—	—	0.65	UI
T_{RX_EYE}	Receiver eye opening		0.35	—	—	UI

1. Total jitter includes deterministic jitter, random jitter and sinusoidal jitter. The sinusoidal jitter tolerance mask is shown in Figure .
2. Jitter values are measured with each high-speed input AC coupled into a 50-ohm impedance.
3. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
4. Jitter tolerance parameters are characterized when Full Rx Equalization is enabled.
5. Values are measured at 2.5 Gbps.

Serial Rapid I/O Type 2/CPRI LV E.24 Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-15. Transmit

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
T_{RF}^1	Differential rise/fall time	20%-80%	—	80	—	ps
$Z_{TX_DIFF_DC}$	Differential impedance		80	100	120	Ohms
$J_{TX_DDJ}^{3,4,5}$	Output data deterministic jitter		—	—	0.17	UI
$J_{TX_TJ}^{2,3,4,5}$	Total output data jitter		—	—	0.35	UI

1. Rise and Fall times measured with board trace, connector and approximately 2.5pf load.
2. Total jitter includes both deterministic jitter and random jitter. The random jitter is the total jitter minus the actual deterministic jitter.
3. Jitter values are measured with each CML output AC coupled into a 50-ohm impedance (100-ohm differential impedance).
4. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
5. Values are measured at 2.5 Gbps.

Table 3-16. Receive and Jitter Tolerance

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
RL_{RX_DIFF}	Differential return loss	From 100 MHz to 2.5 GHz	10	—	—	dB
RL_{RX_CM}	Common mode return loss	From 100 MHz to 2.5 GHz	6	—	—	dB
Z_{RX_DIFF}	Differential termination resistance		80	100	120	Ohms
$J_{RX_DJ}^{2,3,4,5}$	Deterministic jitter tolerance (peak-to-peak)		—	—	0.37	UI
$J_{RX_RJ}^{2,3,4,5}$	Random jitter tolerance (peak-to-peak)		—	—	0.18	UI
$J_{RX_SJ}^{2,3,4,5}$	Sinusoidal jitter tolerance (peak-to-peak)		—	—	0.10	UI
$J_{RX_TJ}^{1,2,3,4,5}$	Total jitter tolerance (peak-to-peak)		—	—	0.65	UI
T_{RX_EYE}	Receiver eye opening		0.35	—	—	UI

1. Total jitter includes deterministic jitter, random jitter and sinusoidal jitter. The sinusoidal jitter tolerance mask is shown in Figure .
2. Jitter values are measured with each high-speed input AC coupled into a 50-ohm impedance.
3. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
4. Jitter tolerance, Differential Input Sensitivity and Receiver Eye Opening parameters are characterized when Full Rx Equalization is enabled.
5. Values are measured at 2.5 Gbps.

Gigabit Ethernet/Serial Rapid I/O Type 1/SGMII/CPRI LV E.12 Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-17. Transmit

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
T_{RF}	Differential rise/fall time	20%-80%	—	80	—	ps
$Z_{TX_DIFF_DC}$	Differential impedance		80	100	120	Ohms
$J_{TX_DDJ}^{3,4,5}$	Output data deterministic jitter		—	—	0.10	UI
$J_{TX_TJ}^{2,3,4,5}$	Total output data jitter		—	—	0.24	UI

1. Rise and fall times measured with board trace, connector and approximately 2.5pf load.
2. Total jitter includes both deterministic jitter and random jitter. The random jitter is the total jitter minus the actual deterministic jitter.
3. Jitter values are measured with each CML output AC coupled into a 50-ohm impedance (100-ohm differential impedance).
4. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
5. Values are measured at 1.25 Gbps.

Table 3-18. Receive and Jitter Tolerance

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
RL_{RX_DIFF}	Differential return loss	From 100 MHz to 1.25 GHz	10	—	—	dB
RL_{RX_CM}	Common mode return loss	From 100 MHz to 1.25 GHz	6	—	—	dB
Z_{RX_DIFF}	Differential termination resistance		80	100	120	Ohms
$J_{RX_DJ}^{1,2,3,4,5}$	Deterministic jitter tolerance (peak-to-peak)		—	—	0.34	UI
$J_{RX_RJ}^{1,2,3,4,5}$	Random jitter tolerance (peak-to-peak)		—	—	0.26	UI
$J_{RX_SJ}^{1,2,3,4,5}$	Sinusoidal jitter tolerance (peak-to-peak)		—	—	0.11	UI
$J_{RX_TJ}^{1,2,3,4,5}$	Total jitter tolerance (peak-to-peak)		—	—	0.71	UI
T_{RX_EYE}	Receiver eye opening		0.29	—	—	UI

1. Total jitter includes deterministic jitter, random jitter and sinusoidal jitter. The sinusoidal jitter tolerance mask is shown in Figure .
2. Jitter values are measured with each high-speed input AC coupled into a 50-ohm impedance.
3. Jitter and skew are specified between differential crossings of the 50% threshold of the reference signal.
4. Jitter tolerance, Differential Input Sensitivity and Receiver Eye Opening parameters are characterized when Full Rx Equalization is enabled.
5. Values are measured at 1.25 Gbps.

SMPTE SD/HD-SDI/3G-SDI (Serial Digital Interface) Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-19. Transmit

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
BR _{SDO}	Serial data rate		270	—	2975	Mbps
T _{JALIGNMENT} ²	Serial output jitter, alignment	270 Mbps	—	—	0.20	UI
T _{JALIGNMENT} ²	Serial output jitter, alignment	1485 Mbps	—	—	0.20	UI
T _{JALIGNMENT} ^{1,2}	Serial output jitter, alignment	2970 Mbps	—	—	0.30	UI
T _{JTIMING}	Serial output jitter, timing	270 Mbps	—	—	0.20	UI
T _{JTIMING}	Serial output jitter, timing	1485 Mbps	—	—	1.0	UI
T _{JTIMING}	Serial output jitter, timing	2970 Mbps	—	—	2.0	UI

Notes:

- Timing jitter is measured in accordance with SMPTE RP 184-1996, SMPTE RP 192-1996 and the applicable serial data transmission standard, SMPTE 259M-1997 or SMPTE 292M (proposed). A color bar test pattern is used. The value of f_{SCLK} is 270 MHz or 360 MHz for SMPTE 259M, 540 MHz for SMPTE 344M or 1485 MHz for SMPTE 292M serial data rates. See the Timing Jitter Bandpass section.
- Jitter is defined in accordance with SMPTE RP1 184-1996 as: jitter at an equipment output in the absence of input jitter.
- All Tx jitter is measured at the output of an industry standard cable driver; connection to the cable driver is via a 50 ohm impedance differential signal from the Lattice SERDES device.
- The cable driver drives: RL=75 ohm, AC-coupled at 270, 1485, or 2970 Mbps, RREFLVL=RREFPRE=4.75kohm 1%.

Table 3-20. Receive

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
BR _{SDI}	Serial input data rate		270	—	2970	Mbps
CID	Stream of non-transitions (=Consecutive Identical Digits)		7(3G)/26(SMPTE Triple rates) @ 10-12 BER	—	—	Bits

Table 3-21. Reference Clock

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
F _{VCLK}	Video output clock frequency		27	—	74.25	MHz
DC _V	Duty cycle, video clock		45	50	55	%

ECP5 sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter		Min.	Max.	Units
POR, Configuration Initialization, and Wakeup					
t _{ICFG}	Time from the Application of V _{CC} , V _{CCAUX} or V _{CCIO8} (whichever is the last) to the rising edge of INITN	Master mode	-	33	ms
		Slave mode	-	16	ms
t _{VMC}	Time from t _{ICFG} to the valid Master CCLK		-	5	us
t _{MWC}	Additional wake master clock cycles after DONE goes HIGH		100	500	cycles
t _{CZ}	CCLK from Active to High-Z		-	300	ns
Master CCLK					
	Frequency	Select from OSC	-20	20	%
	Duty Cycle	Select from OSC	40	60	%
All Configuration Modes					
t _{PRGM}	PROGRAMN LOW pulse accepted		55	-	ns
t _{PRGMRJ}	PROGRAMN LOW pulse rejected		-	25	ns
t _{INITL}	INITN LOW time		-	55	ns
t _{DPPINT}	PROGRAMN LOW to INITN LOW		-	70	ns
t _{DPPDONE}	PROGRAMN LOW to DONE LOW		-	80	ns
t _{IODISS}	PROGRAMN LOW to I/O Disabled		-	120	ns
Slave SPI					
f _{CCLK}	CCLK input clock frequency		-	66	MHz
t _{CCLKH}	CCLK input clock pulsewidth HIGH		6	-	ns
t _{CCLKL}	CCLK input clock pulsewidth LOW		6	-	ns
t _{STSU}	CCLK setup time		2	-	ns
t _{STH}	CCLK hold time		0	-	ns
t _{STCO}	CCLK falling edge to valid output		-	10	ns
t _{STOZ}	CCLK falling edge to valid disable		-	10	ns
t _{STOV}	CCLK falling edge to valid enable		-	10	ns
t _{SCS}	Chip Select HIGH time		25	-	ns
t _{SCSS}	Chip Select setup tim		3	-	ns
t _{SCSH}	Chip Select hold time		3	-	ns
Master SPI					
f _{CCLK}	CCLK output clock frequency		-	133	MHz
t _{CCLKH}	CCLK output clock pulse width HIGH		3.5	-	ns
t _{CCLKL}	CCLK output clock pulse width LOW		3.5	-	ns
t _{STSU}	CCLK setup time		5	-	ns
t _{STH}	CCLK hold time		1	-	ns
t _{CSSPI}	INITN HIGH to Chip Select LOW		100	200	ns
t _{CFGX}	INITN HIGH to first CCLK edge		0.75	1	ns
Slave Serial					
f _{CCLK}	CCLK input clock frequency		-	66	MHz
t _{SSCH}	CCLK input clock pulse width HIGH		5	-	ns
t _{SSCL}	CCLK input clock pulse width LOW		5	-	ns
t _{SUSCDI}	CCLK setup time		2	-	ns
t _{HSCDI}	CCLK hold time		0	-	ns

ECP5 sysCONFIG Port Timing Specifications (Continued)

Over Recommended Operating Conditions

Slave Parallel					
f_{CCLK}	CCLK input clock frequency		-	66	MHz
t_{BSCH}	CCLK input clock pulsewidth HIGH		6	-	ns
t_{BSCL}	CCLK input clock pulsewidth LOW		6	-	ns
t_{CORD}	CCLK to DOUT for Read Data		-	12	ns
t_{SUCBDI}	Data Setup Time to CCLK		5	-	ns
t_{HCBDI}	Data Hold Time to CCLK		1	-	ns
t_{SUCS}	CSN, CSN1 Setup Time to CCLK		7	-	ns
t_{HCS}	CSN, CSN1 Hold Time to CCLK		1	-	ns
t_{SUWD}	WRITEN Setup Time to CCLK		7	-	ns
t_{HCWD}	WRITEN Hold Time to CCLK		1	-	ns
t_{DCB}	CCLK to BUSY Delay Time		-	12	ns

Figure 3-13. sysCONFIG Parallel Port Read Cycle

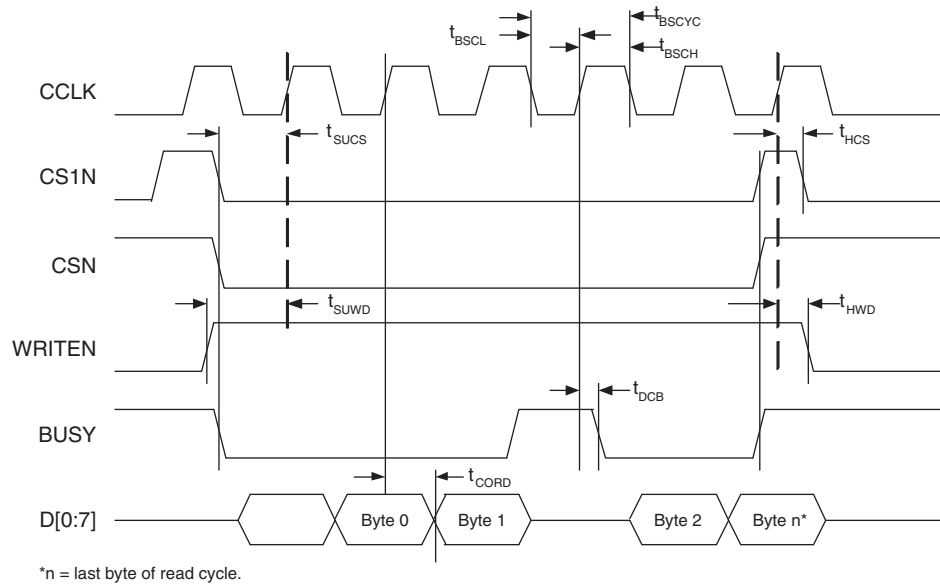


Figure 3-17. sysCONFIG Port Timing

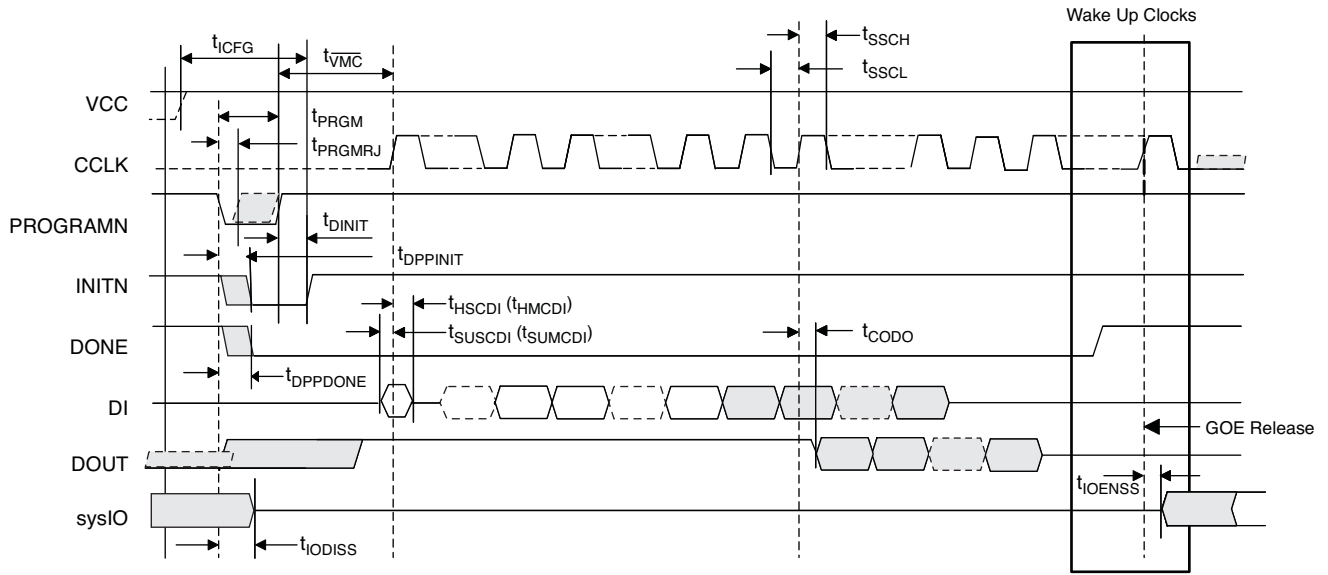
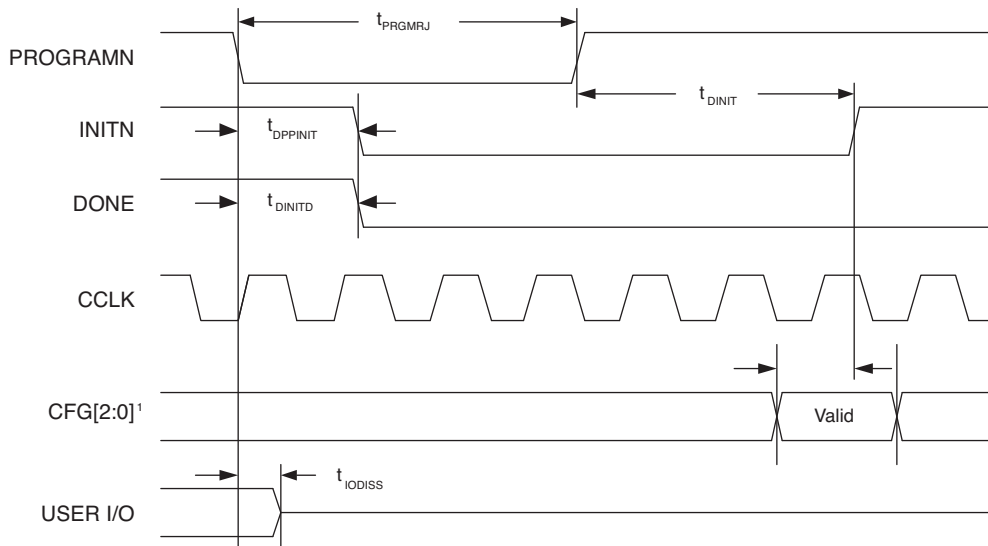


Figure 3-18. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-19. Wake-Up Timing

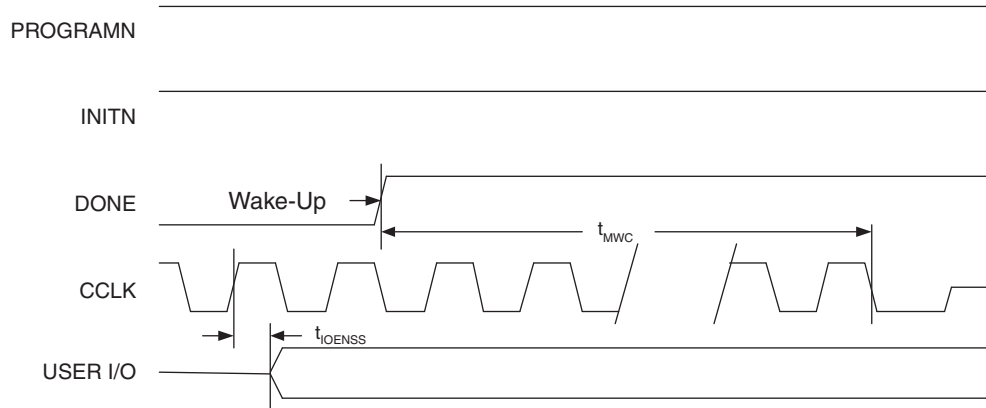
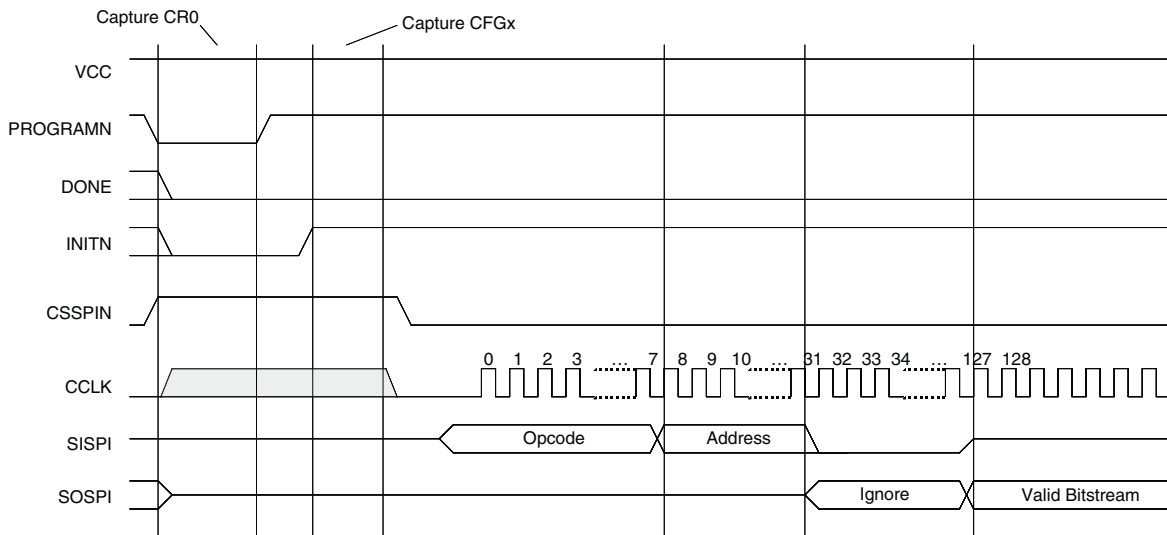


Figure 3-20. Master SPI Configuration Waveforms

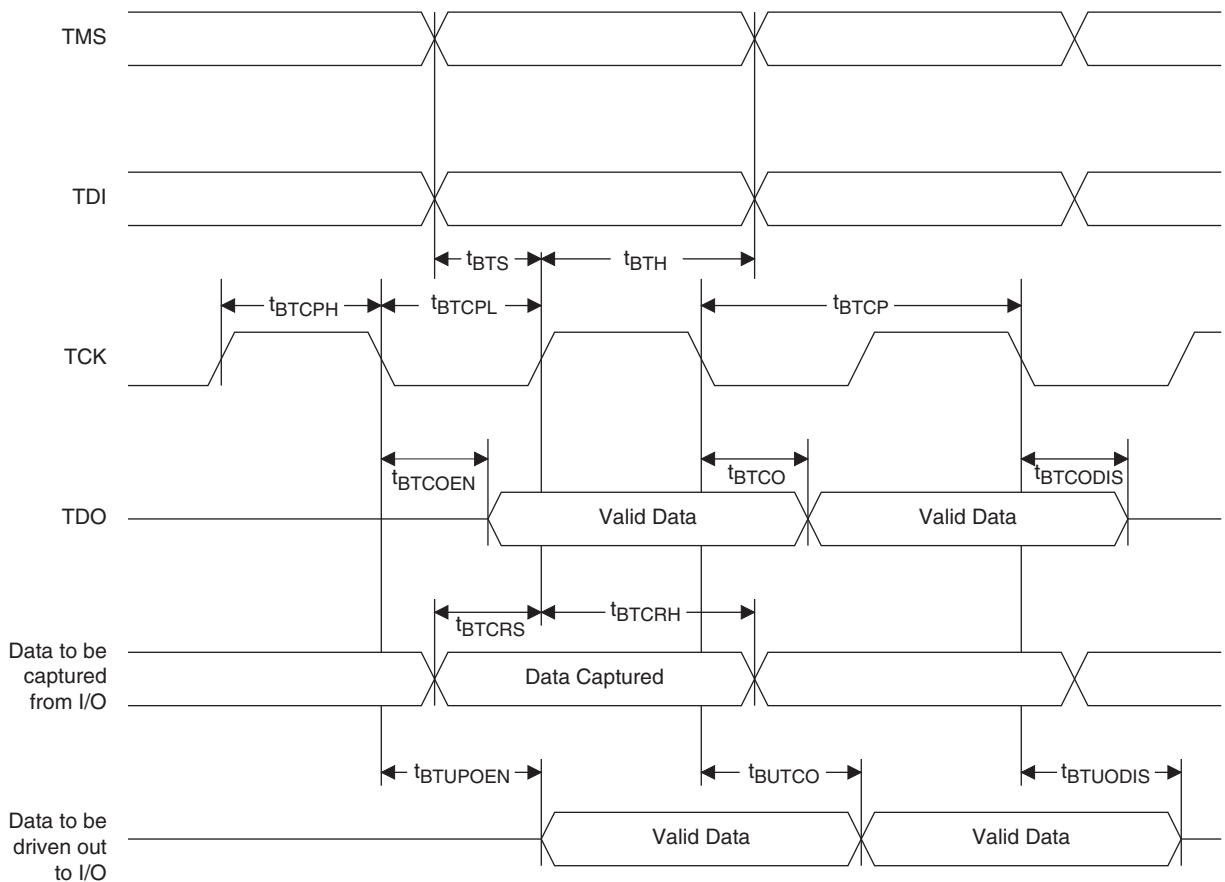


JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	10	—	ns
t_{BTH}	TCK [BSCAN] hold time	8	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

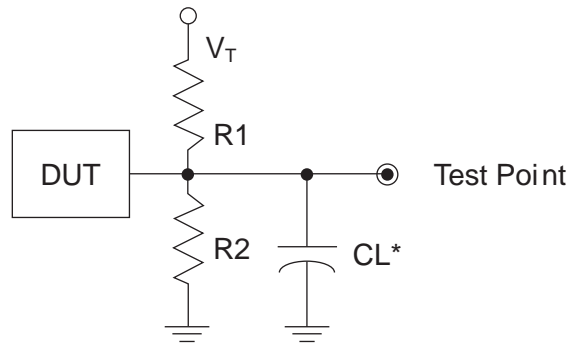
Figure 3-21. JTAG Port Timing Waveforms



Switching Test Conditions

Figure 3-22 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-22.

Figure 3-22. Output Test Load, LVTTTL and LVCMOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-22. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	R ₂	C _L	Timing Ref.	V _T
LVTTTL and other LVCMOS settings (L -> H, H -> L)	∞	∞	0pF	LVCMOS 3.3 = 1.5V	—
				LVCMOS 2.5 = V _{CCIO} /2	—
				LVCMOS 1.8 = V _{CCIO} /2	—
				LVCMOS 1.5 = V _{CCIO} /2	—
				LVCMOS 1.2 = V _{CCIO} /2	—
LVCMOS 2.5 I/O (Z -> H)	∞	1MΩ	0pF	V _{CCIO} /2	—
LVCMOS 2.5 I/O (Z -> L)	1MΩ	∞	0pF	V _{CCIO} /2	V _{CCIO}
LVCMOS 2.5 I/O (H -> Z)	∞	100	0pF	V _{OH} - 0.10	—
LVCMOS 2.5 I/O (L -> Z)	100	∞	0pF	V _{OL} + 0.10	V _{CCIO}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[L/R] [Group Number]_[A/B/C/D]	I/O	[L/R] indicates the L (Left), or R (Right) edge of the device. [Group Number] indicates the PIO [A/B/C/D] group. [A/B/C/D] indicates the PIO within the PIC to which the pad is connected. Some of these user-programmable pins are shared with special function pins. These pins, when not used as special purpose pins, can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tristated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tristated with an internal pull-up resistor enabled after configuration. PIO A and B are grouped as a pair, and PIO C and D are group as a pair. Each pair supports true LVDS differential input buffer. Only PIO A and B pair supports true LVDS differential output buffer. Each A/B and C/D pair supports programmable on/off differential input termination of 100 ohms.
P[T/B][Group Number]_[A/B]	I/O	[T/B] indicates the T (top) or B (bottom) edge of the device. [Group Number] indicates the PIO [A/B] group. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user-programmable pins are shared with sysConfig pins. These pins, when not used as configuration pins, can be programmed as I/Os for user logic. During configuration, the pins not used in configuration are tristated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), They are also tristated with an internal pull-up resistor enabled after configuration. PIOs on top and bottom do not support differential input signaling or true LVDS output signaling, but it can support emulated differential output buffer. PIO A/B forms a pair of emulated differential output buffer.
GSRN	I	Global RESET signal (active low). Any I/O pin can be GSRN.
NC	—	No connect.
RESERVED	—	This pin is reserved and should not be connected to anything on the board.
GND	—	Ground. Dedicated pins.
VCC	—	Power supply pins for core logic. Dedicated pins. VCC = 1.1V
VCCAUX	—	Auxiliary power supply pin. This dedicated pin powers all the differential and referenced input buffers. VCCAUX = 2.5 V.
VCCIOx	—	Dedicated power supply pins for I/O bank x. VCCIO8 is used for configuration and JTAG.
VREF1_x	—	Reference supply pins for I/O bank x. Pre-determined shared pin in each bank are assigned as VREF1 input. When not used, they may be used as I/O pins.
PLL, DLL and Clock Functions		
[LOC]_[GPLL][T, C]_IN	I	General Purpose PLL (GPLL) input pads: [LOC] = ULC, LLC, URC and LRC, T = true and C = complement. These pins are shared I/O pins. When not configured as GPLL input pads, they can be used as general purpose I/O pins.

Signal Name	I/O	Description
GR_PCLK[Bank][num]	I	General Routing Signals in Banks 0, 1, 2, 3, 4, 6 and 7. There are 2 in each bank ([num] = 0, 1). Please refer to ECP5 sysCLOCK Usage Guide. These pins are shared I/O pins. When not configured as GR pins, they can be used as general purpose I/O pins.
PCLK[T/C][Bank]_[num]	I/O	General Purpose Primary CLK pads: [T/C] = True/Complement, [Bank] = (0, 1, 2, 3, 6 and 7). There are 2 in each bank ([num] = 0, 1). These are shared I/O pins. When not configured as PCLK pins, they can be used as general purpose I/O pins.
[L/R]DQS[group_num]	I/O	DQS input/output pads: T (top), R (right), group_num = ball number associated with DQS[T] pin.
[T/R]DQ[group_num]	I/O	DQ input/output pads: T (top), R (right), group_num = ball number associated with DQS[T] pin.
Test and Programming (Dedicated Pins)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine. Pull-up is enabled during configuration. This is a dedicated input pin.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine. No pull-up enabled. This is a dedicated input pin.
TDI	I	Test Data in pin. Used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence). Pull-up is enabled during configuration. This is a dedicated input pin.
TDO	O	Output pin. Test Data Out pin used to shift data out of a device using 1149.1. This is a dedicated output pin.
Configuration Pads (Used During sysCONFIG)		
CFG[2:0]	I	Mode pins used to specify configuration mode values latched on rising edge of INITN. During configuration, a pull-up is enabled. These are dedicated pins.
INITN	I/O	Open Drain pin. Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. This is a dedicated pin.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up. This is a dedicated pin.
DONE	I/O	Open Drain pin. Indicates that the configuration sequence is complete, and the startup sequence is in progress. This is a dedicated pin.
CCLK	I/O	Input Configuration Clock for configuring an FPGA in Slave SPI, Serial, and CPU modes. Output Configuration Clock for configuring an FPGA in Master configuration modes (Master SPI, Master Serial). This is a dedicated pin.
HOLDN/DI/BUSY/CSSPIN/CEN	I/O	Parallel configuration mode busy indicator. SPI/SPI _m mode data output. This is a shared I/O pin. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
CSN/SN	I/O	Parallel configuration mode active-low chip select. Slave SPI chip select. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
CS1N	I	Parallel configuration mode active-low chip select. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
WRITEN	I	Write enable for parallel configuration modes. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.

Signal Name	I/O	Description
DOUT/CS0N	O	Serial data output. Chip select output. SPI/SPIm mode chip select. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D0/MOSI/IO0	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D1/MISO/IO1	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an input in Master mode, and output in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D2/IO2	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D3/IO3	I/O	Parallel configuration I/O. Open drain during configuration. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D4/MOSI2/IO4	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D5/MISO/IO5	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D6/IO6	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
D7/IO7	I/O	Parallel configuration I/O. Open drain during configuration. When in SPI modes, it is an output in Master mode, and input in Slave mode. This is a shared I/O pin. When not in configuration, it can be used as general purpose I/O pin.
SERDES Function		
VCCA _x	—	SERDES, transmit, receive, PLL and reference clock buffer power supply for SERDES Dual x. All VCCA supply pins must always be powered to the recommended operating voltage range. If no SERDES channels are used, connect VCCA to VCC. VCCA _x = 1.1 V.
VCCAUX _x	—	SERDES Aux Power Supply pin for SERDES Dual x. VCCAUX _x = 2.5 V.
HDRX[P/N]_D[dual_num]CH[chan_num]	I	High-speed SERDES inputs, P = Positive, N = Negative, dual_num = [0, 1], chan_num = [0, 1]. These are dedicated SERDES input pins.
HDTX[P/N]_D[dual_num]CH[chan_num]	O	High-speed SERDES outputs, P = Positive, N = Negative, dual_num = [0, 1], chan_num = [0, 1]. These are dedicated SERDES output pins.
REFCLK[P/N]_D[dual_num]	I	SERDES Reference Clock inputs, P = Positive, N = Negative, dual_num = [0, 1]. These are dedicated SERDES input pins.
VCCHR _x _D[dual_num]CH[chan_num]	—	SERDES High-Speed Inputs Termination Voltage Supplies, dual_num = [0, 1], chan_num = [0, 1]. These can be powered to 1.1 V or 1.2 V. If powered to 1.1V, it is recommended to connect it to VCCA _x .
VCCHT _x _D[dual_num]CH[chan_num]	—	SERDES High-Speed Outputs Buffer Voltage Supplies, dual_num = [0, 1], chan_num = [0, 1]. These can be powered to 1.1 V or 1.2 V.

- When placing switching I/Os around these critical pins that are designed to supply the device with the proper reference or supply voltage, care must be given.
- These pins are dedicated inputs or can be used as general purpose I/O.
- m defines the associated channel in the quad.

PICs and DDR Data (DQ) Pins Associated with the DDR Strobe (DQS) Pin

PICs Associated with DQS Strobe	PIO Within PIC	DDR Strobe (DQS) and Data (DQ) Pins
For Left and Right Edges of the Device Only		
P[L/R] [n-6]	A	DQ
	B	DQ
	C	DQ
	D	DQ
P[L/R] [n-3]	A	DQ
	B	DQ
	C	DQ
	D	DQ
P[L/R] [n]	A	DQS (P)
	B	DQS (N)
	C	DQ
	D	DQ
P[L/R] [n+3]	A	DQ
	B	DQ
	C	DQ
	D	DQ

Note: "n" is a row PIC number.

Pin Information Summary

LFE5UM

Pin Information Summary		LFE5UM-25		LFE5UM-45			LFE5UM-85			
Pin Type		285 csfBGA	381 caBGA	285 csf- BGA	381 caBGA	554 caBGA	285 csfBGA	381 caBGA	554 caBGA	756 caBGA
General Purpose Inputs/Outputs per Bank	Bank 0	6	24	6	27	32	6	27	32	56
	Bank 1	6	32	6	33	40	6	33	40	48
	Bank 2	21	32	21	32	32	21	34	32	48
	Bank 3	28	32	28	33	48	28	33	48	64
	Bank 4	0	0	0	0	0	0	0	14	24
	Bank 6	26	32	26	33	48	26	33	48	64
	Bank 7	18	32	18	32	32	18	32	32	48
	Bank 8	13	13	13	13	13	13	13	13	13
Total Single-Ended User I/O		118	197	118	203	245	118	205	259	365
VCC		13	20	13	20	24	13	20	24	36
VCCAUX (Core)		3	4	3	4	9	3	4	9	8
VCCIO	Bank 0	1	2	1	2	3	1	2	3	4
	Bank 1	1	2	1	2	3	1	2	3	4
	Bank 2	2	3	2	3	4	2	3	4	4
	Bank 3	2	3	2	3	3	2	3	3	4
	Bank 4	0	0	0	0	0	0	0	2	2
	Bank 6	2	3	2	3	4	2	3	4	4
	Bank 7	2	3	2	3	3	2	3	3	4
	Bank 8	2	2	2	2	2	2	2	2	2
TAP		4	4	4	4	4	4	4	4	4
Miscellaneous Dedicated Pins		7	7	7	7	7	7	7	7	7
GND		83	59	83	59	113	83	59	113	166
NC		1	8	1	2	33	1	0	17	29
Reserved		0	2	0	2	4	0	2	4	4
SERDES		14	28	14	28	28	14	28	28	28
VCCA (SERDES)	VCCA0	2	2	2	2	6	2	2	6	8
	VCCA1	0	2	0	2	6	0	2	6	9
VCCAUX (SERDES)	VCCAUXA0	2	2	2	2	2	2	2	2	2
	VCCAUXA1	0	2	0	2	2	0	2	2	2
GNDA (SERDES)		26	26	26	26	49	26	26	49	60
Total Balls		285	381	285	381	554	285	381	554	756

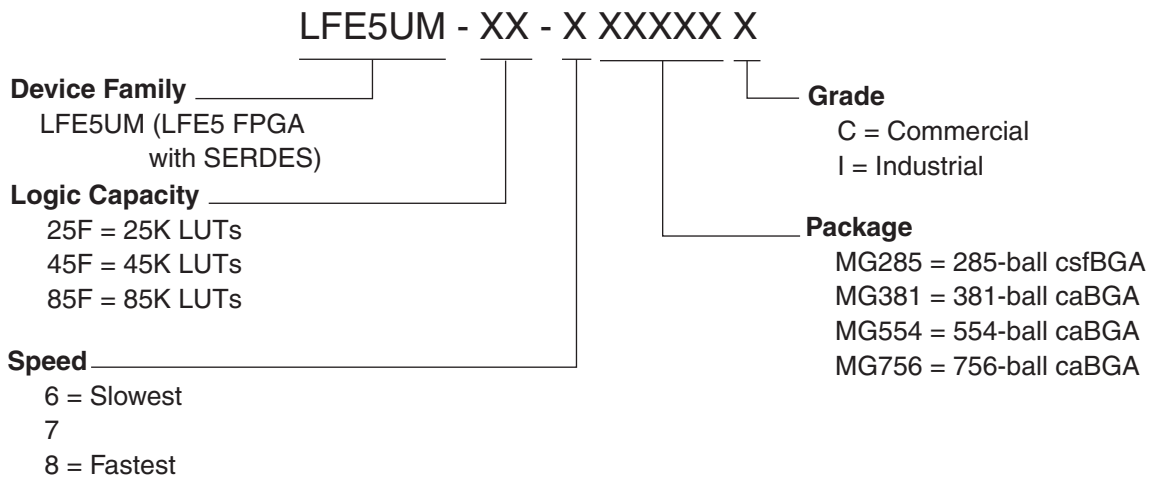
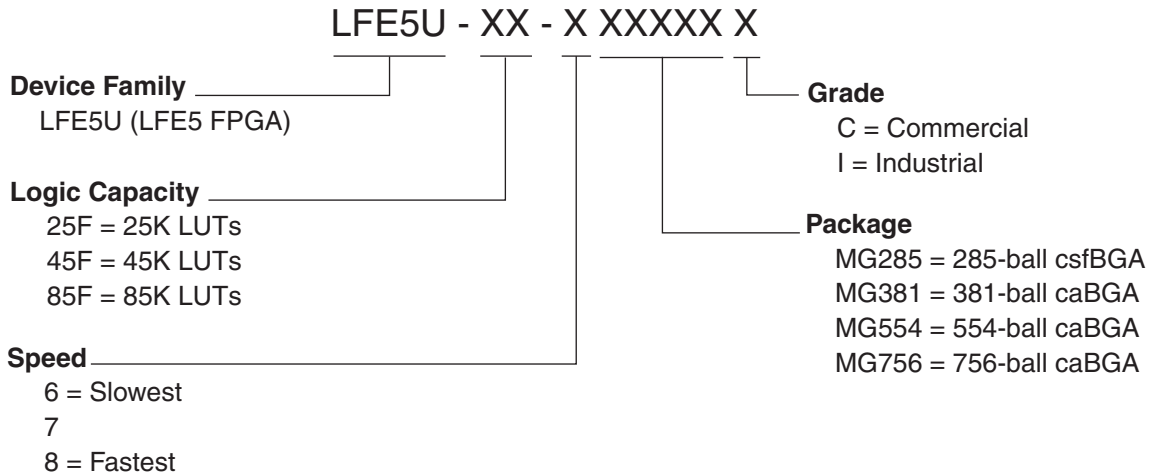
Pin Information Summary		LFE5UM-25		LFE5UM-45			LFE5UM-85			
Pin Type		285 csfBGA	381 caBGA	285 csfBGA	381 caBGA	554 caBGA	285 csfBGA	381 caBGA	554 caBGA	756 caBGA
High Speed Differential Input / Output Pairs	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	10/8	16/8	10/8	16/8	16/8	10/8	17/9	16/8	24/12
	Bank 3	14/7	16/8	14/7	16/8	24/12	14/7	16/8	24/12	32/16
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	13/6	16/8	13/6	16/8	24/12	13/6	16/8	24/12	32/16
	Bank 7	8/6	16/8	8/6	16/8	16/8	8/6	16/8	16/8	24/12
	Bank 8	0	0	0	0	0	0	0	0	0
Total High Speed Differential I/O Pairs		45/27	64/32	45/27	64/32	80/40	45/27	65/33	80/40	112/56
DQS Groups (> 11 pins in group)	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	1	2	1	2	2	1	2	2	3
	Bank 3	2	2	2	2	3	2	2	3	4
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	2	2	2	2	3	2	2	3	4
	Bank 7	1	2	1	2	2	1	2	2	3
	Bank 8	0	0	0	0	0	0	0	0	0
Total DQS Groups		6	8	6	8	10	6	8	10	14

LFE5U

Pin Information Summary		LFE5U-25		LFE5U-45			LFE5U-85			
Pin Type		285 csfBGA	381 caBGA	285 csfBGA	381 caBGA	554 caBGA	285 csfBGA	381 caBGA	554 caBGA	756 caBGA
General Purpose Inputs/Outputs per Bank	Bank 0	6	24	6	27	32	6	27	32	56
	Bank 1	6	32	6	33	40	6	33	40	48
	Bank 2	21	32	21	32	32	21	34	32	48
	Bank 3	28	32	28	33	48	28	33	48	64
	Bank 4	0	0	0	0	0	0	0	14	24
	Bank 6	26	32	26	33	48	26	33	48	64
	Bank 7	18	32	18	32	32	18	32	32	48
	Bank 8	13	13	13	13	13	13	13	13	13
Total Single-Ended User I/O		118	197	118	203	245	118	205	259	365
VCC		13	20	13	20	24	13	20	24	36
VCCAUX (Core)		3	4	3	4	9	3	4	9	8
VCCIO	Bank 0	1	2	1	2	3	1	2	3	4
	Bank 1	1	2	1	2	3	1	2	3	4
	Bank 2	2	3	2	3	4	2	3	4	4
	Bank 3	2	3	2	3	3	2	3	3	4
	Bank 4	0	0	0	0	0	0	0	2	2
	Bank 6	2	3	2	3	4	2	3	4	4
	Bank 7	2	3	2	3	3	2	3	3	4
	Bank 8	2	2	2	2	2	2	2	2	2
TAP		4	4	4	4	4	4	4	4	4
Miscellaneous Dedicated Pins		7	7	7	7	7	7	7	7	7
GND		123	59	123	59	113	123	59	113	166
NC		1	8	1	2	33	1	0	17	29
Reserved		4	2	4	2	4	4	2	4	4
SERDES		0	28	0	28	28	0	28	28	28
VCCA (SERDES)	VCCA0	0	2	0	2	6	0	2	6	8
	VCCA1	0	2	0	2	6	0	2	6	9
VCCAUX (SERDES)	VCCAUXA0	0	2	0	2	2	0	2	2	2
	VCCAUXA1	0	2	0	2	2	0	2	2	2
GNDA (SERDES)		0	26	0	26	49	0	26	49	60
Total Balls		285	381	285	381	554	285	381	554	756

Pin Information Summary		LFE5U-25		LFE5U-45			LFE5U-85			
Pin Type		285 csfBGA	381 caBGA	285 csfBGA	381 caBGA	554 caBGA	285 csfBGA	381 caBGA	554 caBGA	756 caBGA
High Speed Differential Input / Output Pairs	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	10/8	16/8	10/8	16/8	16/8	10/8	17/9	16/8	24/12
	Bank 3	14/7	16/8	14/7	16/8	24/12	14/7	16/8	24/12	32/16
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	13/6	16/8	13/6	16/8	24/12	13/6	16/8	24/12	32/16
	Bank 7	8/6	16/8	8/6	16/8	16/8	8/6	16/8	16/8	24/12
Total High Speed Differential I/O Pairs		45/27	64/32	45/27	64/32	80/40	45/27	65/33	80/40	112/56
DQS Groups (> 11 pins in group)	Bank 0	0	0	0	0	0	0	0	0	0
	Bank 1	0	0	0	0	0	0	0	0	0
	Bank 2	1	2	1	2	2	1	2	2	3
	Bank 3	2	2	2	2	3	2	2	3	4
	Bank 4	0	0	0	0	0	0	0	0	0
	Bank 6	2	2	2	2	3	2	2	3	4
	Bank 7	1	2	1	2	2	1	2	2	3
Total DQS Groups		6	8	6	8	10	6	8	10	14

ECP5 Part Number Description



Ordering Part Numbers

Commercial

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5U-25F-6MG285C	-6	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-7MG285C	-7	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-8MG285C	-8	Lead free csfBGA	285	Commercial	24	No
LFE5U-25F-6MG381C	-6	Lead free caBGA	381	Commercial	24	No
LFE5U-25F-7MG381C	-7	Lead free caBGA	381	Commercial	24	No
LFE5U-25F-8MG381C	-8	Lead free caBGA	381	Commercial	24	No
LFE5U-45F-6MG285C	-6	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-7MG285C	-7	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-8MG285C	-8	Lead free csfBGA	285	Commercial	44	No
LFE5U-45F-6MG381C	-6	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-7MG381C	-7	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-8MG381C	-8	Lead free caBGA	381	Commercial	44	No
LFE5U-45F-6MG554C	-6	Lead free caBGA	554	Commercial	44	No
LFE5U-45F-7MG554C	-7	Lead free caBGA	554	Commercial	44	No
LFE5U-45F-8MG554C	-8	Lead free caBGA	554	Commercial	44	No
LFE5U-85F-6MG285C	-6	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-7MG285C	-7	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-8MG285C	-8	Lead free csfBGA	285	Commercial	84	No
LFE5U-85F-6MG381C	-6	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-7MG381C	-7	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-8MG381C	-8	Lead free caBGA	381	Commercial	84	No
LFE5U-85F-6MG554C	-6	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-7MG554C	-7	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-8MG554C	-8	Lead free caBGA	554	Commercial	84	No
LFE5U-85F-6MG756C	-6	Lead free caBGA	756	Commercial	84	No
LFE5U-85F-7MG756C	-7	Lead free caBGA	756	Commercial	84	No
LFE5U-85F-8MG756C	-8	Lead free caBGA	756	Commercial	84	No
LFE5UM-25F-6MG285C	-6	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-7MG285C	-7	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-8MG285C	-8	Lead free csfBGA	285	Commercial	24	Yes
LFE5UM-25F-6MG381C	-6	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-25F-7MG381C	-7	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-25F-8MG381C	-8	Lead free caBGA	381	Commercial	24	Yes
LFE5UM-45F-6MG285C	-6	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-7MG285C	-7	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-8MG285C	-8	Lead free csfBGA	285	Commercial	44	Yes
LFE5UM-45F-6MG381C	-6	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-7MG381C	-7	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-8MG381C	-8	Lead free caBGA	381	Commercial	44	Yes
LFE5UM-45F-6MG554C	-6	Lead free caBGA	554	Commercial	44	Yes
LFE5UM-45F-7MG554C	-7	Lead free caBGA	554	Commercial	44	Yes
LFE5UM-45F-8MG554C	-8	Lead free caBGA	554	Commercial	44	Yes

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5UM-85F-6MG285C	-6	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-7MG285C	-7	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-8MG285C	-8	Lead free csfBGA	285	Commercial	84	Yes
LFE5UM-85F-6MG381C	-6	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-7MG381C	-7	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-8MG381C	-8	Lead free caBGA	381	Commercial	84	Yes
LFE5UM-85F-6MG554C	-6	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-7MG554C	-7	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-8MG554C	-8	Lead free caBGA	554	Commercial	84	Yes
LFE5UM-85F-6MG756C	-6	Lead free caBGA	756	Commercial	84	Yes
LFE5UM-85F-7MG756C	-7	Lead free caBGA	756	Commercial	84	Yes
LFE5UM-85F-8MG756C	-8	Lead free caBGA	756	Commercial	84	Yes

Industrial

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5U-25F-6MG285I	-6	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-7MG285I	-7	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-8MG285I	-8	Lead free csfBGA	285	Industrial	24	No
LFE5U-25F-6MG381I	-6	Lead free caBGA	381	Industrial	24	No
LFE5U-25F-7MG381I	-7	Lead free caBGA	381	Industrial	24	No
LFE5U-25F-8MG381I	-8	Lead free caBGA	381	Industrial	24	No
LFE5U-45F-6MG285I	-6	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-7MG285I	-7	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-8MG285I	-8	Lead free csfBGA	285	Industrial	44	No
LFE5U-45F-6MG381I	-6	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-7MG381I	-7	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-8MG381I	-8	Lead free caBGA	381	Industrial	44	No
LFE5U-45F-6MG554I	-6	Lead free caBGA	554	Industrial	44	No
LFE5U-45F-7MG554I	-7	Lead free caBGA	554	Industrial	44	No
LFE5U-45F-8MG554I	-8	Lead free caBGA	554	Industrial	44	No
LFE5U-85F-6MG285I	-6	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-7MG285I	-7	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-8MG285I	-8	Lead free csfBGA	285	Industrial	84	No
LFE5U-85F-6MG381I	-6	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-7MG381I	-7	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-8MG381I	-8	Lead free caBGA	381	Industrial	84	No
LFE5U-85F-6MG554I	-6	Lead free caBGA	554	Industrial	84	No
LFE5U-85F-7MG554I	-7	Lead free caBGA	554	Industrial	84	No
LFE5U-85F-8MG554I	-8	Lead free caBGA	554	Industrial	84	No
LFE5U-85F-6MG756I	-6	Lead free caBGA	756	Industrial	84	No
LFE5U-85F-7MG756I	-7	Lead free caBGA	756	Industrial	84	No
LFE5U-85F-8MG756I	-8	Lead free caBGA	756	Industrial	84	No
LFE5UM-25F-6MG285I	-6	Lead free csfBGA	285	Industrial	24	Yes
LFE5UM-25F-7MG285I	-7	Lead free csfBGA	285	Industrial	24	Yes
LFE5UM-25F-8MG285I	-8	Lead free csfBGA	285	Industrial	24	Yes
LFE5UM-25F-6MG381I	-6	Lead free caBGA	381	Industrial	24	Yes
LFE5UM-25F-7MG381I	-7	Lead free caBGA	381	Industrial	24	Yes
LFE5UM-25F-8MG381I	-8	Lead free caBGA	381	Industrial	24	Yes
LFE5UM-45F-6MG285I	-6	Lead free csfBGA	285	Industrial	44	Yes
LFE5UM-45F-7MG285I	-7	Lead free csfBGA	285	Industrial	44	Yes
LFE5UM-45F-8MG285I	-8	Lead free csfBGA	285	Industrial	44	Yes
LFE5UM-45F-6MG381I	-6	Lead free caBGA	381	Industrial	44	Yes
LFE5UM-45F-7MG381I	-7	Lead free caBGA	381	Industrial	44	Yes
LFE5UM-45F-8MG381I	-8	Lead free caBGA	381	Industrial	44	Yes
LFE5UM-45F-6MG554I	-6	Lead free caBGA	554	Industrial	44	Yes
LFE5UM-45F-7MG554I	-7	Lead free caBGA	554	Industrial	44	Yes
LFE5UM-45F-8MG554I	-8	Lead free caBGA	554	Industrial	44	Yes
LFE5UM-85F-6MG285I	-6	Lead free csfBGA	285	Industrial	84	Yes
LFE5UM-85F-7MG285I	-7	Lead free csfBGA	285	Industrial	84	Yes

Part number	Grade	Package	Pins	Temp.	LUTs (K)	SERDES
LFE5UM-85F-8MG285I	-8	Lead free csfBGA	285	Industrial	84	Yes
LFE5UM-85F-6MG381I	-6	Lead free caBGA	381	Industrial	84	Yes
LFE5UM-85F-7MG381I	-7	Lead free caBGA	381	Industrial	84	Yes
LFE5UM-85F-8MG381I	-8	Lead free caBGA	381	Industrial	84	Yes
LFE5UM-85F-6MG554I	-6	Lead free caBGA	554	Industrial	84	Yes
LFE5UM-85F-7MG554I	-7	Lead free caBGA	554	Industrial	84	Yes
LFE5UM-85F-8MG554I	-8	Lead free caBGA	554	Industrial	84	Yes
LFE5UM-85F-6MG756I	-6	Lead free caBGA	756	Industrial	84	Yes
LFE5UM-85F-7MG756I	-7	Lead free caBGA	756	Industrial	84	Yes
LFE5UM-85F-8MG756I	-8	Lead free caBGA	756	Industrial	84	Yes

For Further Information

A variety of technical notes for the ECP5 family are available.

- TN1260, [ECP5 sysCONFIG Usage Guide](#)
- TN1261, [ECP5 SERDES/PCS Usage Guide](#)
- TN1262, [ECP5 sysIO Usage Guide](#)
- TN1263, [ECP5 sysClock PLL/DLL Design and Usage Guide](#)
- TN1264, [ECP5 Memory Usage Guide](#)
- TN1265, [ECP5 High-Speed I/O Interface](#)
- TN1266, [Power Consumption and Management for ECP5 Devices](#)
- TN1267, [ECP5 sysDSP Usage Guide](#)

For further information on interface standards refer to the following websites:

- JEDEC Standards (LVTTTL, LVCMOS, SSTL): www.jedec.org
- PCI: www.pcisig.com



ECP5 Family Data Sheet Revision History

March 2014

Advance Data Sheet DS1044

Date	Version	Section	Change Summary
March 2014	01.0	All	Initial release.